Application of Plasma Phenomena



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Institute of Space and Plasma Sciences, National Cheng Kung University

Lecture 11

2024 spring semester

Tuesday 9:10-12:00

Materials:

https://capst.ncku.edu.tw/PGS/index.php/teaching/

Online courses:

https://nckucc.webex.com/nckucc/j.php?MTID=m4082f23c59af0571015416f6 e58dd803

Note!

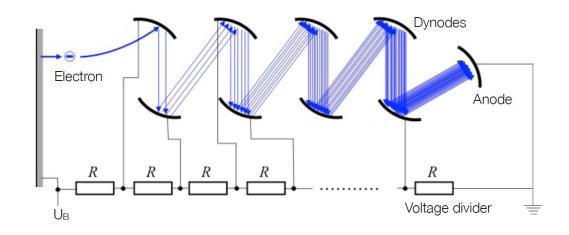


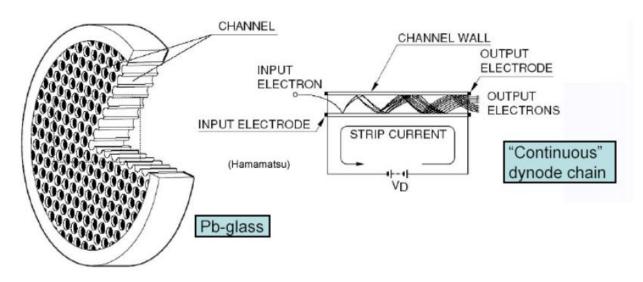
• Quiz in class on 5/28!



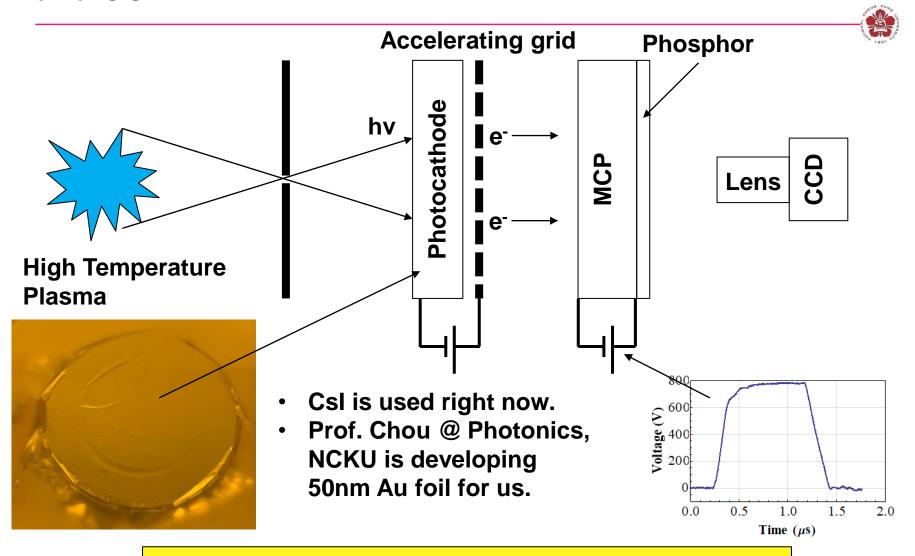
The number of electrons can be increased through photomultipliers or microchannel plate (MCP)







X-rays are imaged using photocathode, MCP, phosphor, and CCD

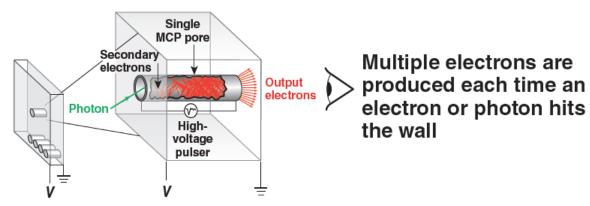


Images can be gated using fast high voltage pulses.

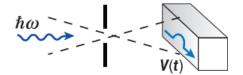
A framing camera provides a series of time-gated 2-D images, similar to a movie camera



- The building block of a framing camera is a gated microchannel-plate (MCP) detector
- An MCP is a plate covered with small holes, each acts as a photomultiplier



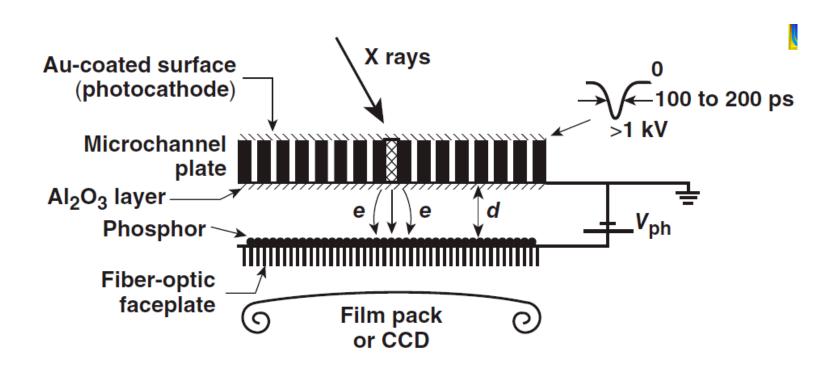
A voltage pulse is sent down the plate, gating the detector



The detector is only on when the voltage pulse is present

E13986b

A framing camera detector consists of a microchannel plate (MCP) in front of a phosphor screen

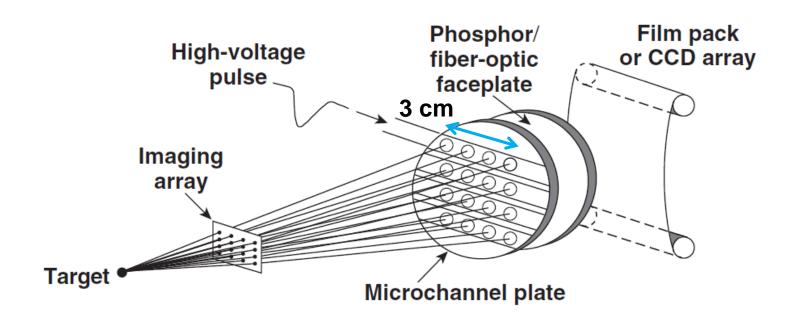


- Electrons are multiplied through MCP by voltage V_c
- Images are recorded on film behind phosphor
- Insulating Al₂O₃ layer allows for V_{ph} to be increased, thereby improving the spatial resolution of phosphor

Framing camera

Two-dimensional time-resolved images are recorded using x-ray framing cameras





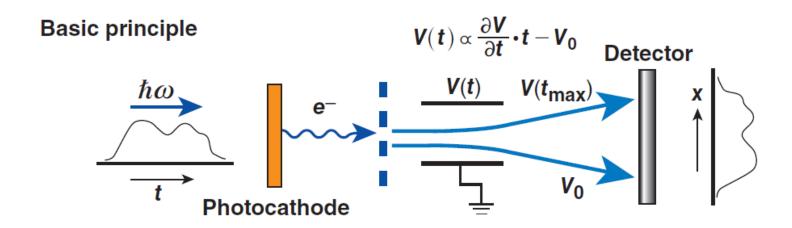
- Temporal resolution = 35 to 40 ps
- Imaging array: Pinholes: 10- to 12- μ m resolution, 1 to 4 keV
- Space-resolved x-ray spectra can be obtained by using Bragg crystals and imaging slits

E7105b

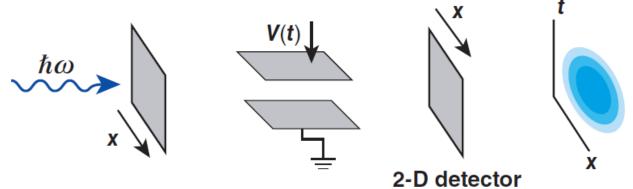
Ex:
$$\Delta t = \frac{3 \text{ cm}/3}{3 \times 10^{10} \text{ cm/s}} = 33 \text{ ps}$$

A streak camera provides temporal resolution of 1-D data





A streak camera can provide 2-D information

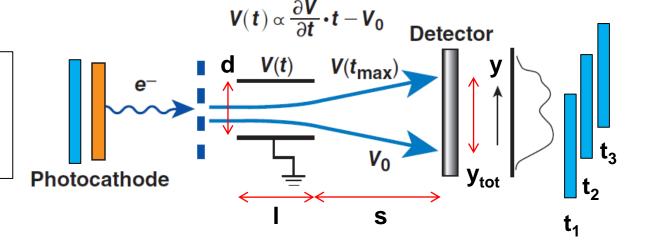


E13984b

A slit is to prevent spatial information at different times interfering with each other

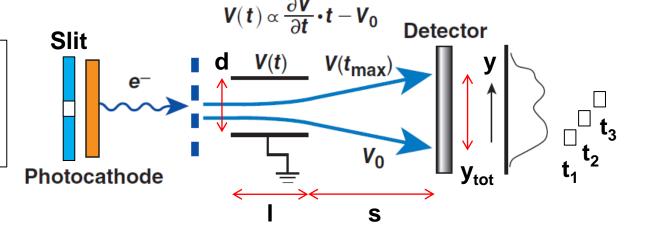
Imaging system

- Visible light: regular lens
- X rays: pinhole



Imaging system

- Visible light: regular lens
- X rays: pinhole

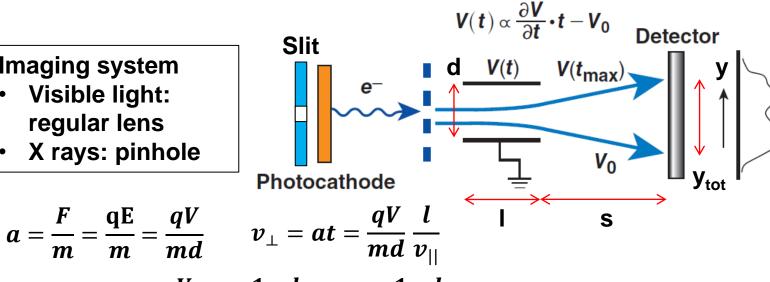


A temporal resolution higher than 15 ps is expected



Imaging system

- Visible light: regular lens
- X rays: pinhole



$$a = \frac{F}{m} = \frac{qE}{m} = \frac{qV}{md}$$

$$y = s \operatorname{Tan}\theta = s \frac{V_{\perp}}{V_{\parallel}} = \frac{1}{2E_{L}} \frac{l}{d} sqV = \frac{1}{2E_{L}} \frac{l}{d} sq(V_{0} + V't)$$

Let d=10 mm, l=20 mm, s=50 mm, E_k =1 keV, V=-200 ~ 200 V

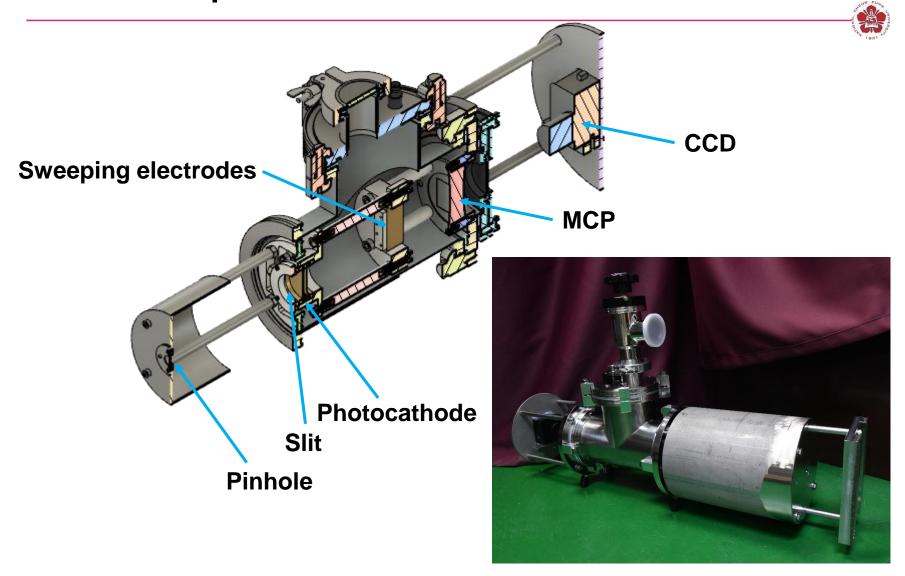
$$V' \equiv \frac{V_{\text{tot}}}{t_{\text{tot}}} = 0.06 \,\text{kV/ns}$$
 $y_{\text{tot}} = 15 \,\text{mm}$ $y_{\text{tot}} = 15 \,\text{mm}$

Temporal resolution:

$$\delta t = \delta y \frac{2E_k d}{lsqV'} = 15 \text{ ps for } \delta y = 45 \mu m$$

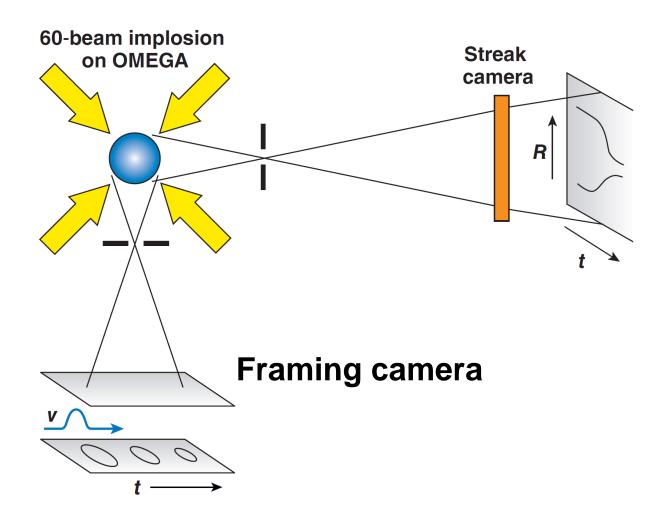
• δt will be adjusted by changing E_k .

A streak camera with temporal resolution of 15 ps has been developed



Shell trajectories can be measured using framing camera or streak camera



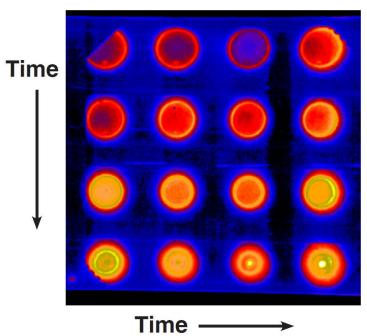


Comparison of images from framing camera versus streak camera

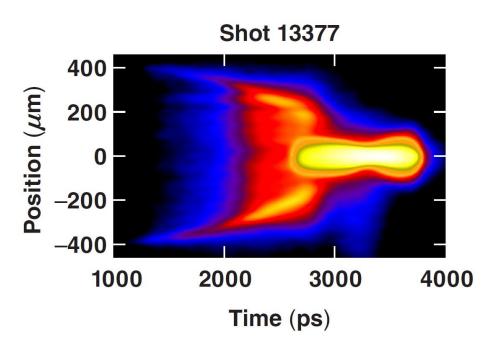




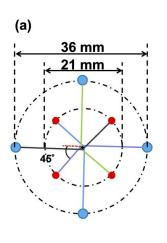
Shot 13377

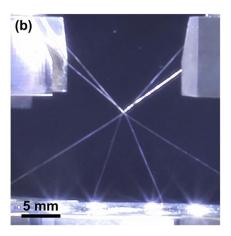


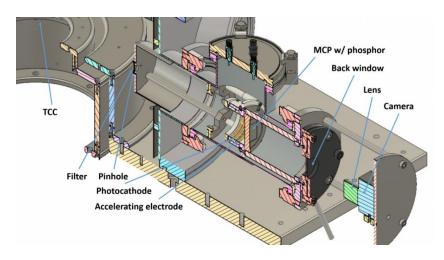
Streak-camera image

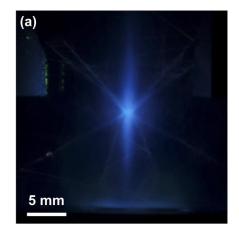


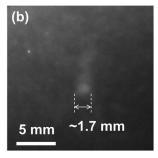
We demonstrated using x-ray pinhole camera to capture the radiation from an imploded x pinch



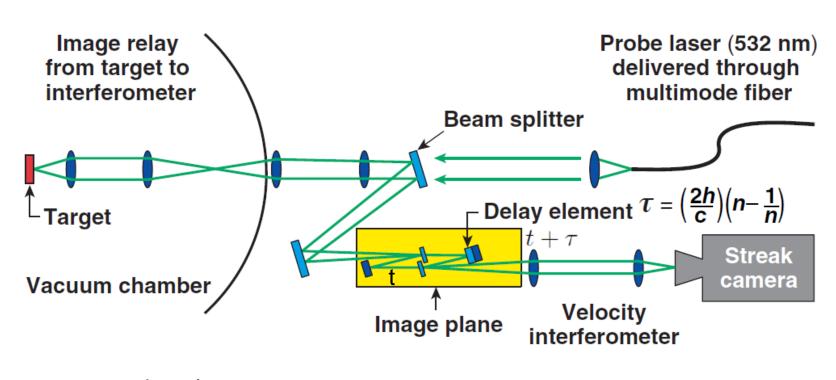








Shock velocities are measured using time-resolved Velocity Interferometer System for Any Reflector (VISAR)



$$-t - \tau$$

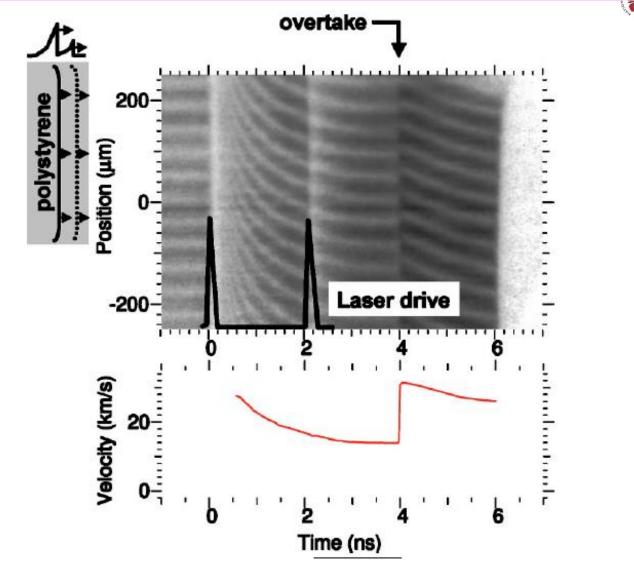
$$-t$$

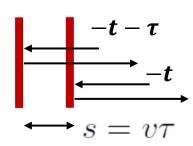
$$-t$$

$$+s = v\tau$$

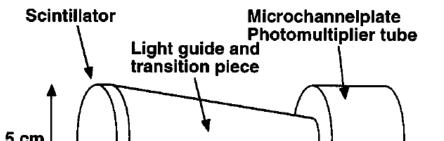
$$\Delta \phi = \frac{v\tau}{\lambda} \propto v$$

Shock velocities are measured using time-resolved Velocity Interferometer System for Any Reflector (VISAR)

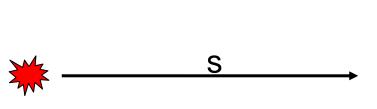




Neutron average temperature is obtained using Neutron Time of Flight (NToF)



0.5 cm

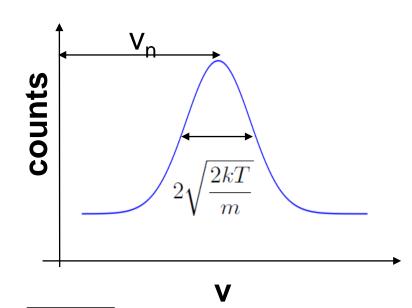


$$D + D \longrightarrow He^3 (0.82 \text{ MeV}) + n (2.45 \text{ MeV})$$

$$D + T \longrightarrow He^4 (3.5 \text{ MeV}) + n (14.1 \text{ MeV})$$

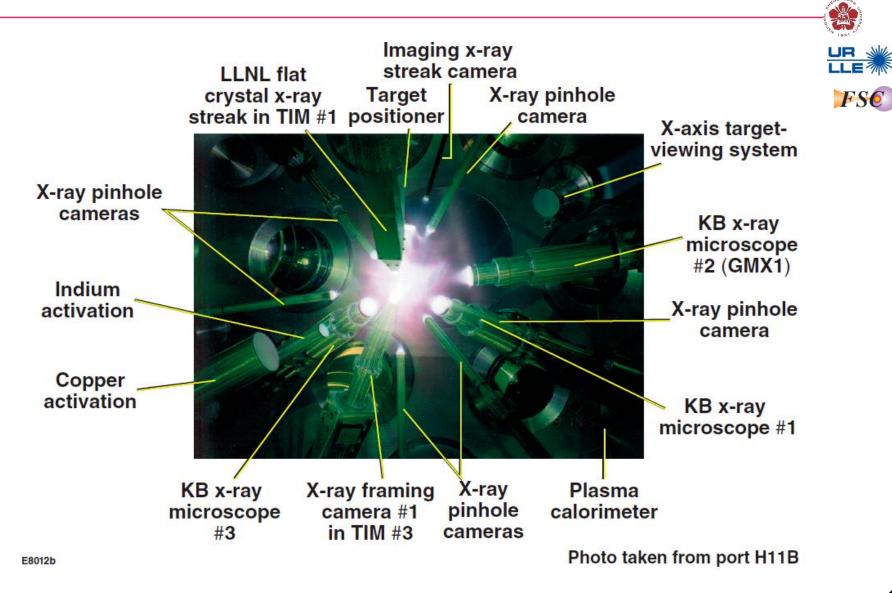
$$s = vt$$
 $v = \frac{s}{t}$

$$f(v) = \sqrt{\left(\frac{m}{2\pi kT}\right)} \exp\left(-\frac{mv^2}{2kT}\right)$$



T. J. Murphy et al., Rev. Sci. Instrum. **72**, 773 (2001) ₁₇

The OMEGA Facility is carrying out ICF experiments using a full suite of target diagnostics



Energetic charged particles losses most of its energy right before it stops



Momentum transfer:

$$\Delta p_{\perp} = \int F_{\perp} dt = \int F_{\perp} \frac{dt}{dx} dx = \int F_{\perp} \frac{dx}{v} \qquad \qquad \boxed{\ }$$

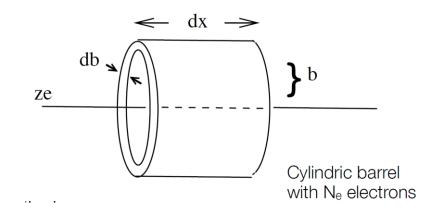
$$= \int_{-\infty}^{\infty} \frac{ze^2}{(x^2 + b^2)} \cdot \frac{b}{\sqrt{x^2 + b^2}} \cdot \frac{1}{v} \, dx = \frac{ze^2b}{v} \left[\frac{x}{b^2 \sqrt{x^2 + b^2}} \right]_{-\infty}^{\infty} = \frac{2ze^2}{bv}$$

 Δp_{\parallel} : averages to zero

$$\Delta E(b) = \frac{\Delta p^2}{2m_e} \quad \text{Ne = n\cdot(2\pi b)\cdot dbdx}$$

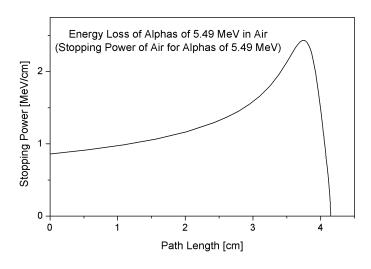
$$-dE(b) = \frac{\Delta p^2}{2m_e} \cdot 2\pi nb \, db \, dx$$

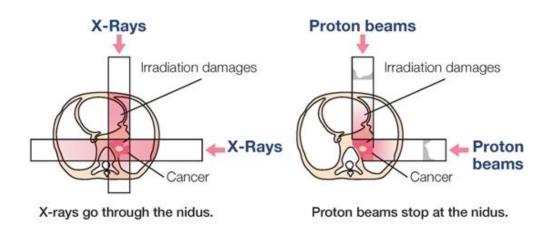
$$-\frac{dE}{dx} = \frac{4\pi \, n \, z^2 e^4}{m_{\rm e} v^2} \cdot \int_{b_{\rm min}}^{b_{\rm max}} \frac{db}{b} = \frac{4\pi \, n \, z^2 e^4}{m_{\rm e} v^2} \, \ln \frac{b_{\rm max}}{b_{\rm min}}$$



Proton therapy takes the advantage of using Bragg peak

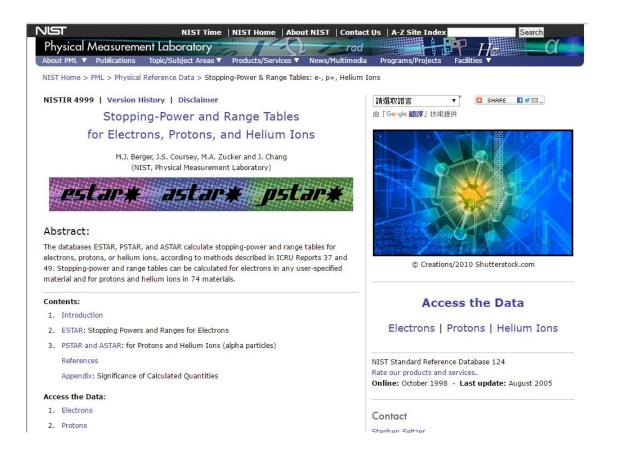




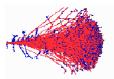


There are two suggested website for getting the information of proton stopping power in different materials

http://www.nist.gov/pml/data/star/

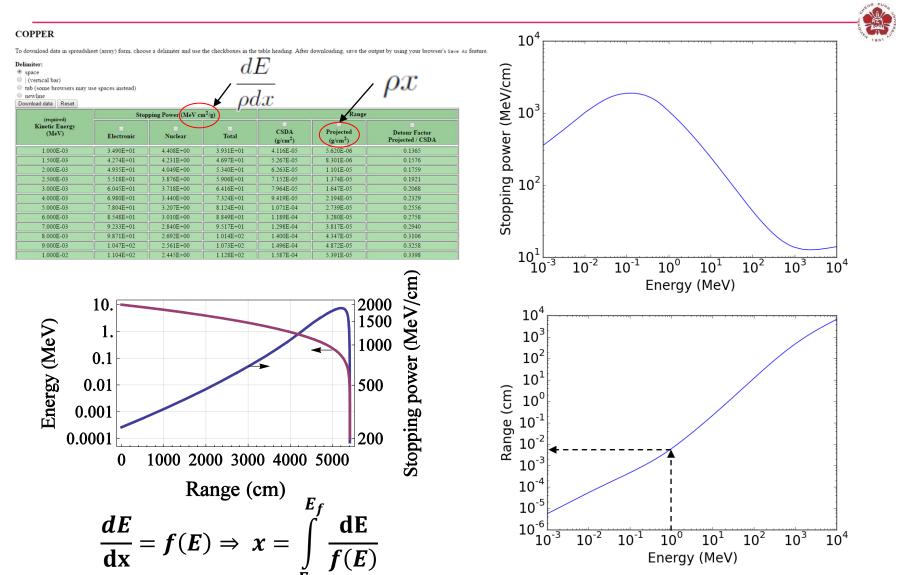


http://www.srim.org/



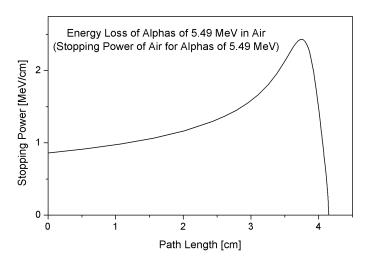
SRIM Textbook	
Software	Science
SRIM / TRIM Introduction	Historical Review
Download SRIM- 2013	Details of SRIM- 2013
SRIM Install Problems	Experimental Data Plots Stopping of Ions in Matter
SRIM Tutorials	Stopping in Compounds
Download TRIM Manual Part-1, Part-2	Scientific Citations of Experimental Data
Stanning Pangs and Damage	High Energy Stepping

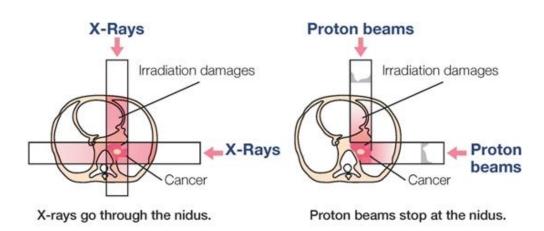
The thickness of a filter can be decided from the range data from NIST website



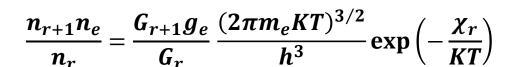
Proton therapy takes the advantage of using Bragg peak







Saha equation gives the relative proportions of atoms of a certain species that are in two different states of ionization in thermal equilibrium



- n_{r+1}, n_r: Density of atoms in ionization state r+1, r (m⁻³)
- n_e: Density of electrons (m⁻³)
- G_{r+1}, G_r: Partition function of ionization state r+1, r
- g_e=2: Statistical weight of the electron
- m_e: Mass of the electron
- χ_r: Ionization potential of ground level of state r to reach to the ground level of state r+1
- T: Temperature
- h: Planck's constant
- K: Boltzmann constant

Some backgrounds of quantum mechanics



Planck blackbody function:

$$u(\nu, T) = \frac{8\pi h \nu^3}{c^3} \frac{1}{e^{h\nu/KT} - 1} (W/m^3 Hz)$$

- **Boltzmann formula:**
 - g_i, g_i: statistical weight

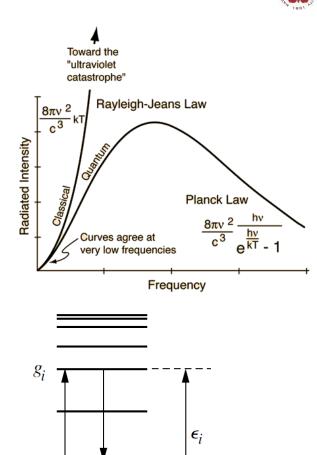
$$\frac{n_i}{n_j} = \frac{g_i e^{-\epsilon_i/\text{KT}}}{g_j e^{-\epsilon_j/\text{KT}}} = \frac{g_i}{g_j} e^{-h\nu_{ij}/\text{KT}} \qquad \frac{g_i}{g_j} = \frac{2J_i + 1}{2J_j + 1}$$

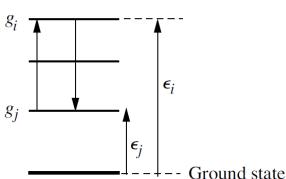
(J: angular momenta quantum number)

– Number in the ith state to the total atom:

$$\frac{n_i}{n} = \frac{n_i}{\Sigma n_i} \equiv \frac{g_i e^{-\epsilon_i/\text{KT}}}{G} \qquad G \equiv \Sigma g_j e^{-\epsilon_j/\text{KT}}$$

G: partition function of statistical weight for the atom, taking into account all its excited states.





Einstein coefficient



- Probability of electron energy transition:
 - Excitation (\uparrow): $P_{ji} = B_{ji}u(\nu, T)$
 - De-excitation (\downarrow): $P_{ij} = A_{ij} + B_{ij}u(\nu, T)$
- In thermal equilibrium:

$$n_{i}(A_{ij} + B_{ij}u) = n_{j}B_{ji}u$$

$$\frac{g_{i}}{g_{j}}e^{-x}(A_{ij} + B_{ij}u) = B_{ji}u$$

$$x \equiv \frac{h\nu}{KT}$$

$$u = a(e^{x} - 1)^{-1}$$

$$a \equiv \frac{8\pi h\nu^{3}}{c^{3}}$$

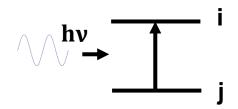
$$a\left(e^{x}B_{ji} - \frac{g_{i}}{g_{j}}B_{ij}\right) = (e^{x} - 1)\frac{g_{i}}{g_{j}}A_{ij}$$

• The Einstein coefficients are independent of T or ν .

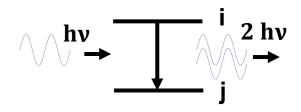
$$x \to 0, e^x \to 1$$
 $x \to \infty, e^x \to \infty$
$$\frac{B_{ij}}{B_{ii}} = \frac{g_j}{g_i}$$

$$aB_{ji} = \frac{g_i}{g_j} A_{ij} \quad \frac{A_{ij}}{B_{ij}} = \frac{8\pi h \nu^3}{c^3}$$

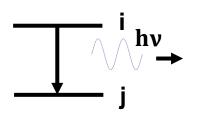
Photoexcitation:



· Induced radiation:



Spontaneous radiation:



Saha equation is derived using the transition between different ionization states

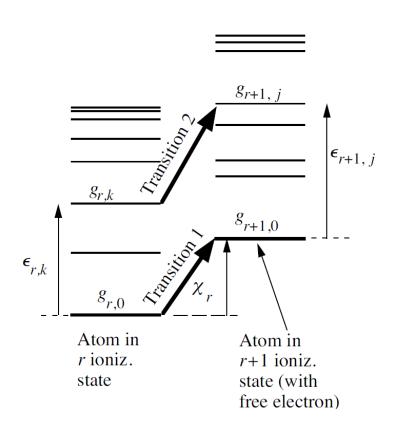


 Required photon energy for transition 1 from the ground state of r ionization state to the ground state of r+1 ionization state:

$$hv = \chi_r + \frac{p^2}{2m}$$
 Energy of the free electron

 Required photon energy for transition 2 from the energy level k of r ionization state to the energy level j of r+1 ionization state:

$$hv = \chi_r + \epsilon_{r+1,j} - \epsilon_{r,k} + \frac{p^2}{2m}$$



Saha equation is derived using the transition between different ionization states



Photoionization:

$$R_{\mathrm{pi}} = n_{r,k} u(\nu) B_{r,k \to r+1,j}$$

Induced radiation:

$$R_{ir} = n_{r+1,j} n_{e,p}(p) u(\nu) B_{r+1,j\to r,k}$$

Spontaneous emission:

$$R_{\rm sr} = n_{r+1,j} n_{e,p}(p) A_{r+1,j\to r,k}$$

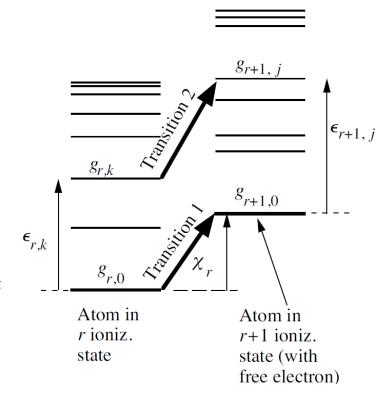
In thermal equilibrium:

$$n_{r+1,j}n_{e,p}A_{r+1,j\to r,k} + n_{r+1,j}n_{e,p}uB_{r+1,j\to r,k}$$

= $n_{r,k}uB_{r,k\to r+1,j}$

Einstein coefficients:

$$\frac{B_{r,k\to r+1,j}}{B_{r+1,j\to r,k}} = \frac{g_{r+1,j}}{g_{r,k}} \frac{g_e 4\pi p^2}{h^3}$$



$$\frac{A_{r+1,j\to r,k}}{B_{r+1,j\to r,k}} = \frac{8\pi h \nu^3}{c^3}$$

Saha equation - continued



$$n_{r+1,j}n_{e,p}A_{r+1,j\to r,k} + n_{r+1,j}n_{e,p}uB_{r+1,j\to r,k} = n_{r,k}uB_{r,k\to r+1,j}$$

$$n_{r+1,j}n_{e,p}rac{A_{r+1,j o r,k}}{B_{r+1,j o r,k}}+n_{r+1,j}n_{e,p}u=n_{r,k}urac{B_{r,k o r+1,j}}{B_{r+1,j o r,k}}$$

$$\frac{n_{r+1,j}n_{e,p}}{n_{r,k}} = \left(\frac{A_{r+1,j\to r,k}}{uB_{r+1,j\to r,k}} + 1\right)^{-1} \frac{B_{r,k\to r+1,j}}{B_{r+1,j\to r,k}}$$

$$n_{e,p}(p) = \frac{n_e 4\pi p^2}{(2\pi m KT)^{3/2}} \exp\left(-\frac{p^2}{2m KT}\right)$$

$$\frac{B_{r,k\to r+1,j}}{B_{r+1,j\to r,k}} = \frac{g_{r+1,j}}{g_{r,k}} \frac{g_e 4\pi p^2}{h^3}$$

$$\frac{A_{r+1,j\to r,k}}{B_{r+1,j\to r,k}} = \frac{8\pi h \nu^3}{c^3}$$

$$\frac{n_{r+1,j}n_e}{n_{r,k}} = \frac{(2\pi m KT)^{3/2}}{4\pi p^2} \exp\left(\frac{p^2}{2m KT}\right) \left[\frac{c^3}{8\pi h \nu^3} \left(e^{h\nu/KT} - 1\right) \frac{8\pi h \nu^3}{c^3} + 1\right]^{-1} \frac{g_{r+1,j}}{g_{r,k}} \frac{g_e 4\pi p^2}{h^3}$$

$$\frac{n_{r+1,j}n_e}{n_{r,k}} = \frac{(2\pi m KT)^{3/2}}{h^3} \frac{g_{r+1,j}g_e}{g_{r,k}} \exp\left[\frac{1}{KT} \left(\frac{p^2}{2m} - h\nu\right)\right]$$

Saha equation - continued



$$\frac{n_{r+1,j}n_e}{n_{r,k}} = \frac{(2\pi m KT)^{3/2}}{h^3} \frac{g_{r+1,j}g_e}{g_{r,k}} \exp\left[\frac{1}{KT} \left(\frac{p^2}{2m} - h\nu\right)\right]$$

$$\frac{n_{r+1,j}n_e}{n_{r,k}} = \frac{(2\pi m KT)^{3/2}}{h^3} \frac{g_{r+1,j}g_e}{g_{r,k}} \exp\left[\frac{1}{KT} \left(\frac{p^2}{2m} - \chi_r - \epsilon_{r+1,j} + \epsilon_{r,k} - \frac{p^2}{2m}\right)\right]$$

$$\frac{(\epsilon_{r+1,j})}{(\epsilon_{r+1,j})}$$

$$\frac{n_{r+1,j}n_e}{n_{r,k}} = \frac{(2\pi m KT)^{3/2}}{h^3} \frac{g_{r+1,j} \exp\left(\frac{\epsilon_{r+1,j}}{KT}\right)g_e}{g_{r,k} \exp\left(\frac{\epsilon_{r,k}}{KT}\right)} \exp\left(-\frac{\chi_r}{KT}\right)$$

$$rac{n_{r,k}}{n_r} = rac{g_{r,k}e^{-\epsilon_{r,k}/\mathrm{KT}}}{G_r}$$
 $G_r = \Sigma g_{r,k}e^{-\epsilon_{r,k}/\mathrm{KT}}$

$$\frac{n_{r+1,j}}{n_{r+1}} = \frac{g_{r+1,j}e^{-\epsilon_{r+1,j}/KT}}{G_{r+1}} \qquad G_{r+1} = \sum g_{r+1,j}e^{-\epsilon_{r+1,j}/KT}$$

$$\frac{n_{r+1}n_e}{n_r} = \frac{G_{r+1}g_e}{G_r} \frac{(2\pi m_e KT)^{3/2}}{h^3} \exp\left(-\frac{\chi_r}{KT}\right)$$

Saha equation – example: hydrogen plasma of the sun



- Photosphere of the sun hydrogen atoms in an optically thick gas in thermal equilibrium at temperature T=6400 K.
 - Neutral hydrogen (r state / ground state)

$$G_r = \Sigma g_{r,k} = g_{r,0} + g_{r,1} \exp\left(-\frac{\epsilon_{r,1}}{KT}\right) + \dots = 2 + 8 \exp\left(-\frac{10.2 \text{ eV}}{0.56 \text{ eV}}\right) + \dots$$

= 2 + 9.8 × 10⁻⁸ + \dots \approx 2

lonized state (r+1 state)

$$G_{r+1} = \Sigma g_{r+1,j} = g_{r+1,0} + g_{r+1,1} \exp\left(-\frac{\epsilon_{r+1,1}}{KT}\right) + \cdots \approx 1$$

– Other information: $g_e=2$ $\chi_r=13.6 \,\mathrm{eV}; \ \mathrm{kT}=0.56 \,\mathrm{eV}$ $n_{r+1}=n_e$

$$\frac{n_{r+1}^2}{n_r} = 2.41 \times 10^{21} \frac{1 \times 2}{2} (6400)^{3/2} \exp\left(-\frac{13.6}{0.56}\right) = 3.5 \times 10^{16} m^{-3}$$

It is mostly neutral in the photosphere of the sun



Assuming 50 % ionization:

$$n_{r+1} = n_r = 3.5 \times 10^{16} m^{-3}$$
 $n = n_{r+1} + n_r = 7 \times 10^{16} m^{-3}$

In the photosphere of the sun:

$$ho \sim 3 \times 10^{-4} \, \mathrm{kg}/m^3 \rightarrow n = 2 \times 10^{23} m^{-3} \gg 7 \times 10^{16} m^{-3}$$

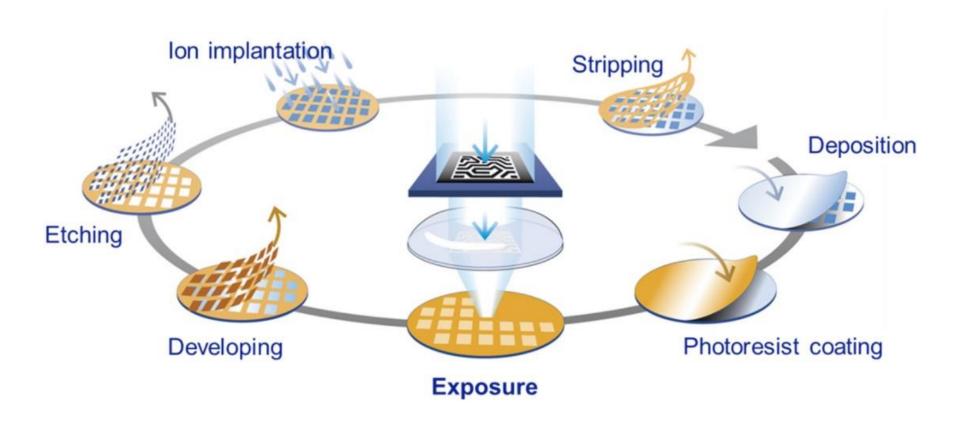
- At higher densities n at the same temperature, there should be more collisions leading to higher recombination rate and thus the plasma is less than 50 % ionization.
 - ⇒ Less than 50 % ionization
- Use the total number density to estimate the ionization percentage:

$$n_{r+1} + n_r = 2 \times 10^{23}$$

$$\frac{n_{r+1}}{n_r} = 4 \times 10^{-4} @6400K$$

A semiconductor device is fabricated by many repetitive production process

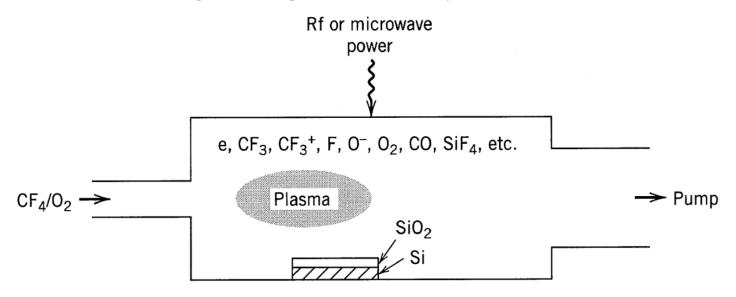




Reference for material processing



- Principles of plasma discharges and materials processing, 2nd edition, by Michael A. Lieberman and Allan J. Lichtenberg
- http://www.eecs.berkeley.edu/~lieber/
- Materials science of thin films, 2nd edition, by Milton Ohring
- Plasma etching, by Dennis M. Manos and Daniel L. Flamm
- Industrial plasma engineering, volume 1, by J. Reece Roth

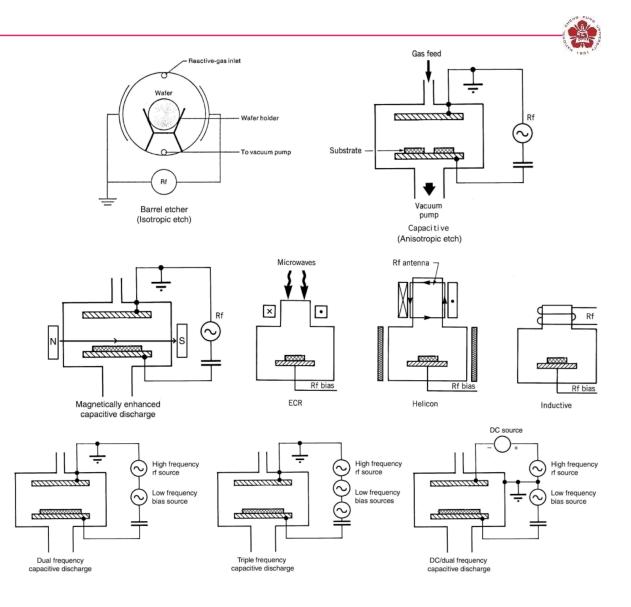


Evolution of etching discharges

1st generation (1 source, multi-wafer, low density)

2nd generation (2 sources, single-wafer, high density)

3rd generation (multi-sources, singlewafer, moderate density)

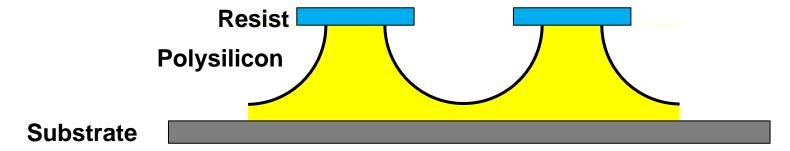




There are two types of etching: isotropic vs anistropic



Isotropic etching



• Anisotropic etching

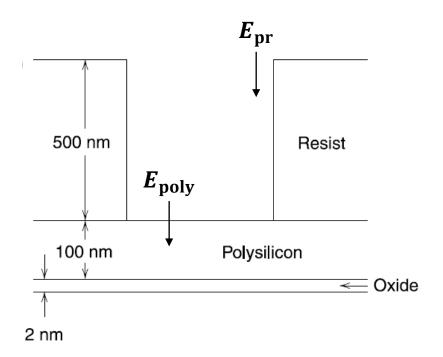
Resist

Polysilicon

Substrate

Plasma etch requirements – etch rate





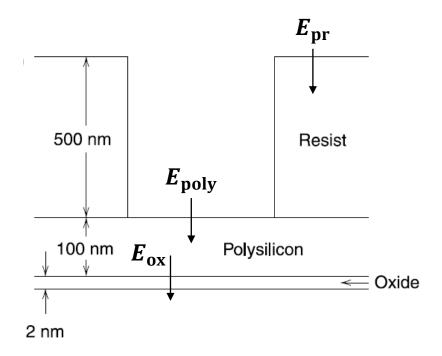
 Etch time needs to be within a few minutes:

$$E_{\rm pr} \geq 250\,{\rm nm/min}$$

$$E_{\rm poly} \geq 50 \, \rm nm/min$$

Plasma etch requirements - selectivity





 Selectivity between polysilicon and resist:

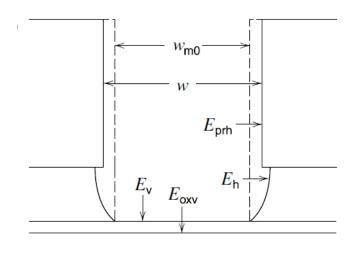
$$s = \frac{E_{\text{poly}} \triangle t}{E_{\text{pr}} \triangle t} >> \frac{100 \text{nm}}{500 \text{nm}} = 0.2$$

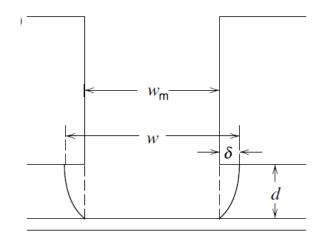
 Assuming 20% nonuniformity on the wafer:

$$s = \frac{E_{\text{poly}} \triangle t}{E_{\text{ox}} \triangle t} >> \frac{20\% \times 100 \text{nm}}{2 \text{nm}} = 10$$

Plasma etch requirements – Anisotropy







Anisotropy

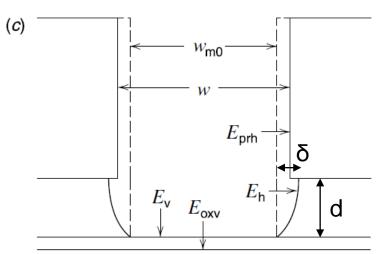
$$a_{h} = \frac{E_{v}}{E_{h}} = \frac{d}{\delta}$$
$$w = w_{m} + 2\delta$$
$$a_{h} \ge \frac{2d}{w - w_{m}}$$

The smallest feature size where w_m=0:

$$w \approx \frac{2d}{a_{\rm h}}$$

Plasma etch requirements – Anisotropy including etching on photoresist



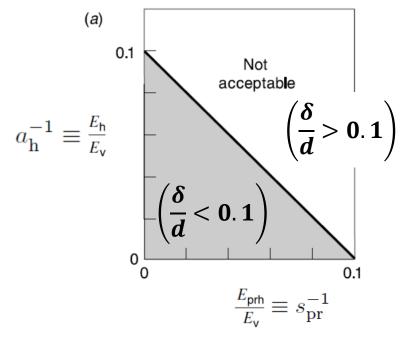


$$\delta \approx (E_{\rm h} + E_{\rm prh}) t$$

$$t = \frac{d}{E_{\rm v}}$$

$$\delta \approx d \frac{E_{\rm h} + E_{\rm prh}}{E_{\rm v}}$$

$$\frac{E_{\rm h} + E_{\rm prh}}{E_{\rm v}} \approx \frac{\delta}{d}$$



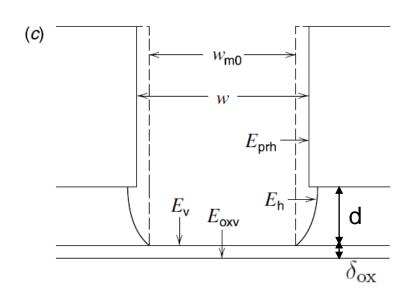
$$\frac{E_h}{E_V} + \frac{E_{\text{prh}}}{E_V} = a_h^{-1} + s_{\text{pr}}^{-1} \approx \frac{\delta}{d} \equiv 0.1$$

 The contribution of the horizontal etching is from both E_h and E_{prh}.

Principles of plasma discharges and materials processing, 2^{nd} edition, by Michael A. Lieberman and Allan J. Lichtenberg

Plasma etch requirements – Uniformity on selectivity and anisotropy



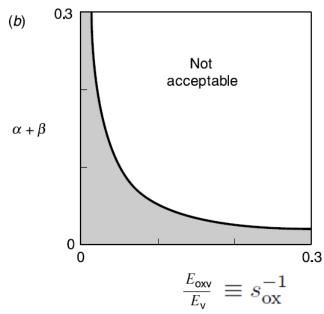


$$d \rightarrow d(1 \pm \alpha)$$
 $E_{v} \rightarrow E_{v}(1 \pm \beta)$

where α , β are variations.

$$t_{\text{max}} = \frac{d(1+\alpha)}{E_{\text{v}}(1-\beta)} \approx \frac{d}{E_{\text{v}}}(1+\alpha+\beta)$$

$$t_{\min} = \frac{d(1-\alpha)}{E_{\nu}(1+\beta)} \approx \frac{d}{E_{\nu}}(1-\alpha-\beta)$$



$$\delta_{\text{ox}} = (t_{\text{max}} - t_{\text{min}}) E_{\text{oxv}}$$
$$= \frac{d}{E_{\text{v}}} 2(\alpha + \beta) E_{\text{oxv}}$$

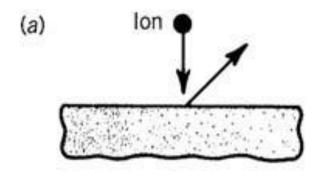
$$2(\alpha + \beta) \frac{E_{\text{oxv}}}{E_{\text{v}}} = \frac{\delta_{\text{ox}}}{d}$$

Principles of plasma discharges and materials processing, 2nd edition, by Michael A. Lieberman and Allan J. Lichtenberg

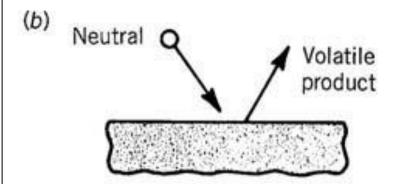
There are four major plasma etching mechanisms

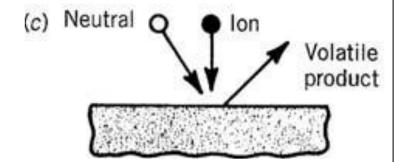


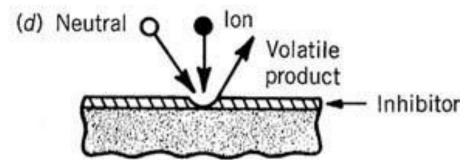




Pure chemical etching







Ion energy-driven etching

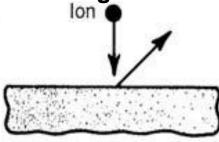
lon-enhanced inhibitor etching

Sputtering etching

Sputtering is an unselective but anisotropic process

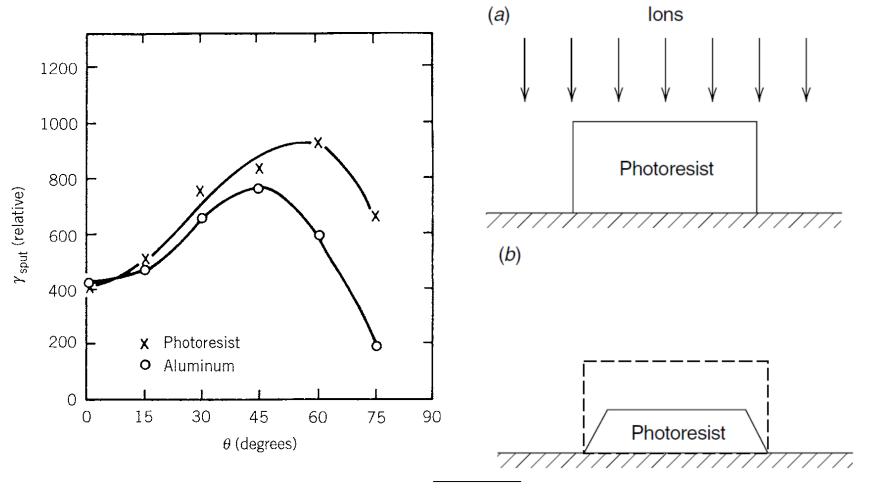


- Unselective process.
- Anisotropic process, strongly sensitive to the angle of incidence of the ion.
- Sputtering rates of different materials are roughly the same.
- Sputtering rates are generally low because the yield is typically of order one atom per incident ion.
- Sputtering is the only one of the four etch processes that can remove nonvolatile products from a surface.
- The process is generally under low pressure since the mean free path of the sputtered atoms must be large enough to prevent redeposition on the substrate or target.



Topographical patterns might not be faithfully transferred during sputter etching





Principles of plasma discharges and materials processing, 2nd edition, by Michael A. Lieberman and Allan J. Lichtenberg

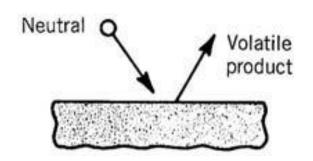
Pure chemical etching

Atoms or molecules chemically react with the surface to form gas-phase products

Highly chemically selective, e.g.,

$$Si(s) + 4F \longrightarrow SiF_4(g)$$

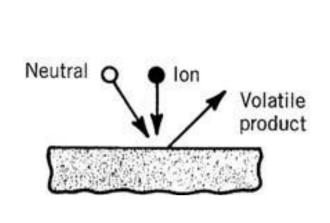
photoresist + O(g) $\longrightarrow CO_2(g) + H_2O(g)$

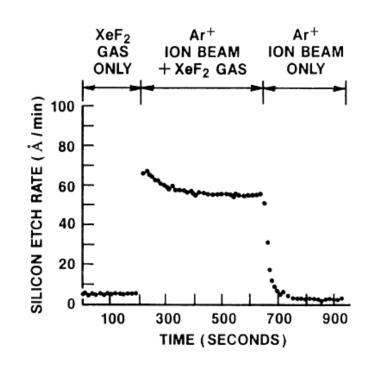


- Almost invariably isotropic.
- Etch products must be volatile.
- The etch rate can be quite large.
- Etch rate are generally not limited by the rate of arrival of etchant atoms, but by one of a complex set of reactions at the surface leading to formation of etch products.

Ion-enhanced energy-driven etching

The discharge supplies both etchants and energetic ions to the surface





- Low chemical etch rate of silicon substrate in XeF2 etchant gas.
- Tenfold increase in etch rate with XeF₂ + 500 V argon ions, simulating ionenhanced plasma etching.
- Very low "etch rate" due to the physical sputtering of silicon by ion bombardment alone.

 Plasma etching, by Daniel L. Flamm and G. Kenneth Herb

Ion-enhanced energy-driven etching has the characteristic of both sputtering and pure chemical etching

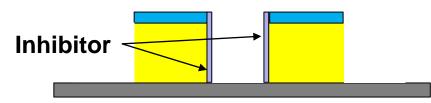
- Chemical in nature but with a reaction rate determined by the energetic ion bombardment.
- Product must be volatile.
- Highly anisotropic.

Ion-enhanced inhibitor etching

An inhibitor species is used



- Inhibitor precursor molecules that absorb or deposit on the substrate form a protective layer or polymer film.
- Etchant is chosen to produce a high chemical etch rate of the substrate in the absence of either ion bombardment or the inhibitor.
- Ion bombardment flux prevents the inhibitor layer from forming or clears it as it forms.
- Where the ion flux does not fall, the inhibitor protects the surface (side wall) from the etchant.
- May not be as selective as pure chemical etching.
- A volatile etch product must be formed.
- Contamination of the substrate and final removal of the protective inhibitor film are other issues.



✓ Inhibitor

Comparison of different processes



	Sputtering etching	Pure chemical etching		Ion-enhanced Inhibitor etching
Selectivity	X	0	0	0
Anisotropic	0	X	0	0
Volatile product	X	0	0	0

TABLE 15.1. Etch Chemistries Based on Product Volatility

Material	Etchant Atoms
Si, Ge	F, Cl, Br
SiO_2	F, F + C
Si ₃ N ₄ , silicides	F
Al	Cl, Br
Cu	$C1 (T > 210^{\circ}C)$
C, organics	O
W, Ta, Ti, Mo, Nb	F, Cl
Au	Cl
Cr	Cl, Cl + O
GaAs	Cl, Br
InP	Cl, C + H

Deposition and implementation

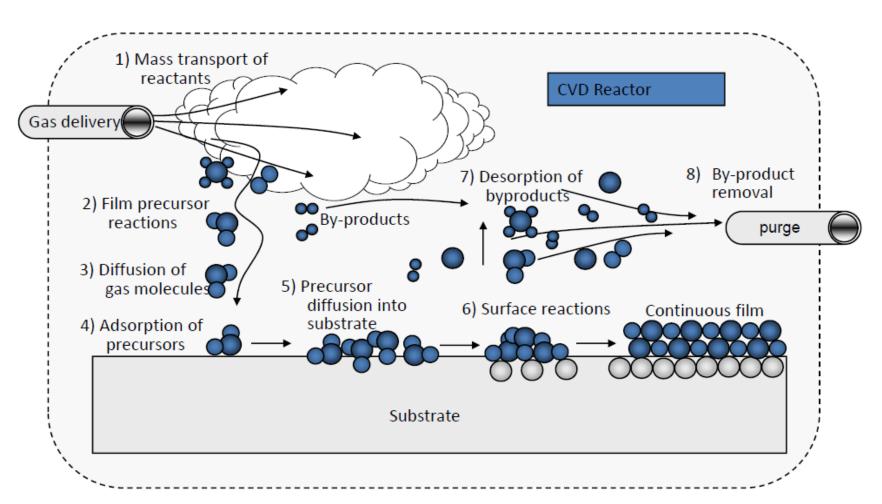


- Plasma-assisted deposition, implantation, and surface modification are important material processes for producing films on surfaces and modifying their properties
- Example processes:
 - Plasma-enhanced chemical vapor deposition (PECVD)
 - Sputter deposition / physical vapor deposition (PVD)
 - Plasma-immersion ion implantation (PIII)



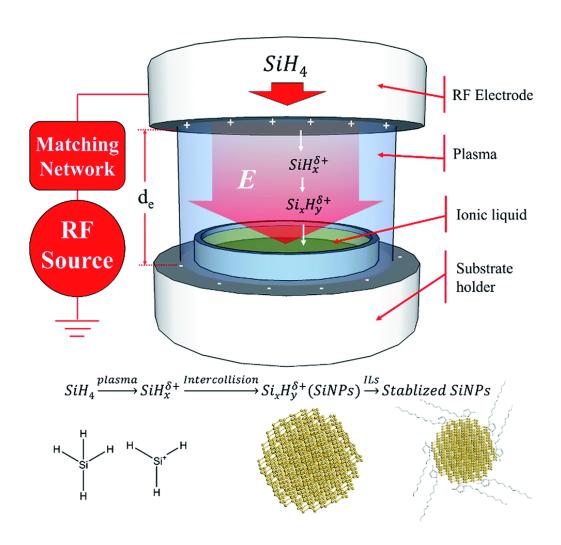
Chemical Vapor Deposition (CVD)





Plasma-enhanced chemical vapor deposition (PECVD)





Films can be deposited in low temperatures using plasma deposition



- Device structures are sensitive to temperature, high-temperature deposition processes cannot be used in many cases.
- High-temperature films can be deposited at low temperatures.
- Unique films not found in nature can be deposited, e.g., diamond.

Working temperature is determined by the desired film properties

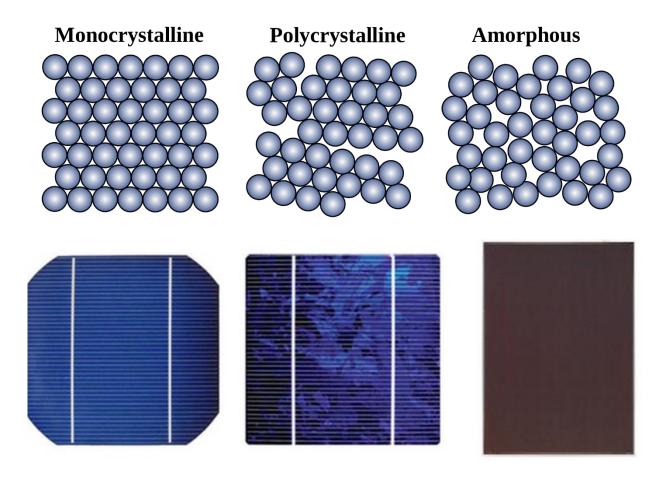


- CVD consists of a thermally activated set of gas-phase and surface reactions that produce a solid product at a surface.
- PECVD gas-phase and the surface reactions are controlled or modified by the plasma properties.
- Te~2-5 eV in PECVD is much greater than the substrate temperature, the temperature in PECVD is much less that CVD.
- Deposition rates are usually not very sensitive to the substrate temperature T.
- Film properties such as composition, stress, and morphology, are functions of T.
- Low-temperature PECVD films are amorphous, not crystalline, which can more easily be achieved with chemical vapor deposition (CVD).

Example of using PECVD – amorphous silicon



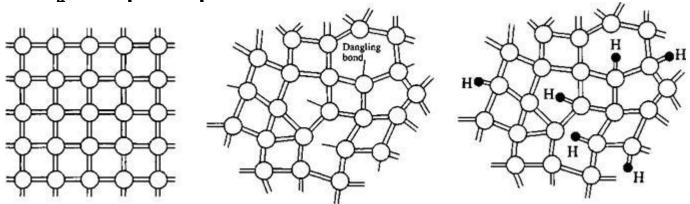
Amorphous silicon thin films are used in solar cells



Example of using PECVD – amorphous silicon



- H is required so that SiH₄ is used
 - For the material to be semiconducting.
 - Terminate the dangling bonds.
 - The dangling bonds are created by ion bombardment (SiH₃+) which also removes hydrogen from the surface.
 - SiH₃ and SiH₂ radicals are important precursors for film growth while
 SiH₄ also participates in surface reactions.

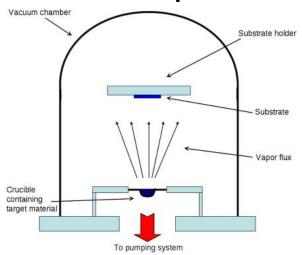


PVD

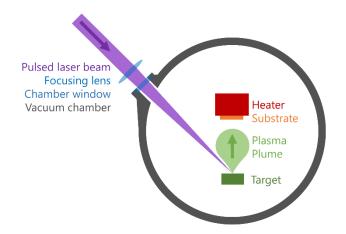
Physical vapor deposition can be achieved by heating the deposited material



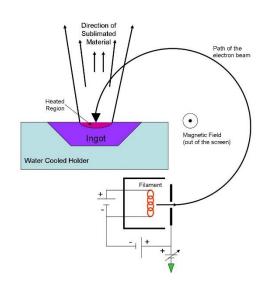
Thermal evaporator



Pulsed-laser deposition

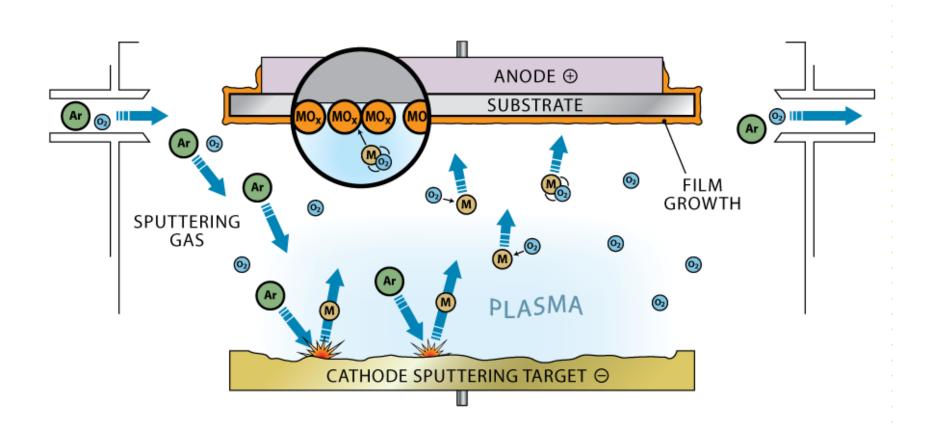


Electron-beam evaporator



Sputtering deposition





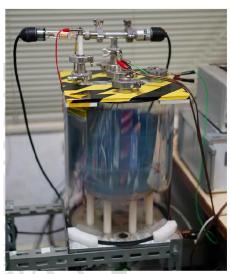
The chamber becomes very dirty after the deposition process



Before



After

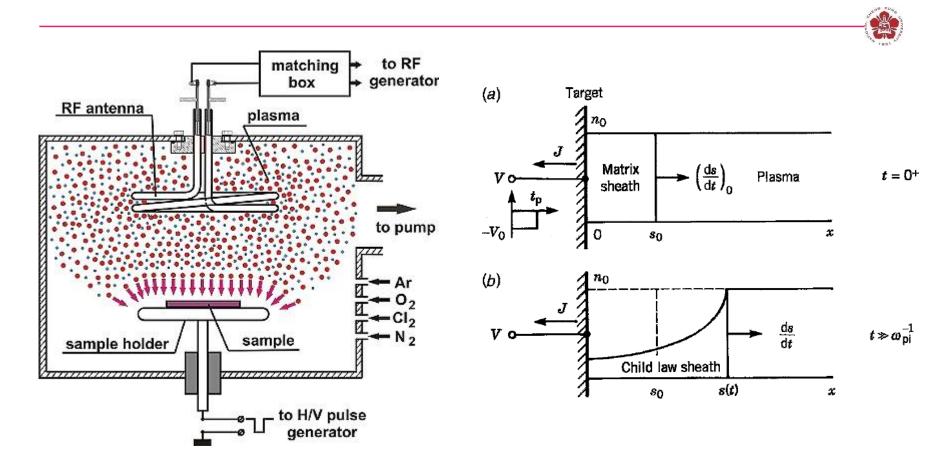


 The turbomolecular pump is also very dirty after the process.



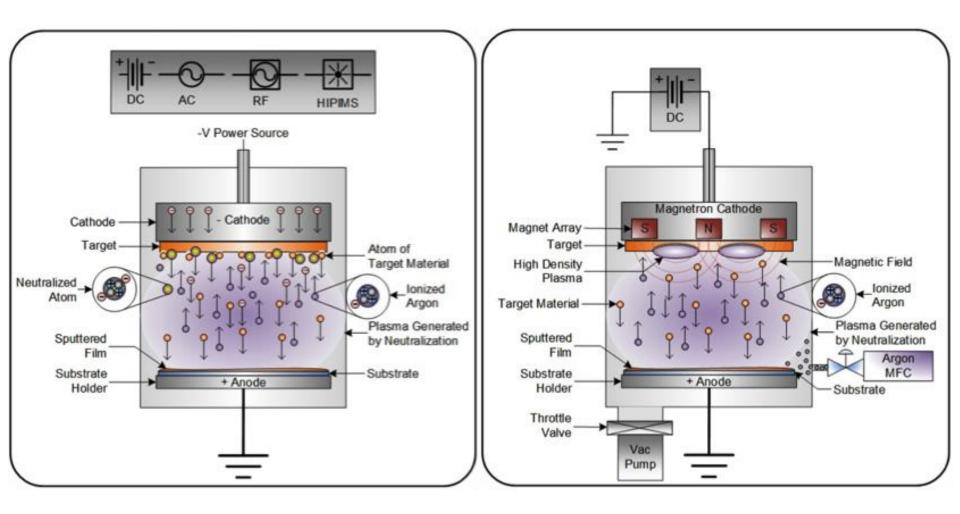


Plasma-immersion ion implantation (PIII)



- Silicon doping ions such as B, P, As are implanted
- Surface hardening of metals N, C are implanted

Magnetron sputtering provides higher deposition rates than conventional sputtering

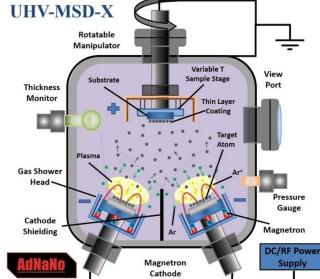


Examples of magnetron sputtering deposition









https://angstromengineering.com/tech/magnetron-sputtering/pulsed-dc/https://dynavac.com/wp-content/uploads/2017/09/Confocal-Sputtering-2.jpg https://www.adnano-tek.com/magnetron-sputtering-deposition-msd.html

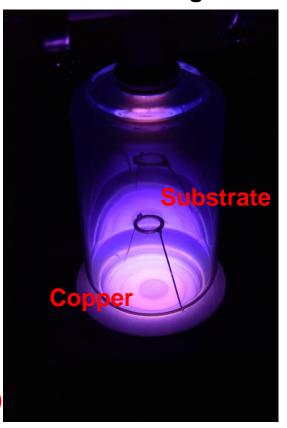
Demonstration experiments – magnetron sputtering



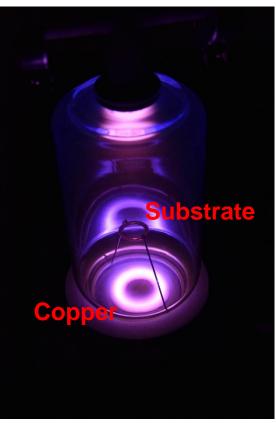
System



Without magnet

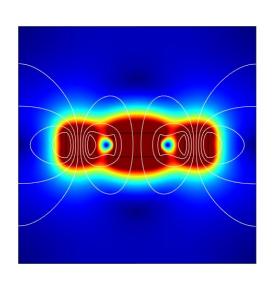


With magnet



A bright ring occurs when the magnet is inserted into the system



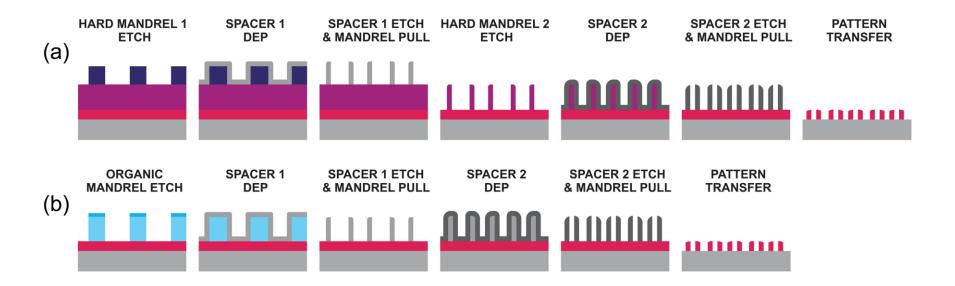




Confined electrons

self-aligned quadruple patterning

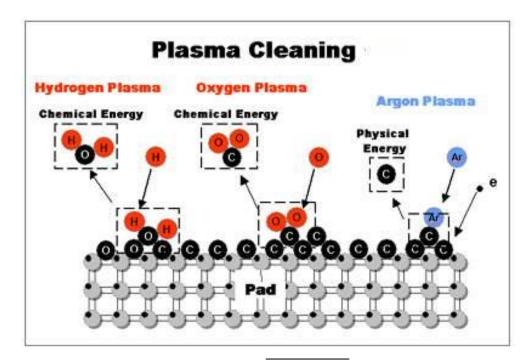




Plasma can be used for cleaning surface



- Cleaning mechanisms:
 - Chemical reactions by free radicals
 - Physical sputtering by high energy ions



Free radicals are generated and used in chemical reactions



$$e^- + H_2 \rightarrow 2H \bullet \qquad \qquad e^- + O_2 \rightarrow 2O \bullet \qquad \qquad O \bullet + O_2 \rightarrow O_3$$

- Highly reactive free radicals generated in plasma may react with the hydrocarbon contaminants of surface oxide.
- **Both H•** and O• can react with grease or oil on surface to form volatile hydrocarbons.

$$\begin{split} \mathbf{H} \bullet_{(g)} + C_n H_{2n+2(s)} &\to \mathbf{CH}_{4(s)} \\ \mathbf{O} \bullet_{(g)} + C_n H_{2n+2(s)} &\to \mathbf{CO}_{(s)} + \mathbf{CH}_x O_{y(g)} + H_2 O_{(g)} \end{split}$$

• O• is more reactive than H•. But O• may also react with surface metal to form oxide, deteriorating the material properties. Nevertheless, H• can make metal oxide back to metal.

$$0 \cdot +Me \rightarrow MeO$$
 $H \cdot +MeO \rightarrow Me + H_2O$

The effect of chemical reactions is increased as the pressure increases



Advantages:

- Stable gas products are formed.
- No redeposition problem.
- High etching selectivity.

Disadvantages:

- Higher concentration of H₂ or O₂ is required to ensure an appropriate etching rate.
- H₂ safety or O₂ strong oxidation ability needs to be monitored.

High energy ions are used in physical sputtering cleaning



- lons generated in plasma can be accelerated toward the substrate to physically bombard away the atoms of contaminants.
- The physical sputtering rate increases as the following quantities increase:
 - Plasma density;
 - Accelerating voltage;
 - Mass of bombardment atoms.
- The physical sputtering is also enhanced by lowering the pressure.
- High cathode bias is used.
- Ar+ has strong sputtering effect.

The physical sputtering rate increases with higher cathode bias and Ar concentration and lower pressure

Advantages:

- Highly efficient cleaning effect can be achieved.
- Gas consumption rate can be very low.

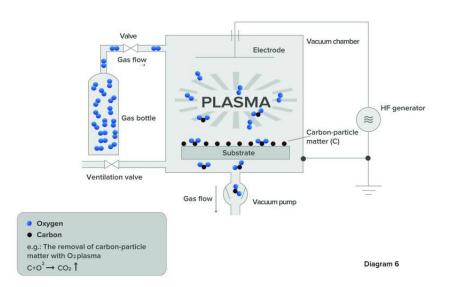
Disadvantages:

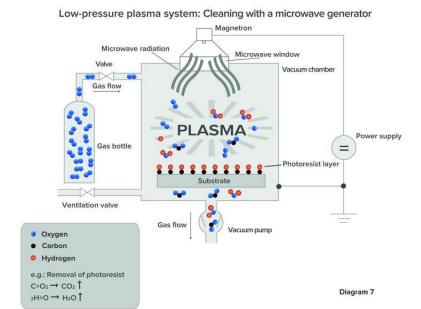
- Etching problems non-selective etching by physical sputtering.
- Redeposition problems: the products sputtered out may be highly unstable and tend to deposit again downstream.

Plasma cleaning examples



Low-pressure plasma system: Generation with a low-frequency or high-frequency generator





Plasma cleaning needs to work in the regime of abnormal glow discharge





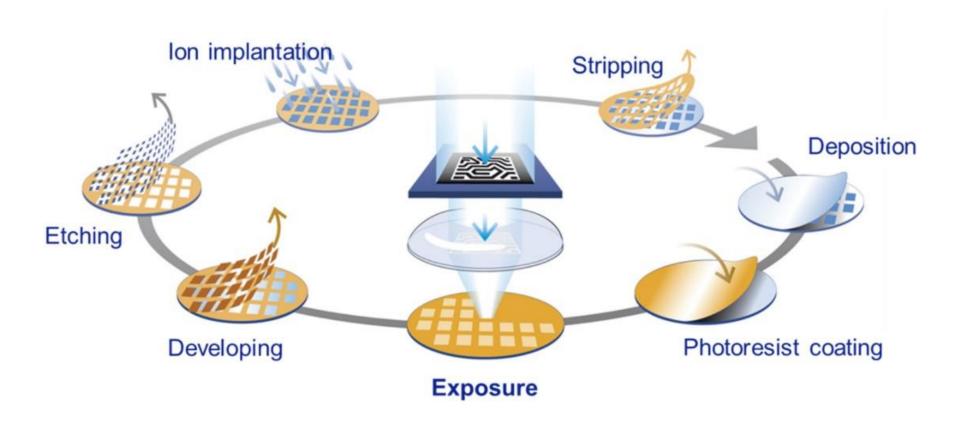




EUV light sources

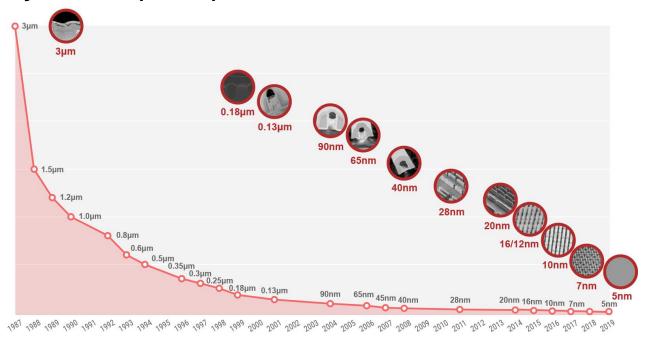
A semiconductor device is fabricated by many repetitive production process





Ultraviolet lithography (EUVL) is one of the key technologies in semiconductor manufacturing nowadays

 The process technology of Taiwan Semiconductor Manufacturing Company Limited (TSMC):



- Optical diffraction needs to be taken into account.
- Shorter wavelength is preferred.
 - Light source with a center wavelength of 13.5 nm is used.

EUV lithography becomes important for semiconductor industry



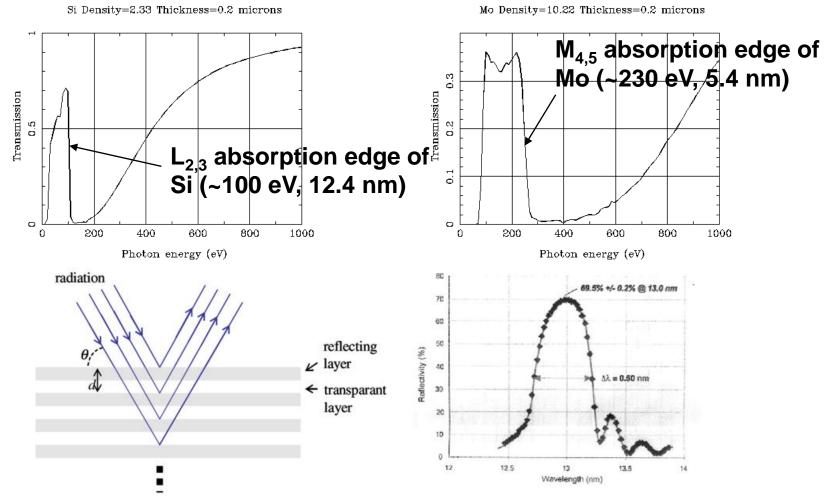
0.15 billion USD for each EUV light source.

https://www.youtube.com/watch?v=NHSR6AHNiDs



EUV light can only be reflected using multilayer mirrors



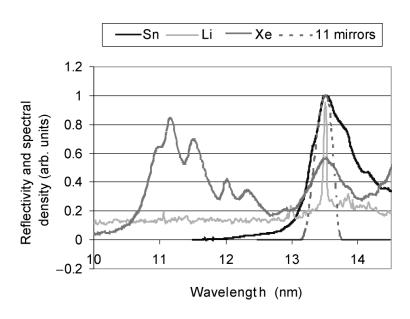


https://henke.lbl.gov/optical_constants/

Mo/Si multilayer coating technology for EUVL, coating uniformity and time stability; E. Louis et al.; SPIE 4146-06, Soft X-ray and EUV Imaging Systems, San Diego, 2000.

13.5-nm EUV light is picked for EUV lithography



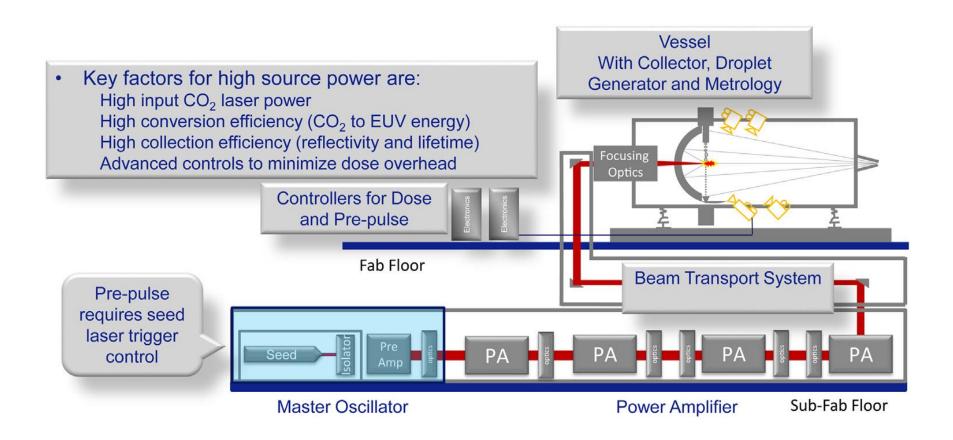


- $\lambda = 13.5 \text{ nm} \pm 1\%$ is required.
- At T=35-40 eV (~450,000 K), in-band emission occurs.
- Xenon:
 - $4p^64d^8 \rightarrow 4p^64d^75p$ from single ion stage Xe¹⁰⁺
 - UTA @ 11 nm

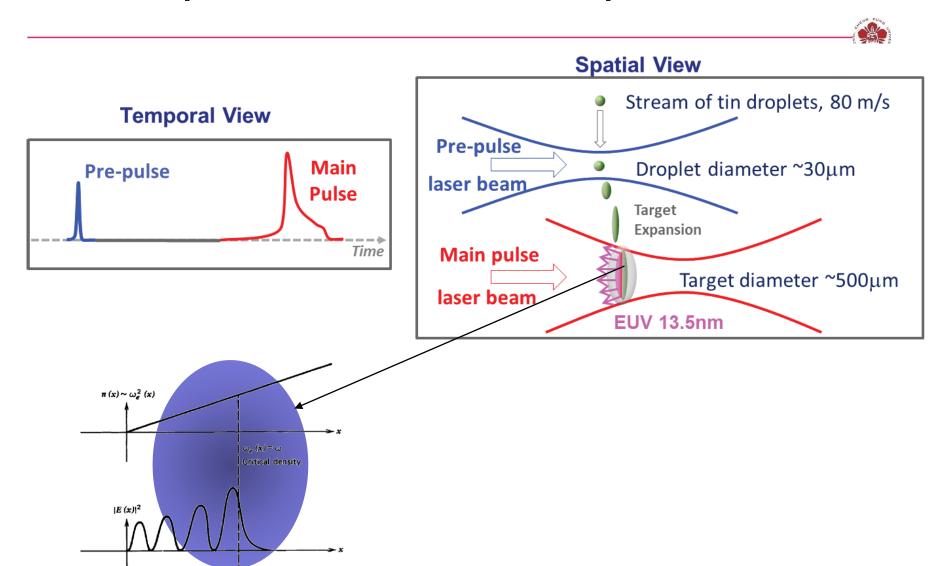
- Tin:
 - $4p^64d^N \rightarrow 4p^54d^{N+1} + 4p^64d^{N-1}4f$ (1 \leq N \leq 6) in ions ranging from Sn⁸⁺ to Sn¹²⁺
 - UTA @ 13.5 nm
 - UTA: unresolved transition array

EUV light is generated from laser-produced plasma (LPP)



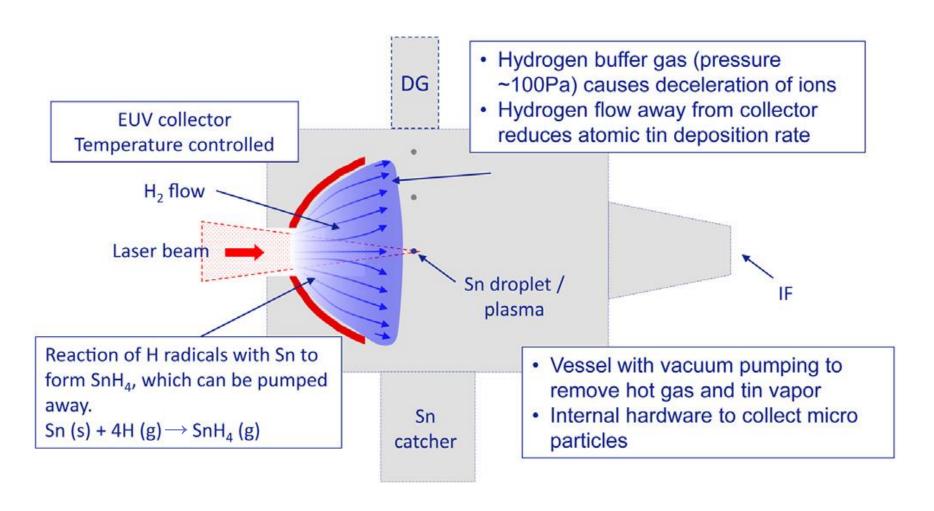


Two laser pulses are used to heat the plasma



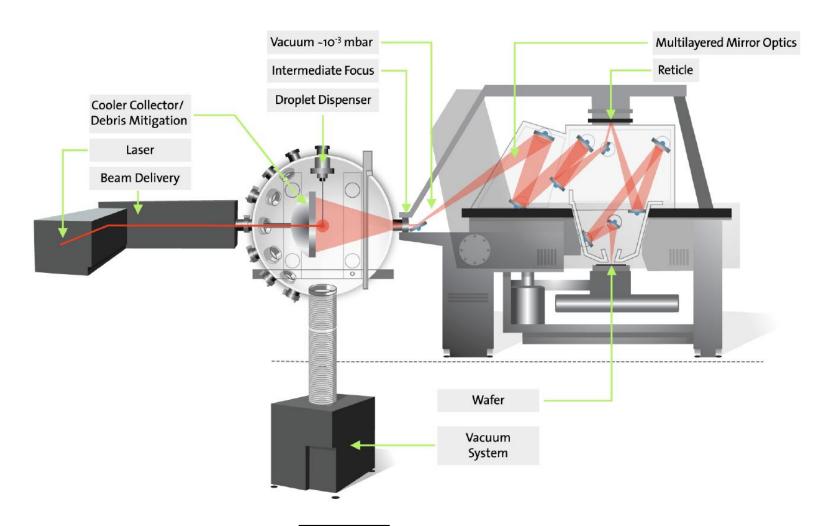
Hydrogen buffer gas with a pressure of ~100 Pa is used to protect the collector mirror





Laser-produced plasma (LPP) is used in the EUV lithography





High harmonic generation from high-power laser

Distance

For $I < 10^{18} \text{ w/cm}^2$ Xe Source gas cell IR field a b C (a) atomic core atomic core (b) 3 E_{rad} half optical period = π/ω Energy 人人人人人人人人 (c) $S(\omega)$

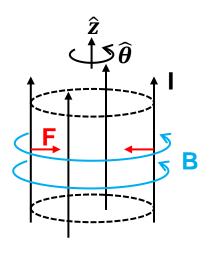
- M. Krüger, etc., Appl. Sci. 9, 378 (2019)
- Nonlinear Optics 3rd edition, by Robert W. Boyd
- P. B. Corkum and F. Krausz, Nature Phys., 3, 381 (2007)

twice laser frequency = $2\omega_{L}$

 $q_{\text{max}} \omega_{\text{L}}$

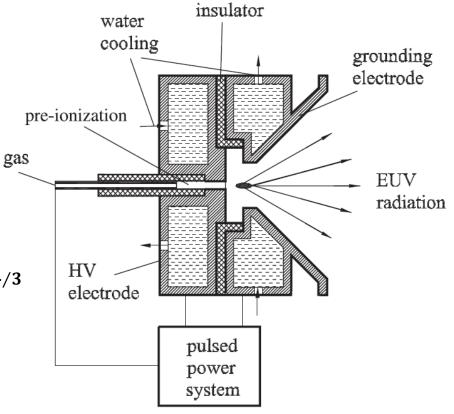
EUV light can be generated using discharged-produced plasma





Adiabatic compression:

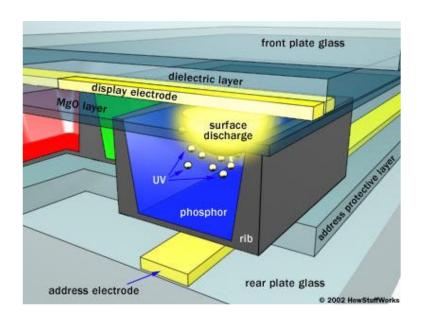
$$TV^{\gamma-1} = \text{const} \quad T_{\rm f} = T_{\rm o} \left(\frac{r_{\rm o}}{r_{\rm f}}\right)^{4/3}$$



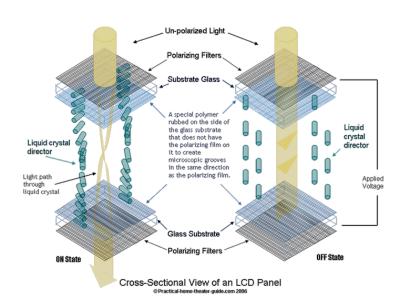
Light source and display systems



Plasma display panel (PDP)



Liquid crystal display (LCD)



Outlines

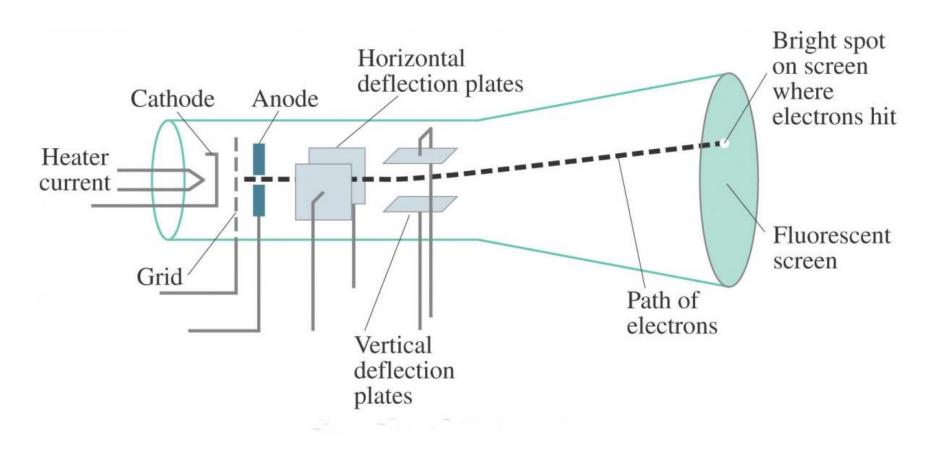


- Cathode Ray Tube
- Color space (CIE 1931 color spaces)
- History of plasma display panel (PDP)
- Design of PDP
- Liquid crystal display (LCD)
- LCD vs PDP



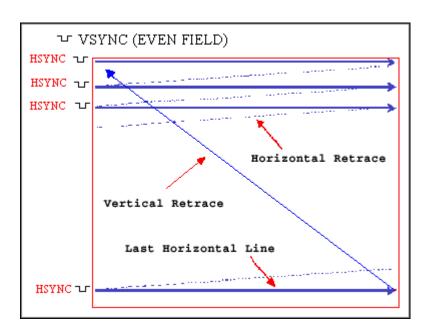
Cathode Ray Tube uses electron beams to light the fluorescent screen

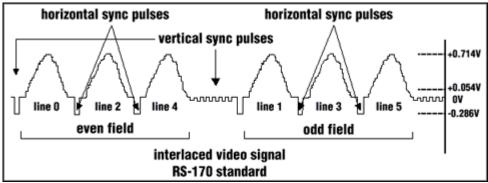


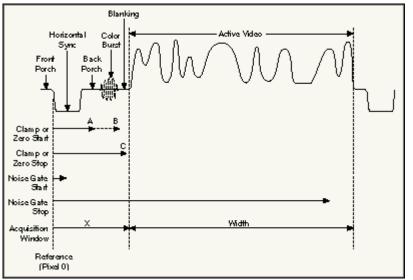


The image is shown by scanning through the whole screen with the single electron beam



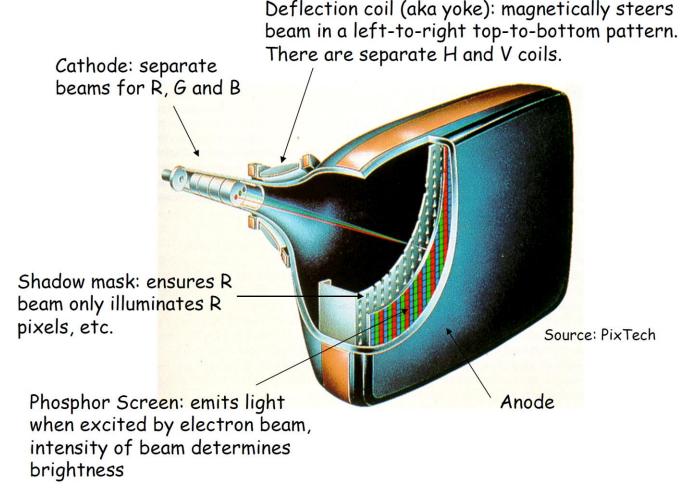






Color image is formed by using three electron beams scanning through three different color channels

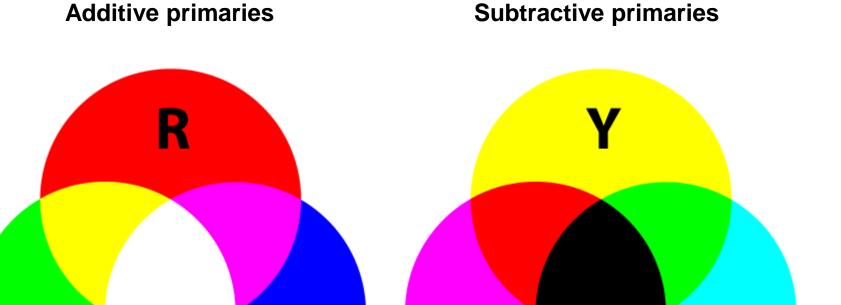




Color space

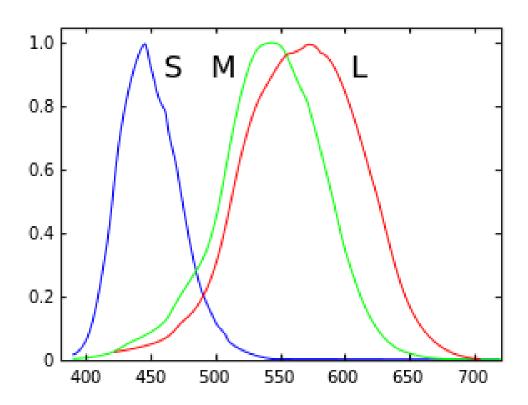
Color can be created using three primary colors





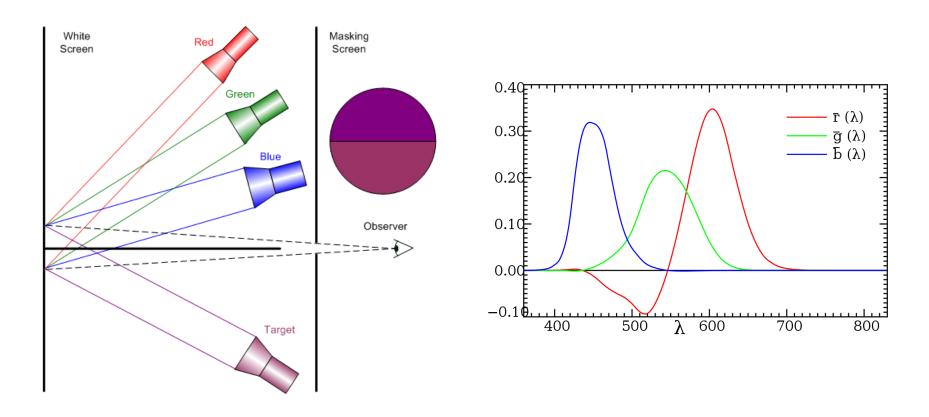
Human retina has three kinds of "cones" that have different spectral response





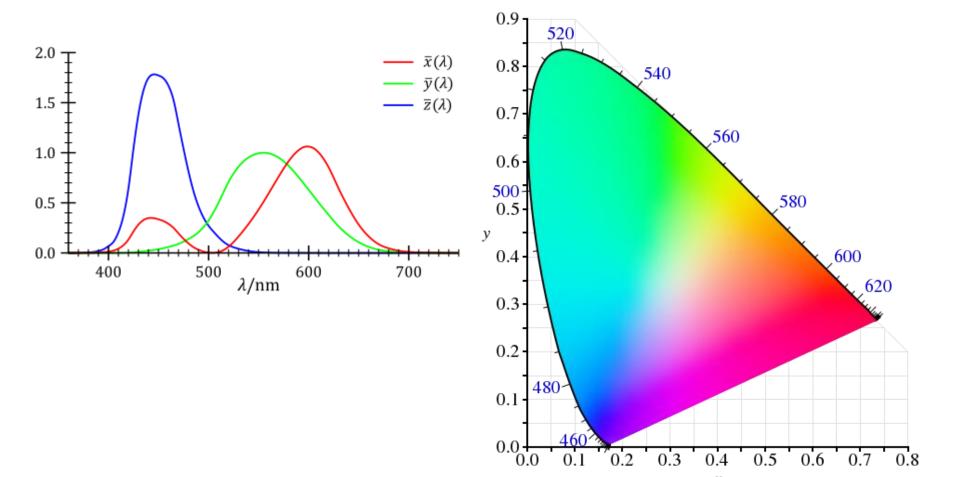
Spectral response of retina "cones" are tested using light sources with single wavelength





The CIE 1931 color space chromaticity diagram is the standard color space





0.1

0.2

0.3

0.4

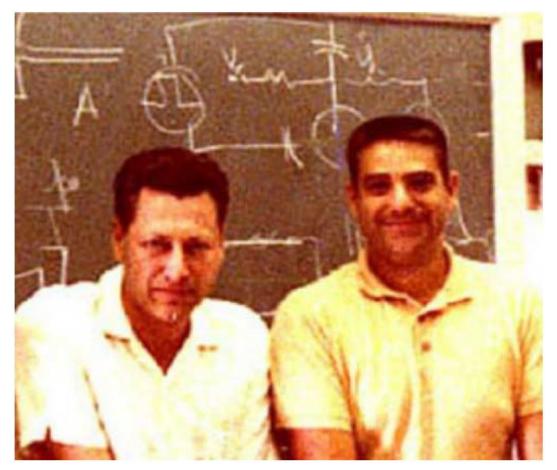
0.5

0.7

0.6

History of PDP

Plasma display panel was invented at the University of Illinois in 1967



Prof. H. Gene Slottow

Prof. Donald L. Bitzer

PDP was invented due to a need for Programmed Logic for Automatic Teaching Operations (PLATO) in 1960s





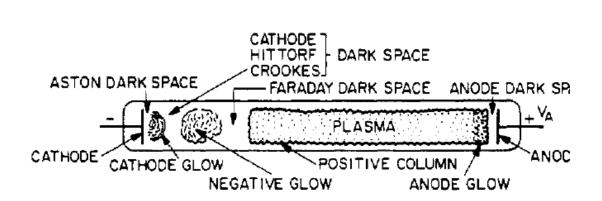


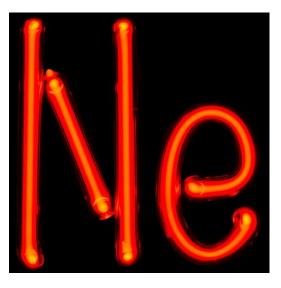


https://topwallpapers.pw/computer/keyboards-computers-history-teletype-typewriters-desktop-hd-wallpaper-1035981/https://en.wikipedia.org/wiki/Punched_tape https://en.wikipedia.org/wiki/PLATO_(computer_system)

The positive column in a glow discharge is used to excite phosphors in color PDP



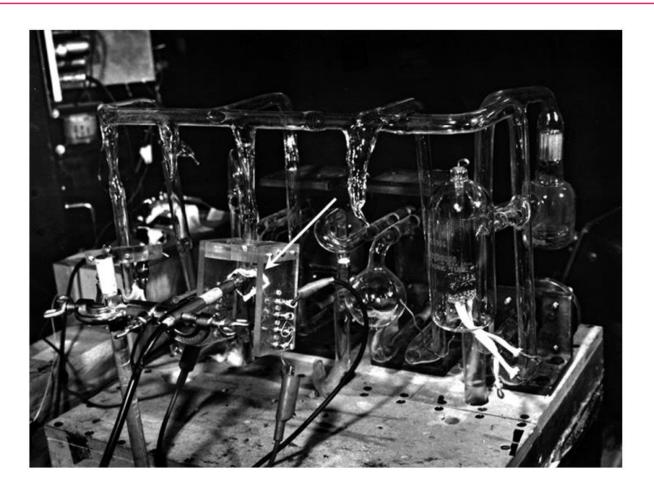




- Majority of monochrome PDPs use the negative glow as the light source
- The positive column is used to excite phosphors in fluorescent lamps and in color PDPs

Early plasma panel (PD) attached to the glass vacuum system used for the first plasma displays at UI

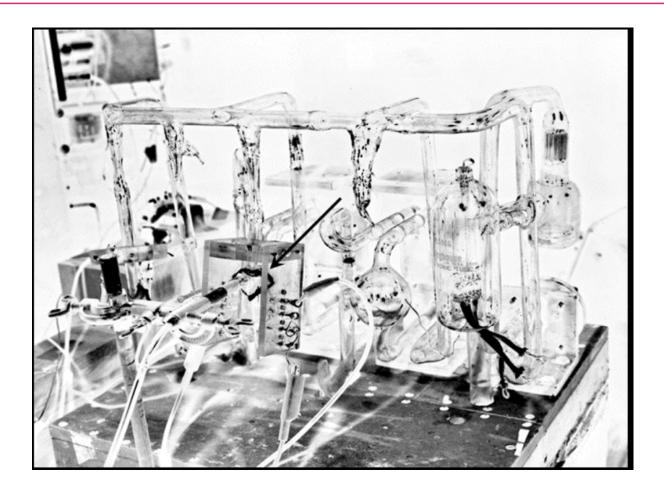




 It had the same alternating sustain voltage, neon, gas, and dielectric glass insulated electrodes that are used for plasma TVs today.

Early plasma panel (PD) attached to the glass vacuum system used for the first plasma displays at UI

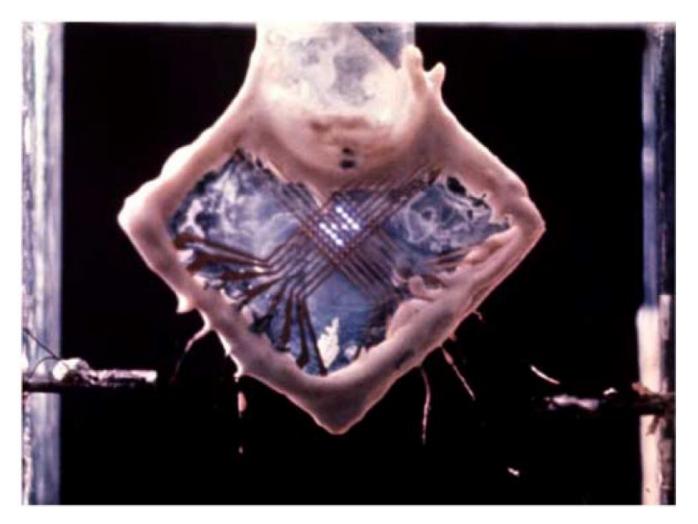




 It had the same alternating sustain voltage, neon, gas, and dielectric glass insulated electrodes that are used for plasma TVs today.

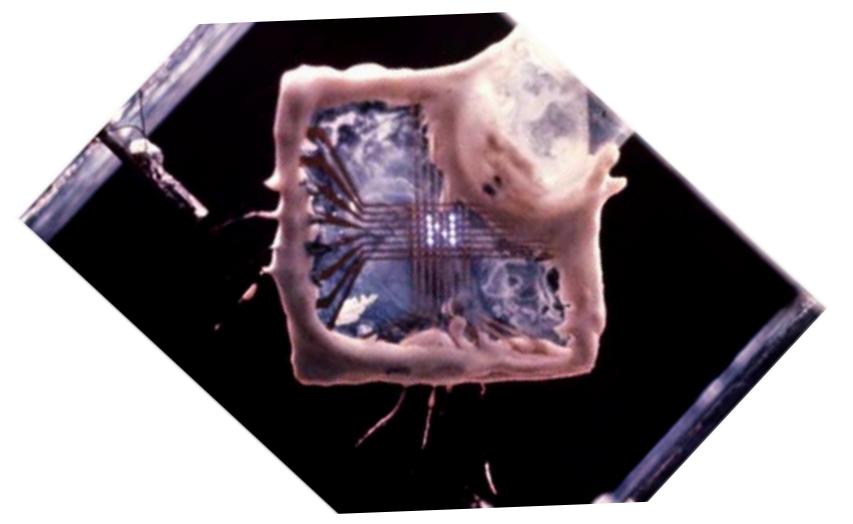
Early 4x4 pixel panel has achieved matrix addressability for the first time





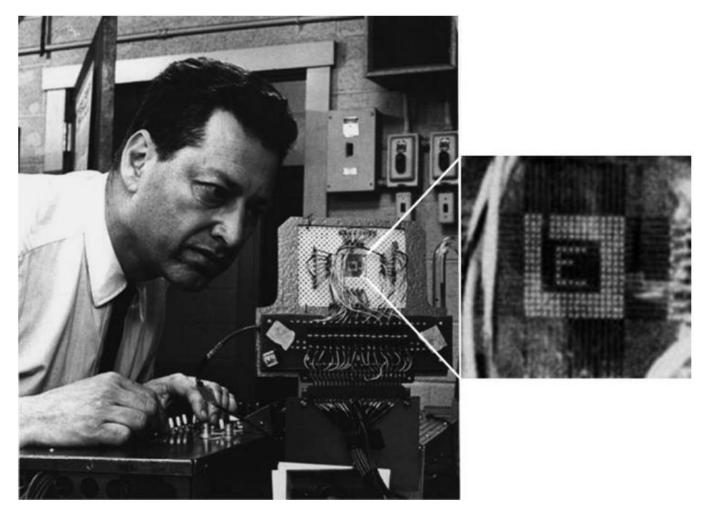
Early 4x4 pixel panel has achieved matrix addressability for the first time



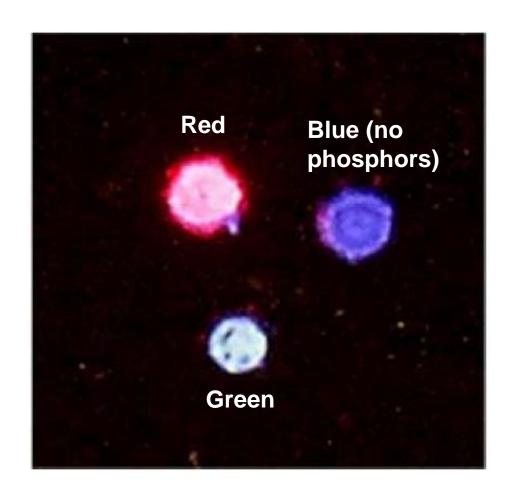


A 16x16 pixel PD, developed in 1967, needed to be addressed manually





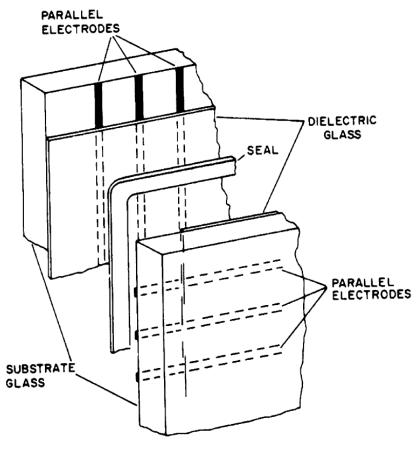
First color PD was three cell prototype with red and green color phosphors excited by a xenon gas discharge



Open-cell structure developed in 1968







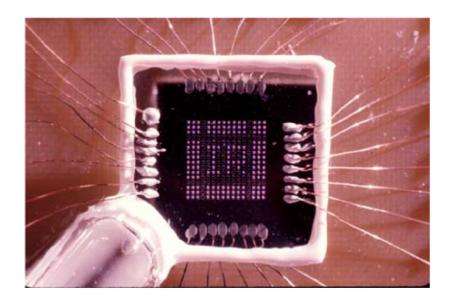
It could be baked under vacuum at 350 °C to drive out contaminants.

More progress



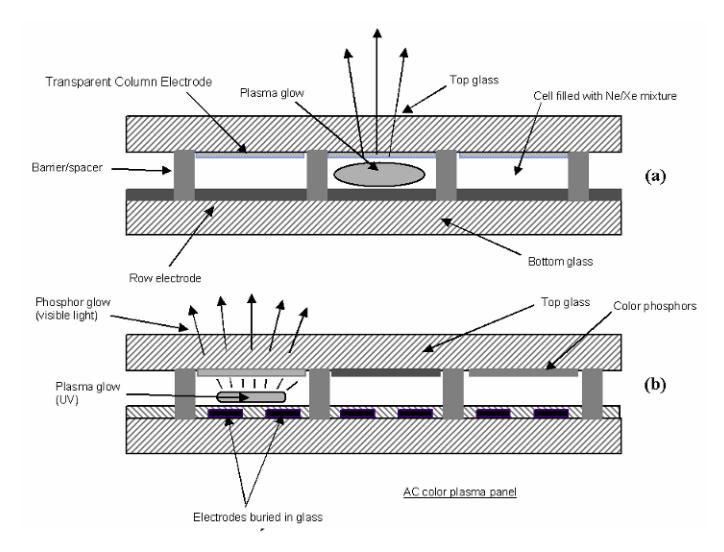
1968, University of Illinois 16x16 pixels

1971, Owens-Illinois 512x512 pixels



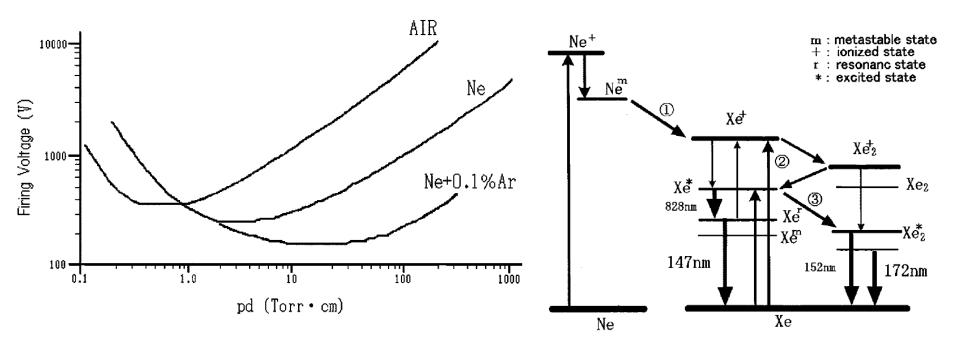


Color PDPs had short display lifetime due to the degradation of color phosphors caused by ion sputtering



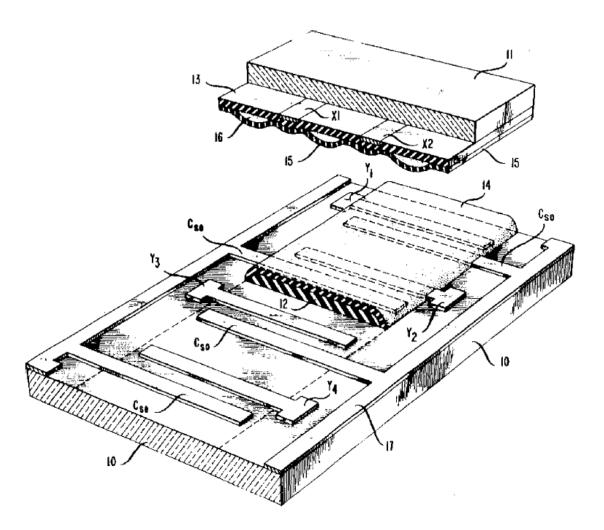
Design of PDP

A lower breakdown voltages can be obtained with very small amounts of added gas



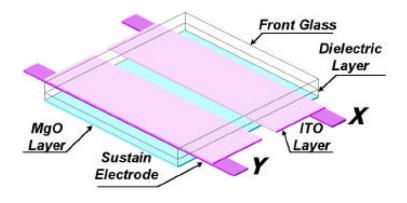
AT&T three-electrode patent

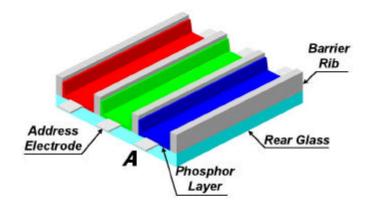


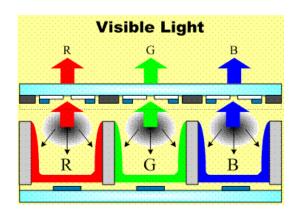


Reflective phosphor geometry is used in most of today's plasma TVs



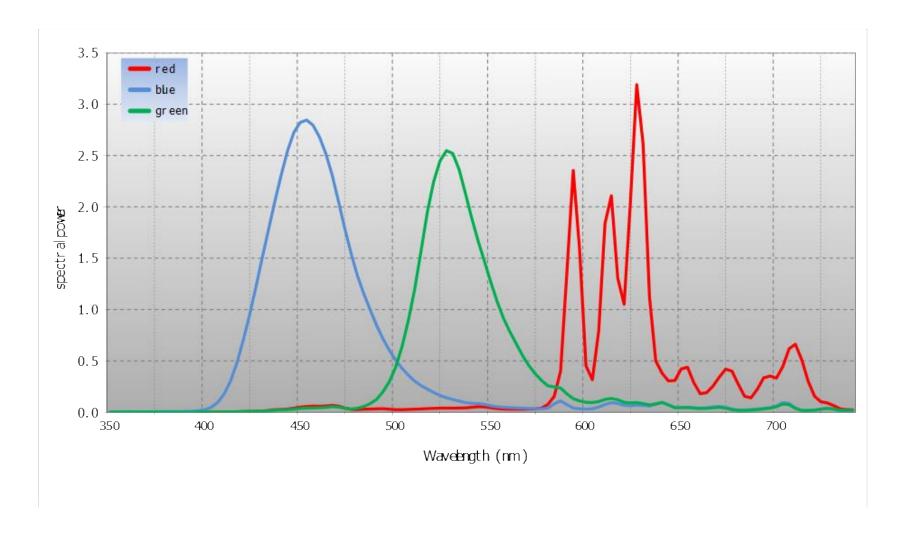






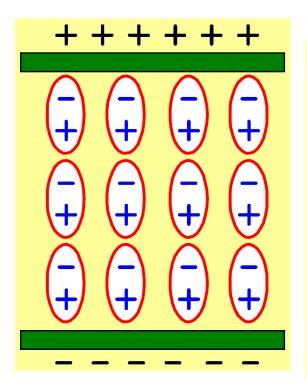
Spectrum of the different phosphors

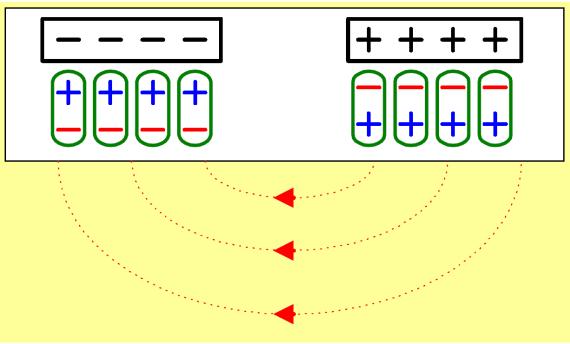




The foundation of AC discharge

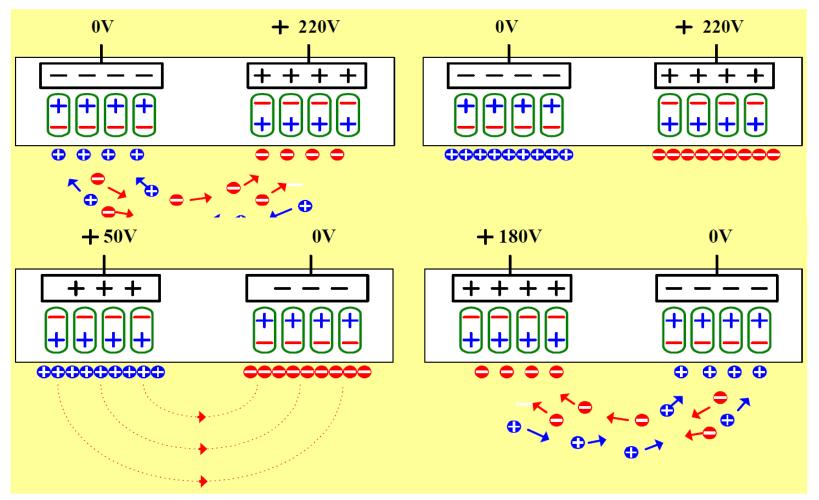






The plasma can be sustained using ac discharged

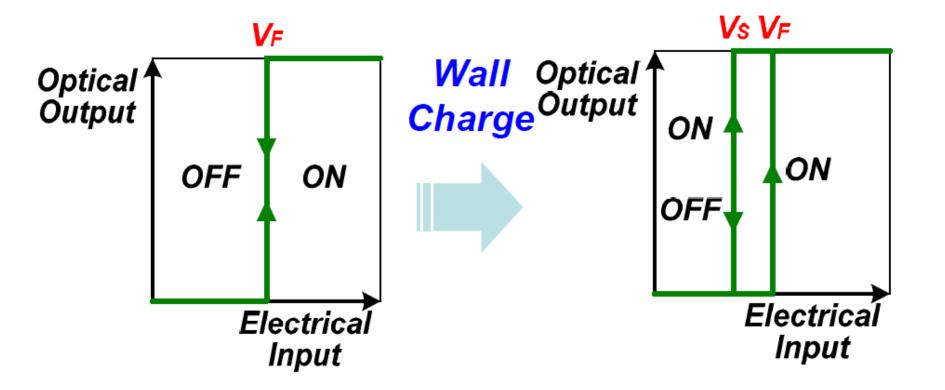




Wall discharge reduced the required discharge voltage

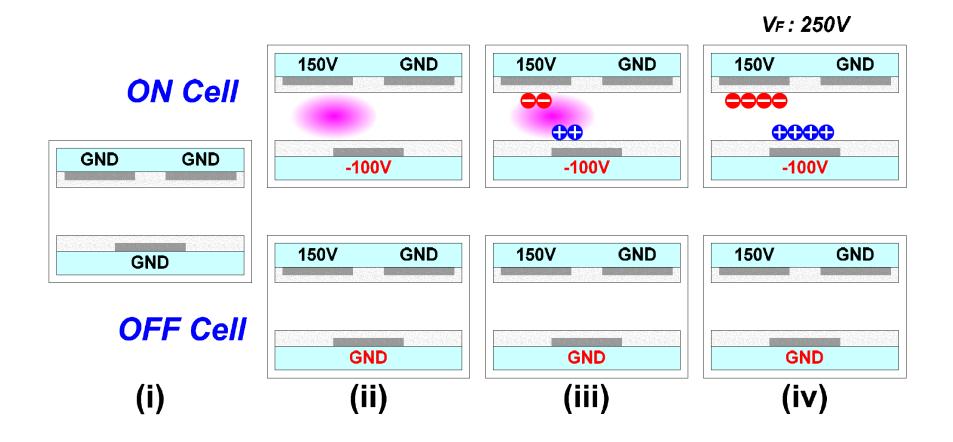
Wall discharge reduced the required discharge voltage





ON/OFF State Selection

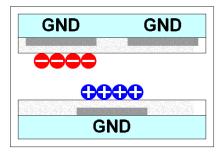


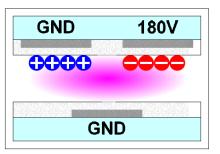


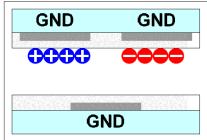
Sustain discharge

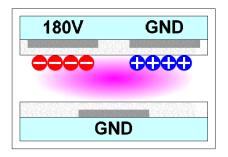


ON Cell

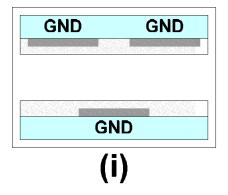


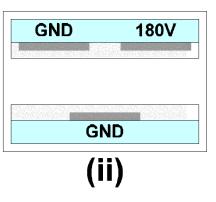


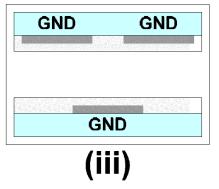


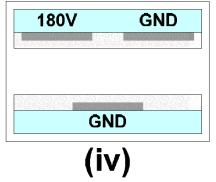


OFF Cell



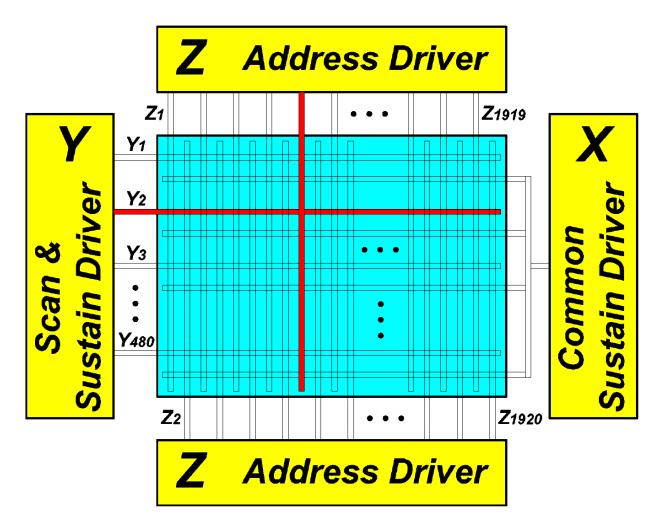






Address and sustain electrodes are connected to different drivers

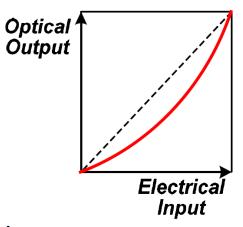




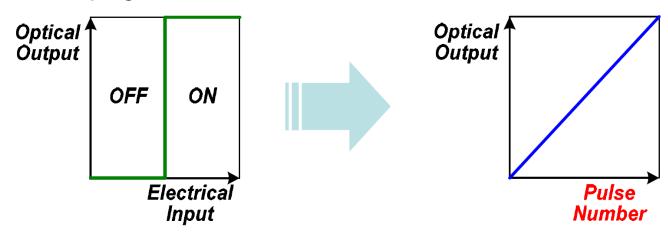
PDP pixel can only be either ON or OFF



Cathode Ray Tube :



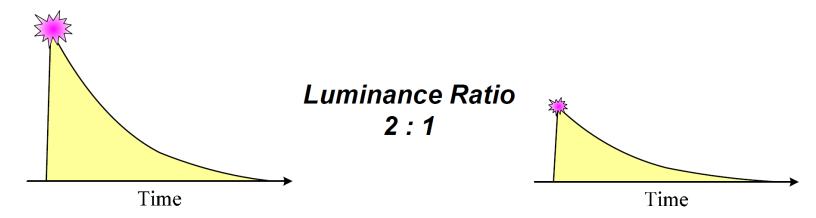
Plasma Display Panel :



PDP luminance is controlled by using number of light pulses



CRT : Control the Luminance using Electron Beam Intensity

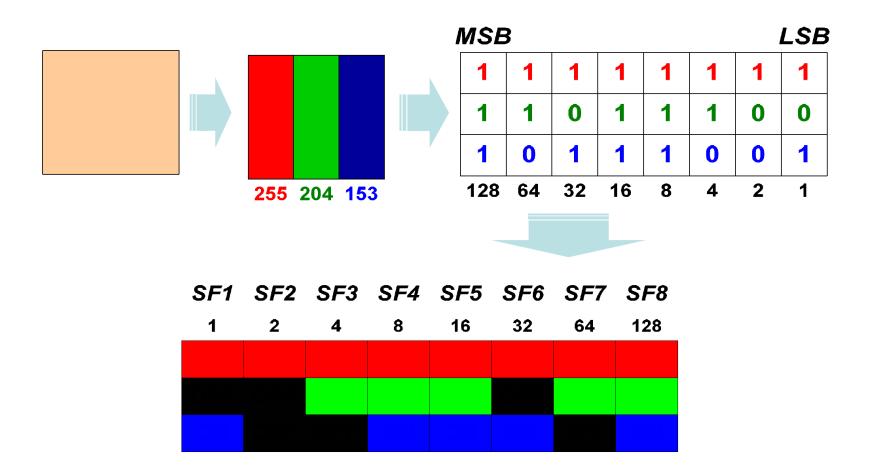


PDP : Control the Luminance using Number of Light Pulses



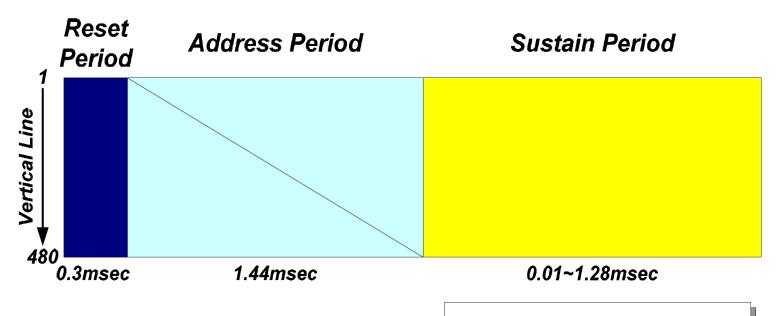
A single field is divided into 8 subfield





Composition of each subfield





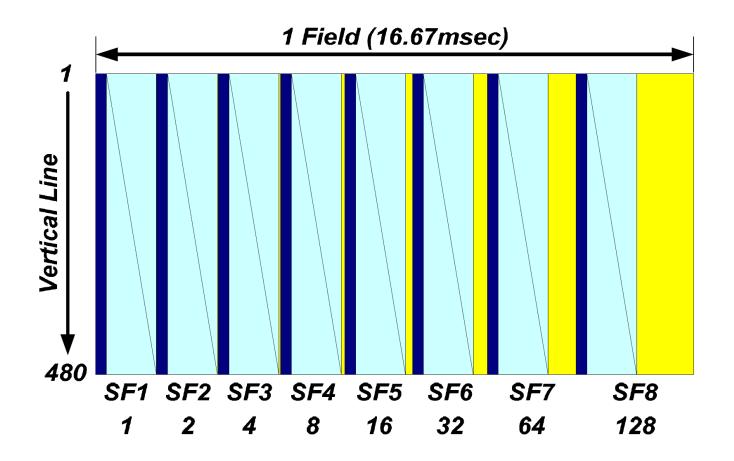
Spec: VGA (640*480) 8 Subfield

0.03msec Address Pulse

100KHz Sustain Freq.

8 subfield in one TV-Field (ADS)

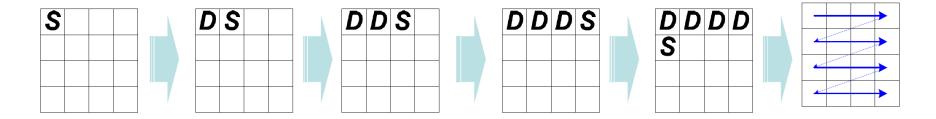




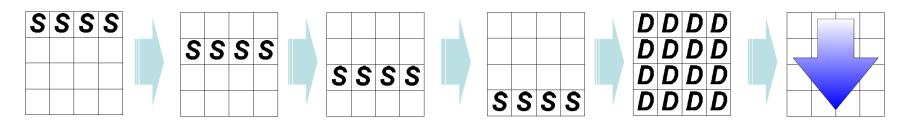
PDP uses line-by-line scanning



Cathode Ray Tube : Cell-by-Cell Scanning



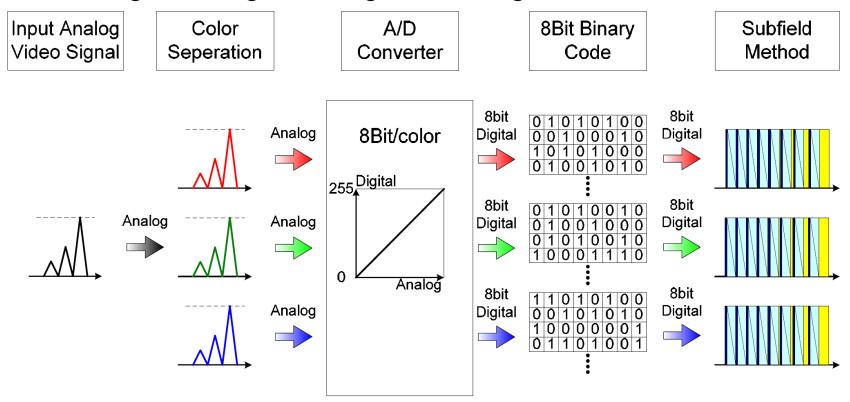
PDP: Line-by-Line Scanning



Video signal processing



Analog Video Signal ⇒ Digital Pulse Signal



Addressing period





Displaying period

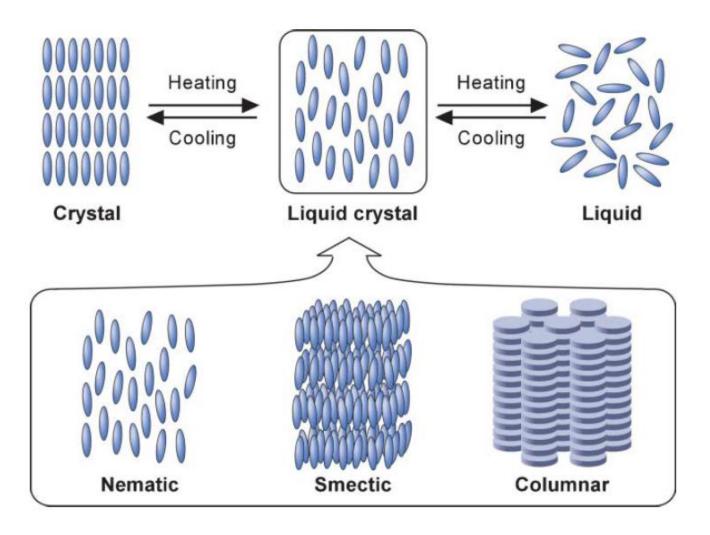






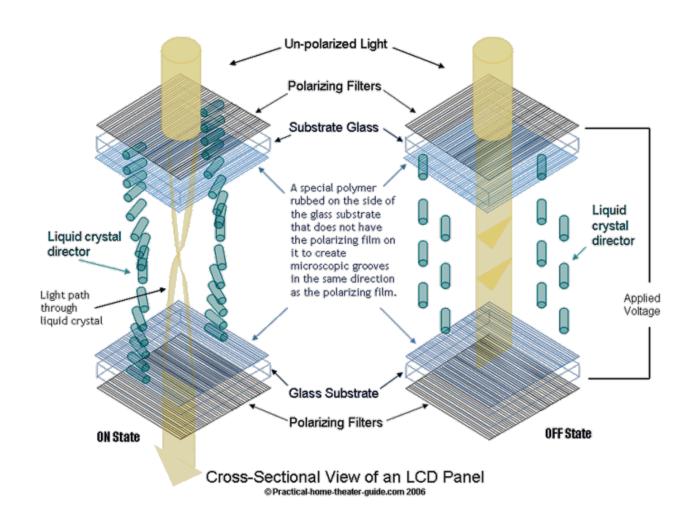
Liquid crystal are a special state of matter between liquid and crystal





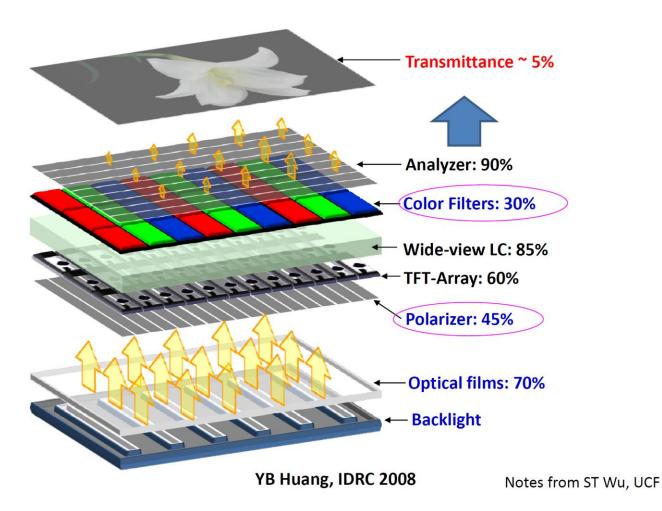
Linear polarization of a light can be rotated by miss aligned liquid crystal





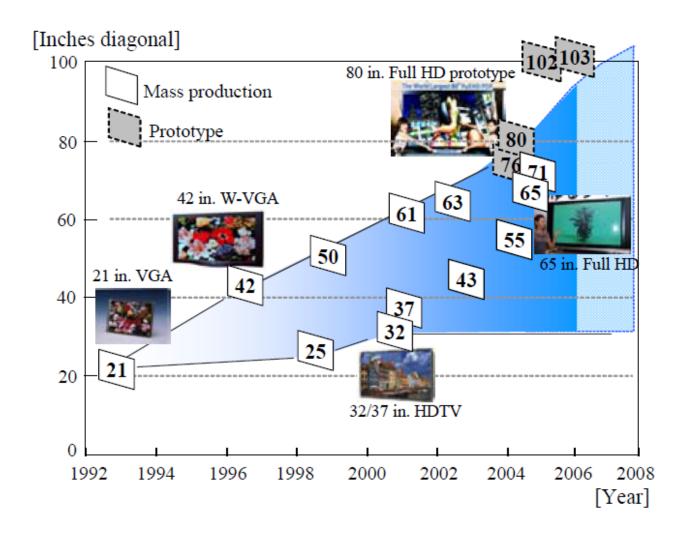
Structure of Liquid crystal display (LCD)





Optimistic projection of PDP market

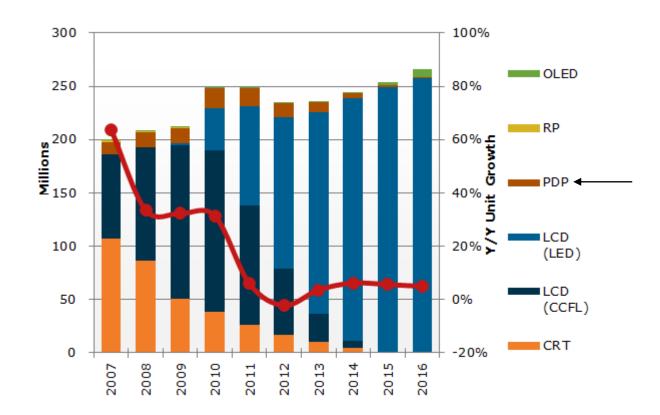




Reality



TV Shipment Growth by Technology



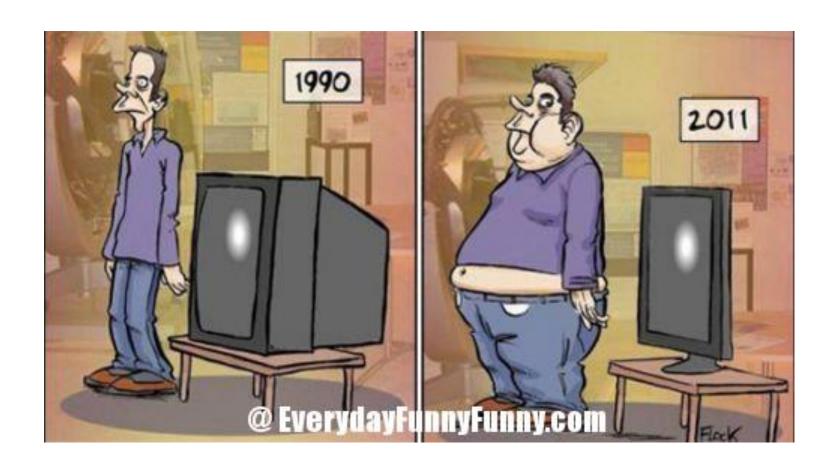
Too many reasons that PDP died!



- Bright showroom conditions put plasmas at a distinct disadvantage versus LED-lit LCDs
- Aesthetics may have played a role in hastening plasma's demise
- UHD/4K caught on quickly
- Screen-size limitations also played a part in plasmas plight
- You can't bend a plasma
- Plasmas were harder to deal with than LCDs
- While OLED is still in the early stages of development, there's no question it offers greater potential than plasma
- Energy efficiency may have played a part in putting plasma out to pasture
- Plasma was the original flat-panel technology, People just thought of it as old technology.
- Projectors improved in quality and prices dropped

Let's stand up and do exercise!!





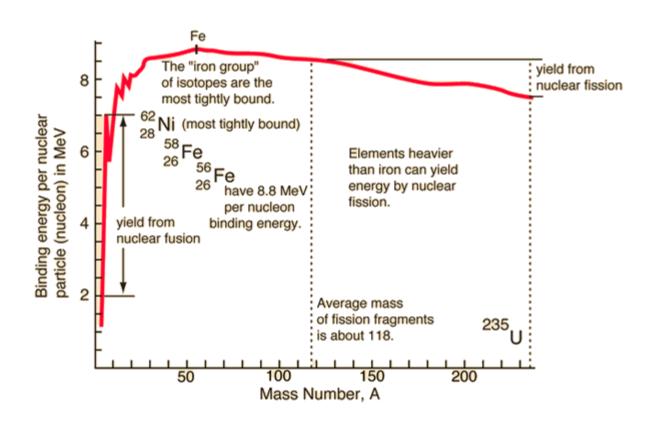
The hydrogen bomb





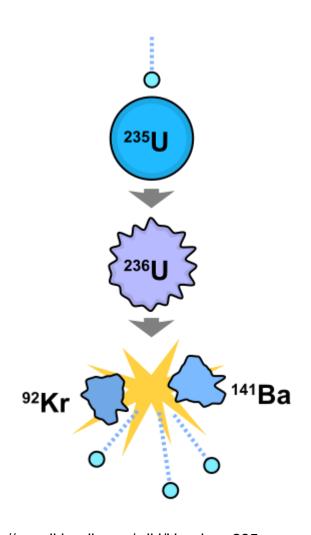
The "iron group" of isotopes are the most tightly bound





Chain reaction can happen in U²³⁵ fission reaction

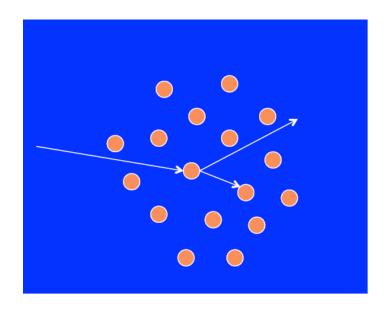




- ~ 200 million electron volts (MeV)/fission, ~million times more than chemical reactions
- Energy for bombs, or for civilian power can generate huge amounts of energy (and toxicity) in a small space with a modest amount of material
- Source of safety, security issues for nuclear power

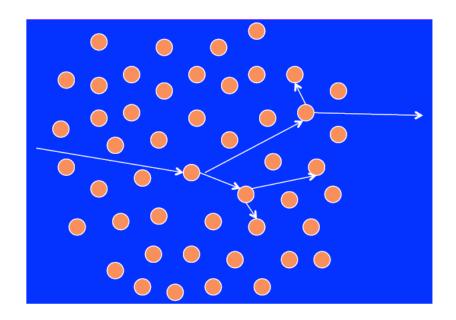
The neutrons are leaking out and stopping the chain reaction in a sub-critical mass





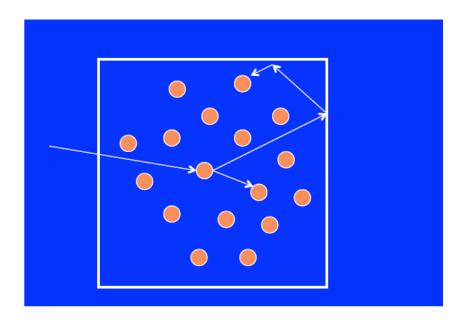
Solution 1: add more material





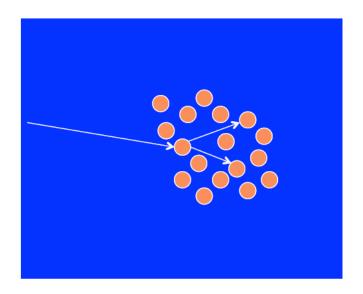
Solution2: reflect the neutron back in





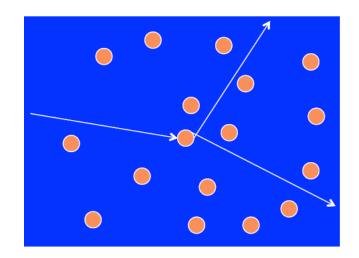
Solution 3: increase the density





How to get the material together before it blows apart?



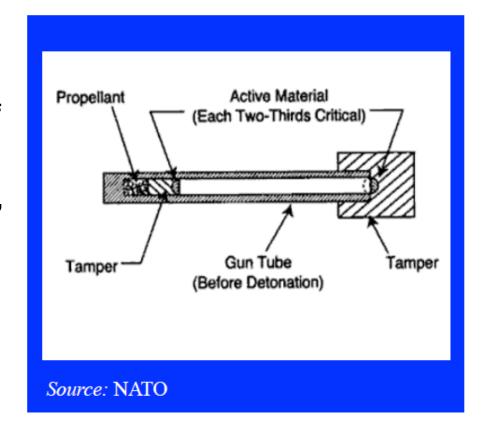


- There are always neutrons around
- Once chain reaction starts, material will heat up, expand, stop reaction
- How to get enough material together fast enough?

Gun-type bomb



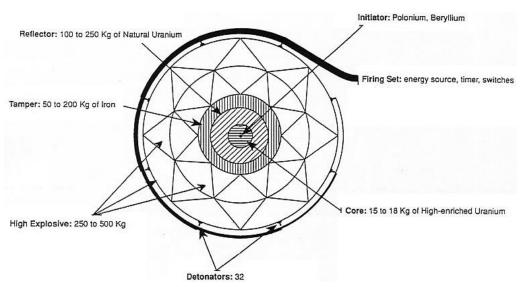
- Simple, reliable can be built without testing
- Highly inefficient require lots of nuclear material (50-60 kg of 90% enriched HEU)
- Can only get high yield with HEU, not plutonium
- Hiroshima bomb: cannon that fired HEU projectile into HEU target



Implosion design



 A schematic diagram of an implosion bomb



 Small-scale slow-motion cross-section of a shaped charge implosion design

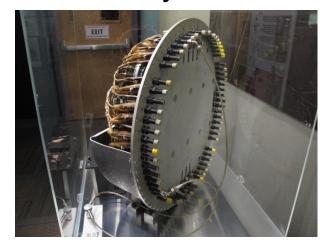


The 1st nuclear bomb: Trinity (Bradbury Science Museum)

Model of the Trinity Gadget



 Project Y Atomic Bomb Detonator System



https://www.flickr.com/photos/rocbolt/with/8061684482

Project Y Atomic Bomb Detonator System

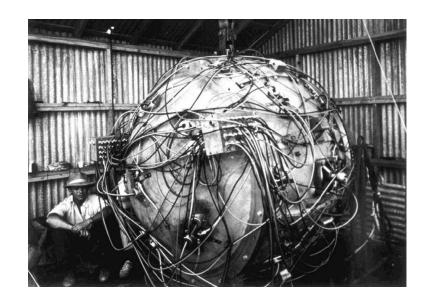


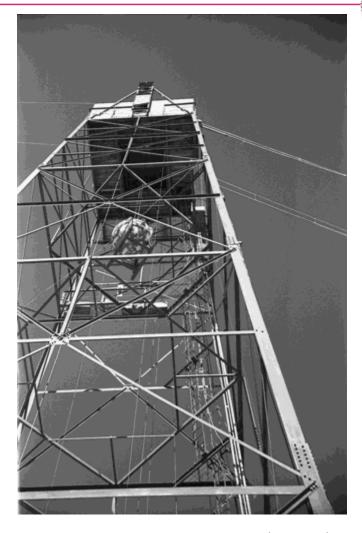
 Project Y Atomic Bomb Detonator System Spark Gap Switch



The 1st nuclear bomb: Trinity



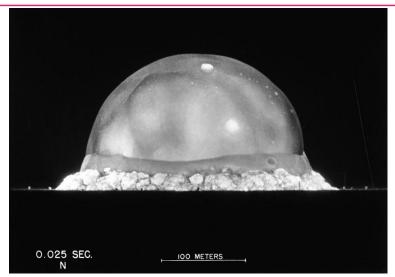


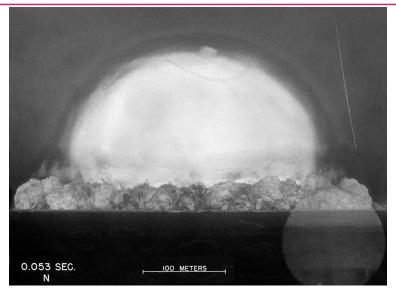


https://www.theatlantic.com/photo/2015/07/70-years-since-trinity-when-we-tested-nuclear-bombs/398735/https://saddlebagnotes.com/arts-and-leisure/tucson-seismographs-detected-first-nuclear-test-at-trinity-n-m/article_b01c5b20-f6fb-11eb-a221-6327df2feaeb.html

Trinity explosion on July 16, 1945





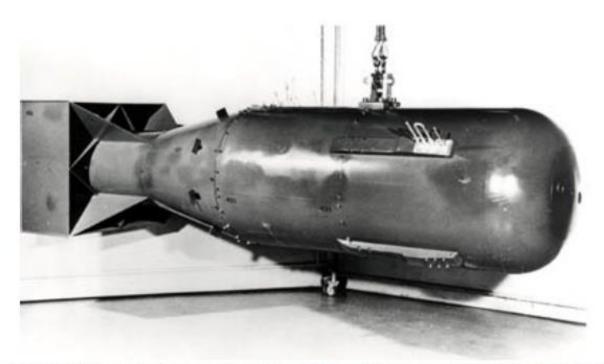




https://www.theatlantic.com/photo/2015/07/70-years-since-trinity-when-we-tested-nuclear-bombs/398735/https://en.wikipedia.org/wiki/Trinity_%28nuclear_test%29

Hiroshima Bomb – "Little Boy"





Gun Type – Easiest to design and build (Hiroshima bomb was never tested)

About 13 kiloton explosive yield

Atomic bomb is very destructive



Hiroshima: August 6, 1945

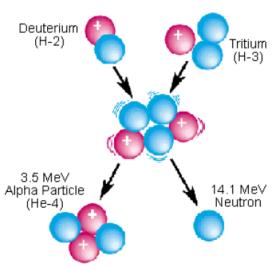


Nagasaki: August 9, 1945



The fusion process





 $^{2}H+^{3}H \Rightarrow ^{4}He+n+Q \equiv 17.6 \text{ MeV}$

Energy release Q=17.6 MeV

In comparison

$${}^{2}H+{}^{2}H \Rightarrow {}^{1}H+{}^{3}H +Q \equiv 4.0 \text{ MeV}$$
 ${}^{2}H+{}^{2}H \Rightarrow {}^{3}He+n +Q \equiv 3.2 \text{ MeV}$
 ${}^{3}H+{}^{3}H \Rightarrow {}^{4}He+2n+Q \equiv 11.3 \text{ MeV}$
 ${}^{235}U+n \Rightarrow X_{A}+X_{B}+3n +Q \approx 200 \text{ MeV}$

Deuterium-Tritium Fusion Reaction

Fusionable Material, deuterium ²H (D) and tritium ³H (t):

Deuterium: natural occurrence (heavy water) (0.015%).

Tritium: natural occurrence in atmosphere through cosmic ray bombardment; radioactive with $T_{1/2}$ =12.3 y.

"Advantages" of hydrogen bomb



Fusion of
$${}^{2}\text{H+}{}^{3}\text{H}$$
: $\frac{Q}{A} = \frac{17.6 \ MeV}{(3+2) \ amu} = 3.5 \frac{MeV}{amu}$

Fission of ²³⁵U:
$$\frac{Q}{A} = \frac{200 \ MeV}{236 \ amu} = 0.85 \frac{MeV}{amu}$$

Fusion is 4 times more powerful than fission and generates 24 times more neutrons!

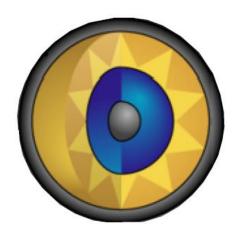
$$^{2}H + ^{3}H : \frac{n}{A} = \frac{1}{5} = 0.2$$

Neutron production:

$$^{235}U + n$$
: $\frac{n}{A} = \frac{2}{236} = 0.0085$

Hydrogen bomb uses a fission bomb to initiate the fusion reaction





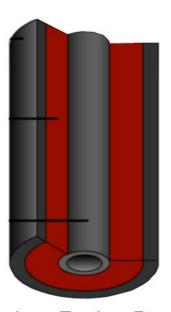
Fuel

Primary Fission Device

Core: ²³⁹Pu, ²³⁵U, plus ²H+³H booster

Shell: ²³⁸U tamper

High explosive lenses

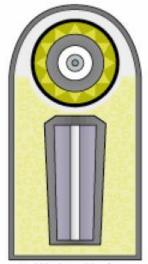


Secondary Fusion Device

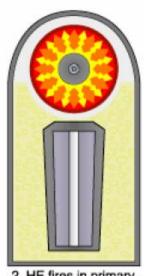
Radiation channel
²³⁹Pu sparkplug
⁶Li, ²H, ³H fusion cell
²³⁸U tamper

Event sequence

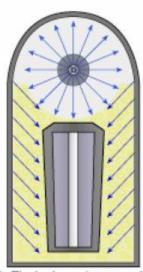




1. Warhead before firing; primary (fission bomb) at top, secondary (fusion fuel) at bottom, all suspended and beginning a fission in polystyrene foam.



2. HE fires in primary, compressing plutonium core into supercriticality reaction.



 Fissioning primary emits X-rays which reflect along the inside of the casing, irradiating the polystyrene foam.



Polystyrene foam becomes plasma, compressing secondary, and plutonium sparkplug begins to fission.

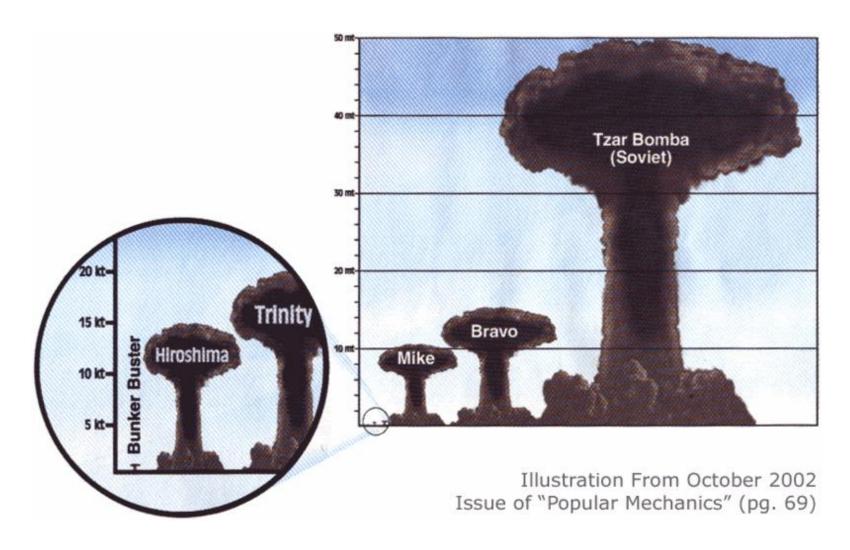


Compressed and heated, lithium-6 deuteride fuel begins fusion reaction, neutron flux causes tamper to fission. A fireball is starting to form...

Additional pressure from recoil of exploding shell (ablation)!

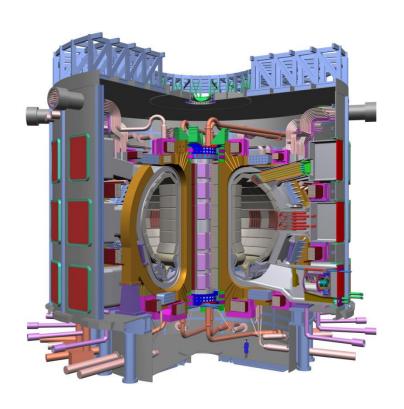
You don't want to build a hydrogen bomb!

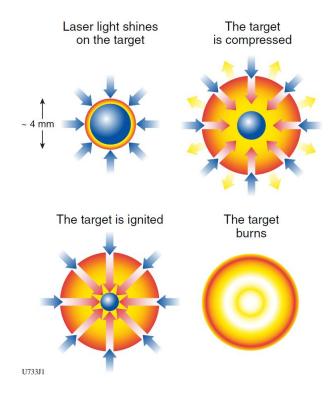




To Fuse, or Not to Fuse...







Outline



- Introduction to nuclear fusion
- Magnetic confinement fusion (MCF)
 - Tokamak
 - Stellarator
- Inertial confinement fusion (ICF)
 - Indirection drive ICF
 - Direct drive ICF
- Innovation idea MCF + ICF
- Pulsed-power system at NCKU

Outline

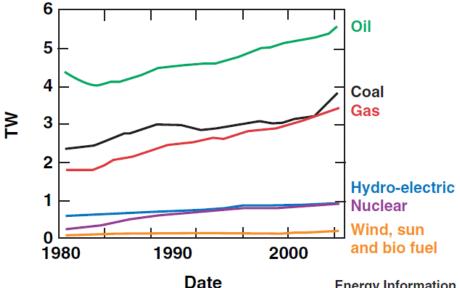


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World energy consumption is dominated by the use of dwindling fossil fuels



Fossil fuel	Estimated reserve	(2005 consumption rate) Years remaining
Oil	1,277,702 million barrels	32 years
Natural gas	~6,500,000 billion cubic ft	72 years
Coal	1,081,279 million tons	252 years



E15657

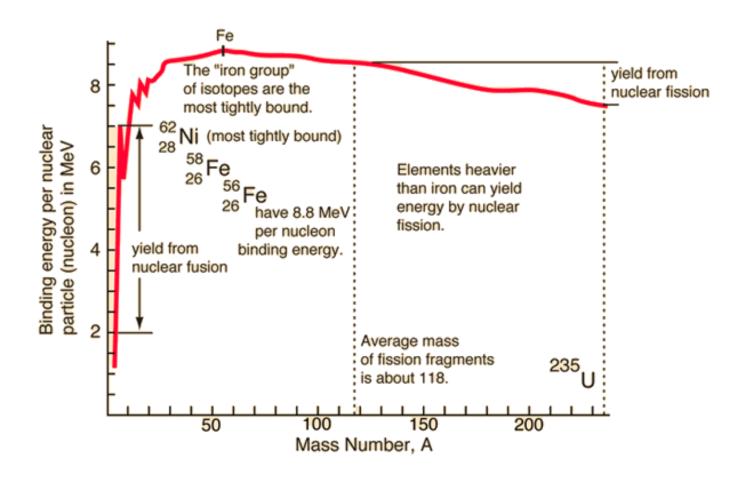
While predictions about the exact number of remaining years vary, fossil fuels will run out.

Energy Information Administration (EIA) 2006 Annual Report, U.S. Department of Energy, Washington, D.C.

^{*}from Laboratory for Laser Energetics, University of Rochester, Rochester, NY

The "iron group" of isotopes are the most tightly bound

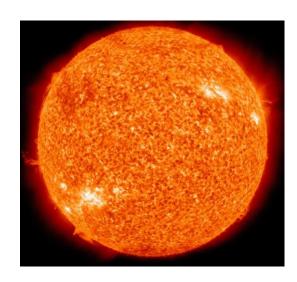




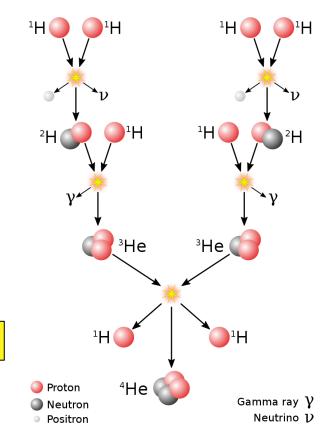
Fusion in the sun provides the energy



Proton-proton chain in sun or smaller

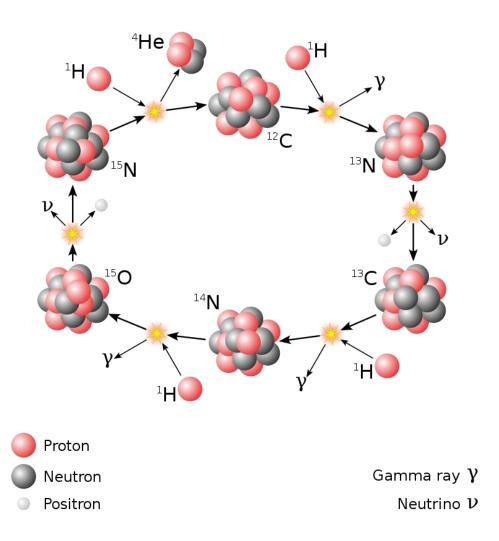


Particles are confined by the gravity.



In heavy sun, the fusion reaction is the CNO cycle





The cross section of proton-proton chain is much smaller than D T fusion

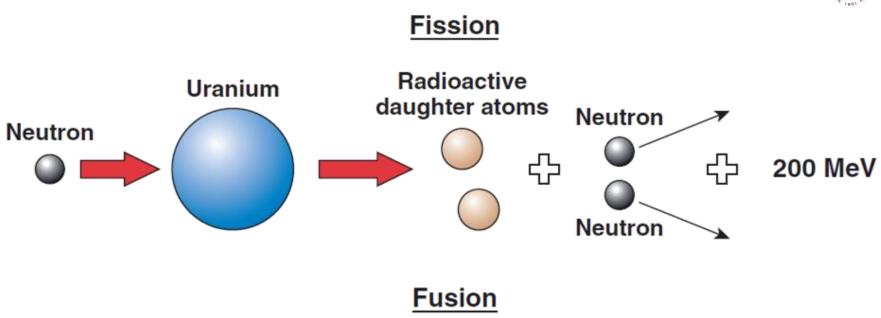


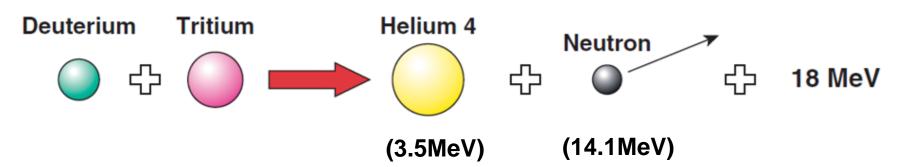
Reaction	σ _{10 keV} (barn)	σ _{100 keV} (barn)	σ _{max} (barn)	ε _{max} (keV)
D+T→α+n	2.72x10 ⁻²	3.43	5.0	64
D+T→T+p	2.81x10 ⁻⁴	3.3x10 ⁻²	0.06	1250
D+T→³He+n	2.78x10 ⁻⁴	3.7x10 ⁻²	0.11	1750
T+T→α+2n	7.90x10 ⁻⁴	3.4x10 ⁻²	0.16	1000
$D+^3He\rightarrow \alpha+p$	2.2x10 ⁻⁷	0.1	0.9	250
p+ ⁶ Li→α+ ³ He	6x10 ⁻¹⁰	7x10 ⁻³	0.22	1500
$p+^{11}B\rightarrow 3\alpha$	(4.6x10 ⁻¹⁷)	3x10 ⁻⁴	1.2	550
p+p→D+e++v	(3.6x10 ⁻²⁶)	(4.4x10 ⁻²⁵)		
$p+^{12}C\rightarrow^{13}N+\gamma$	(1.9x10 ⁻²⁶)	2.0x10 ⁻¹⁰	1.0x10.4	400
¹² C+ ¹² C (all branches)		(5.0x10 ⁻¹⁰³)		

• "()" are theoretical values while others are measured values.

Nuclear fusion and fission release energy through energetic neutrons







Nuclear fusion provides more energy per atomic mass unit (amu) than nuclear fission



Fusion of
$${}^{2}\text{H+}{}^{3}\text{H}$$
: $\frac{Q}{A} = \frac{17.6 \ MeV}{(3+2) \ amu} = 3.5 \frac{MeV}{amu}$

Fission of ²³⁵U:
$$\frac{Q}{A} = \frac{200 \ MeV}{236 \ amu} = 0.85 \frac{MeV}{amu}$$

	Half-life (years)	
U235	7.04x10 ⁸	
U238	4.47x10 ⁹	
Tritium	12.3	

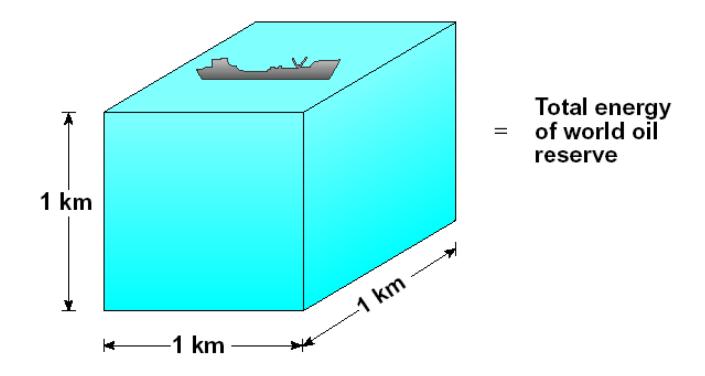
What could you do with 1 kg DT?



- 1 kg DT -> 340 Tera joules
 - You can drive your car for ~40,000 km (back and forth between Keelung and Kaoshiung for 50 times).
 - You can keep your furnace running for 8 years.
 - You can blow things up! 1 TJ = 250 tons of TNT.

Enormous fusion fuel can be produced from sea water





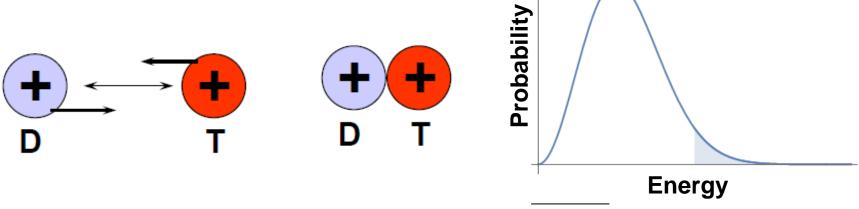
A "hot plasma" at 100M °C is needed



 Probability for fusion reactions to occur is low at low temperatures due to the coulomb repulsion force.



 If the ions are sufficiently hot, i.e., large random velocity, they can collide by overcoming coulomb repulsion

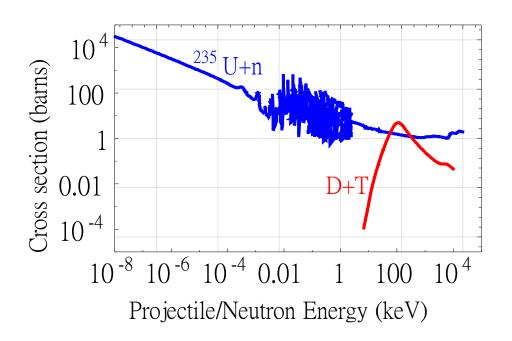


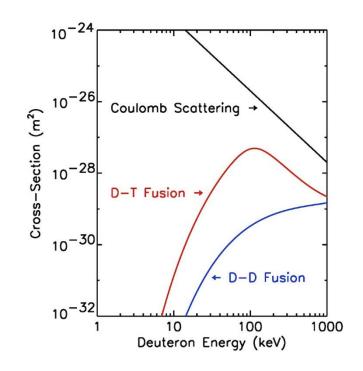
Fusion is much harder than fission, a "hot plasma" at 100M °C is needed



- Fission: $n +_{92}^{235} U \to_{92}^{236} U \to_{56}^{144} Ba +_{36}^{89} Kr + 3n + 177 \text{ MeV}$
- **Fusion:** $D + T \to He^4 (3.5 \text{ MeV}) + n (14.1 \text{ MeV})$







Fast neutrons are slowed down due to the collisions



$$\begin{array}{ccc} \text{Neutron} & \longrightarrow & \bigoplus & \text{Atom} \\ & m_N & & m_M \end{array}$$

- A moderator is used to slow down fast neutrons but not to absorb neutrons.
- For $m_M \sim m_N$, the energy decrement is higher. Therefore, H slows down neutron most efficiently.
- However, H + n → D, i.e., H absorbs neutrons.
- The best option is the D in the heavy water (D₂O).

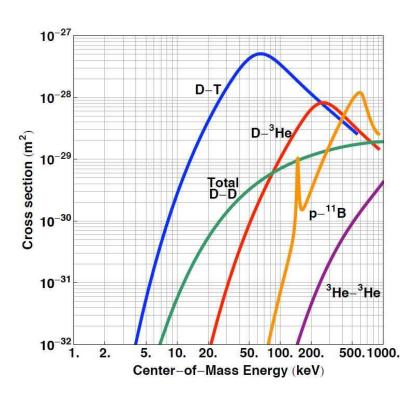
	Energy decrement		Neutron absorption cross section (σs) (Barns)
Н	1	49 (H ₂ O)	0.66 (H ₂ O)
D	0.7261	10.6 (D ₂ O)	0.0013 (D ₂ O)
С	0.1589	4.7 (Graphite)	0.0035 (Graphite)

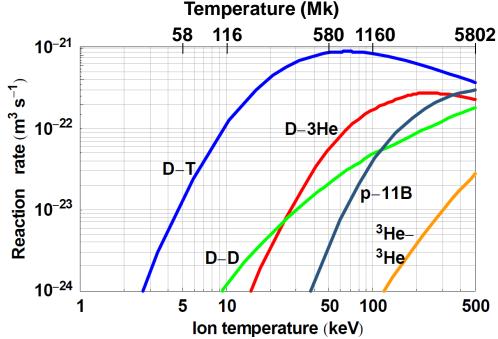
Fusion doesn't come easy



Probability

0.4



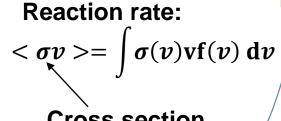


$$\begin{array}{c} D+D \rightarrow T+p \\ \rightarrow He^3+n \end{array}$$

$$D + T \rightarrow He^4 + n$$

$$D + He^3 \rightarrow He^4 + p$$

$$p + B^{11} \rightarrow 3He^4$$



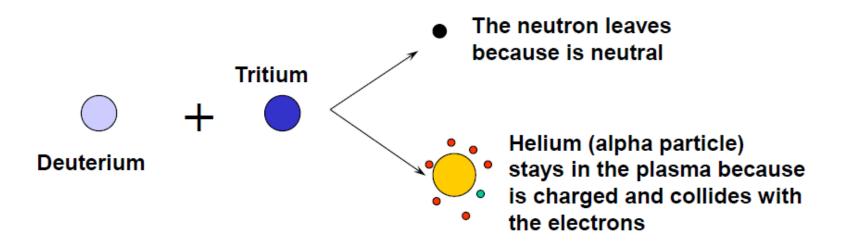
Cross section

https://i.stack.imgur.com/wXQD5.jpg Santarius, J. F., "Fusion Space Propulsion - A Shorter Time Frame Than You Think", JANNAF, Monterey, 5-8 December 2005.

It takes a lot of energy or power to keep the plasma at 100M °C



Let the plasma do it itself!



The α-particles heat the plasma.

Under what conditions the plasma keeps itself hot?



Steady state 0-D power balance:

$$S_{\alpha}+S_{h}=S_{B}+S_{k}$$

 S_{α} : α particle heating

S_h: external heating

S_B: Bremsstrahlung radiation

S_k: heat conduction lost

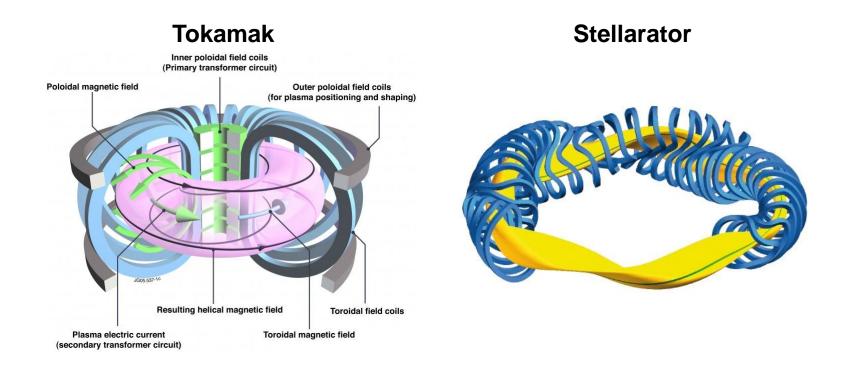
Ignition condition: PT > 10 atm-s = 10 Gbar - ns

- P: pressure, or called energy density
- т is confinement time

The plasma is too hot to be contained



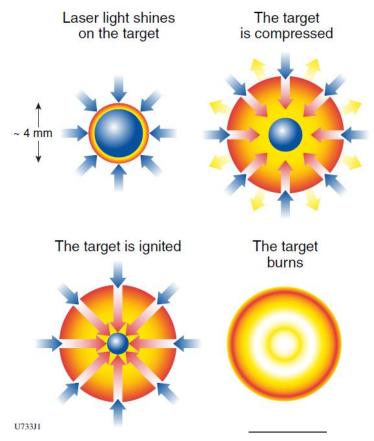
 Solution 1: Magnetic confinement fusion (MCF), use a magnetic field to contain it. P~atm, τ~sec, T~10 keV (10⁸ °C)



Don't confine it!



 Solution 2: Inertial confinement fusion (ICF). Or you can say it is confined by its own inertia: P~Gigabar, τ~nsec, T~10 keV (10⁸ °C)

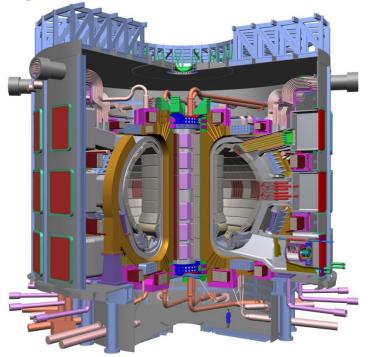


Inertial confinement fusion: an introduction, Laboratory for Laser Energetics, University of Rochester

To control? Or not to control?

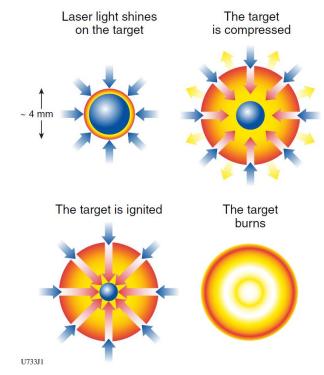


Magnetic confinement fusion (MCF)



Plasma is confined by toroidal magnetic field.

Inertial confinement fusion (ICF)



A DT ice capsule filled with DT gas is imploded by laser.

Laboratory for Laser Energetics, University of Rochester is a pioneer in laser fusion

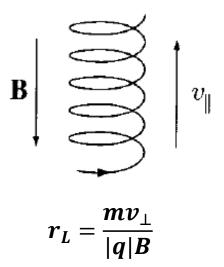
Outline

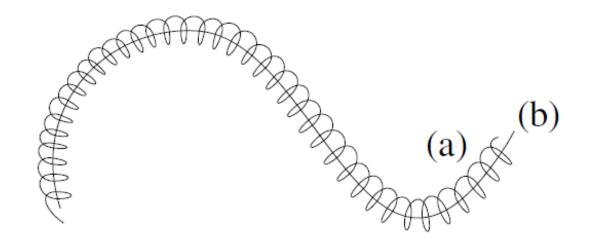


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Charged particles gyro around the magnetic fields



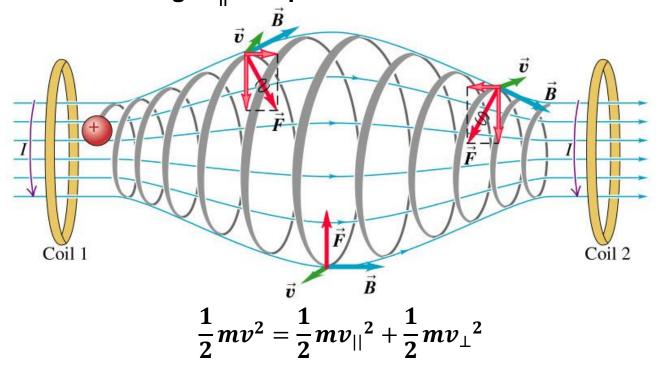




Charged particles can be partially confined by a magnetic mirror machine



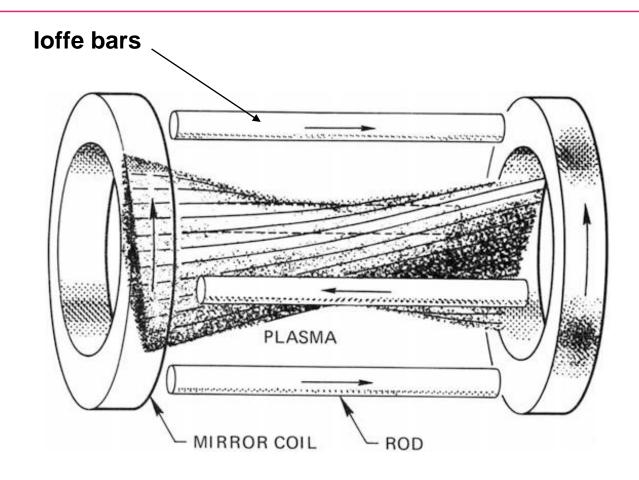
• Charged particles with small $v_{||}$ eventually stop and are reflected while those with large $v_{||}$ escape.



- Large v_{||} may occur from collisions between particles.
- Those confined charged particle are eventually lost due to collisions.

"loffe bars" are added to stabilize the Rayleigh-Taylor instabilities at the center of the mirror machine

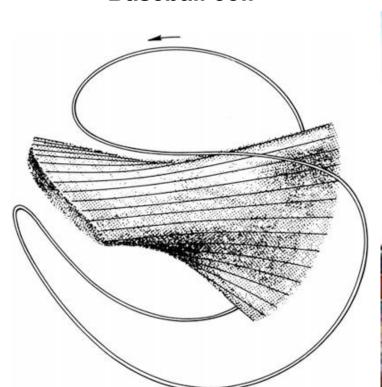




A "baseball coil" is obtained if one links the coils and the bars into a single conductor



Baseball coil

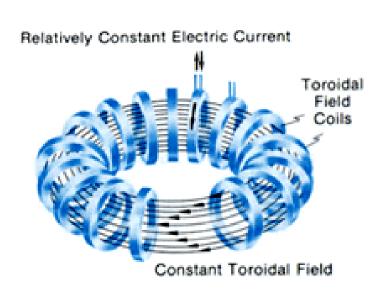


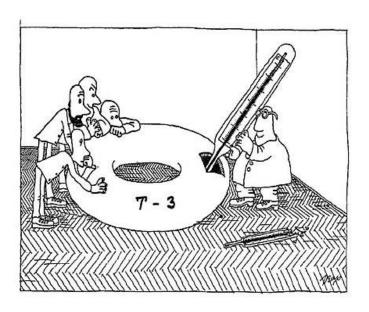
MFTF-B mirror machine



Plasma can be confined in a doughnut-shaped chamber with toroidal magnetic field

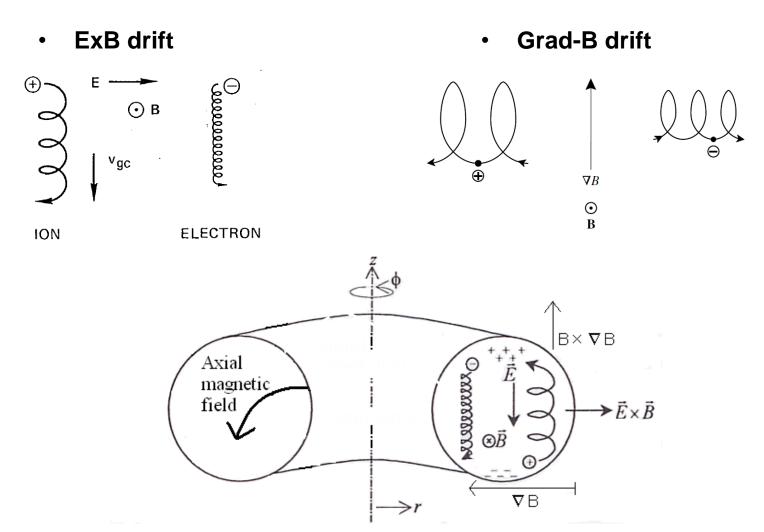
• Tokamak - "toroidal chamber with magnetic coils" (тороидальная камера с магнитными катушками)





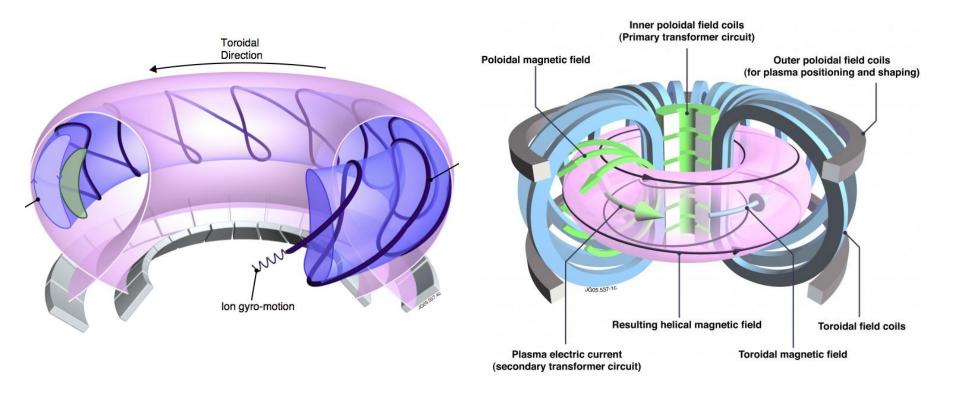
Charged particles drift across field lines





A poloidal magnetic field is required to reduce the drift across field lines



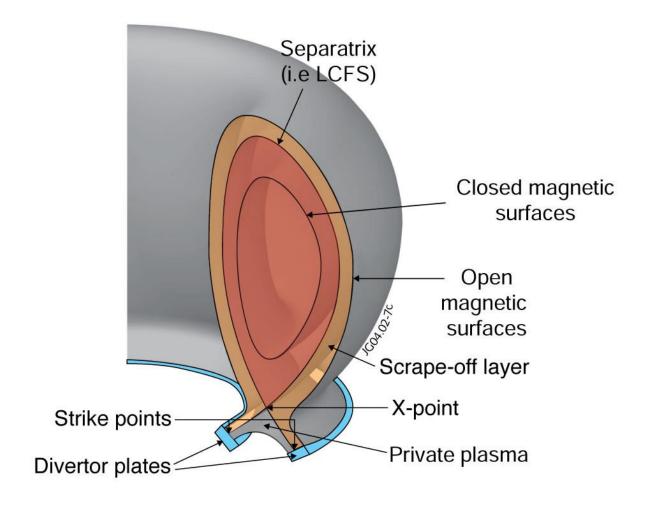


A poloidal magnetic field is required to reduce the drift across field lines



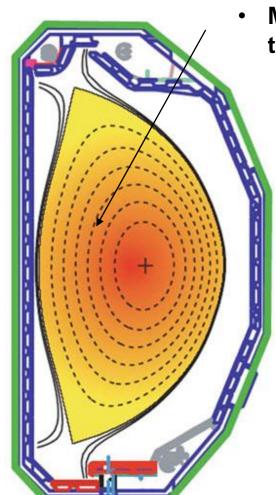
A divertor is needed to remove impurities and the power that escapes from the plasma





D-shaped tokamak with diverter is more preferred nowadays

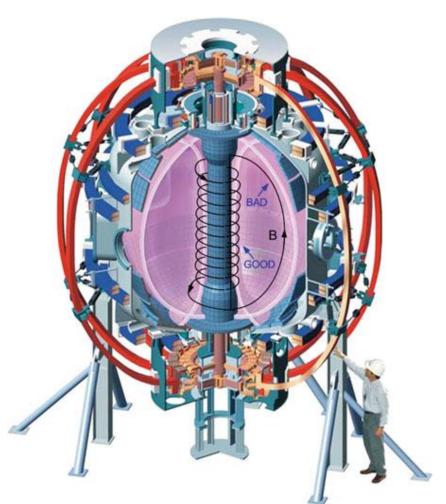




Make the plasma closer to the major axis

Spherical tokamak is formed when the aspect ratio of a tokamak is reduced to the order of unity

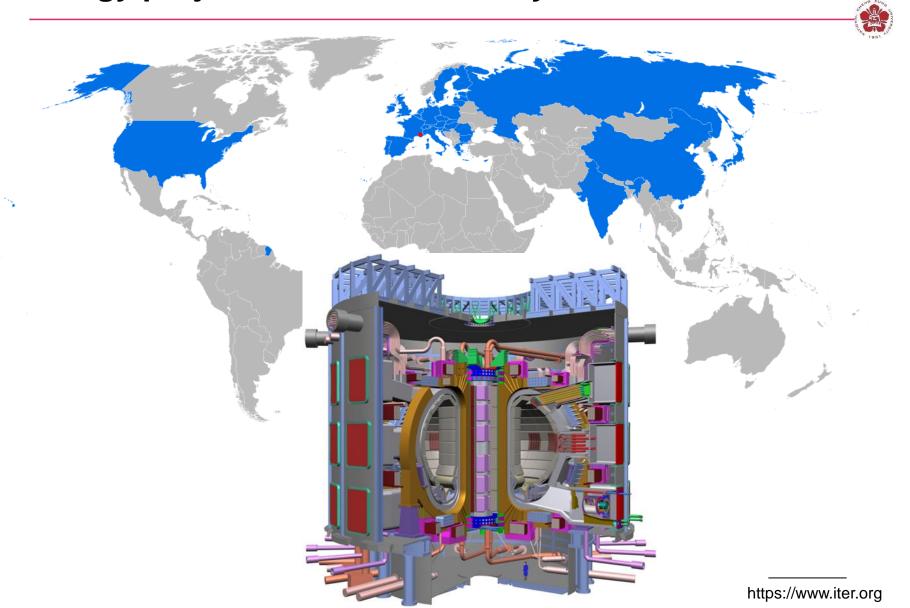
NSTX @ Princeton



MegaAmpere Spherical Tokamak (MAST) @ Culham center for fusion energy, UK

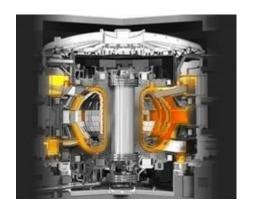


ITER ("The Way" in Latin) is one of the most ambitious energy projects in the world today

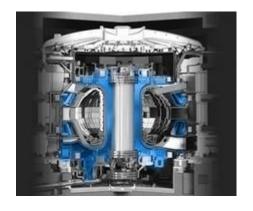


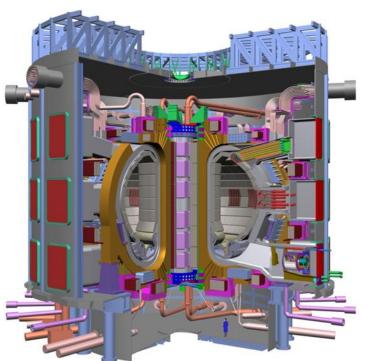
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Vacuum vessel

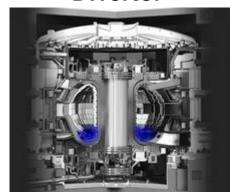


Magnets

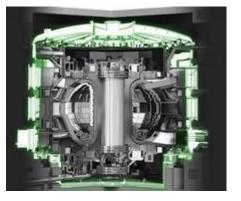




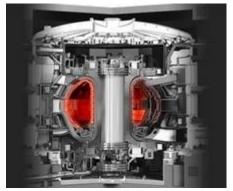
Divertor



Cryostat



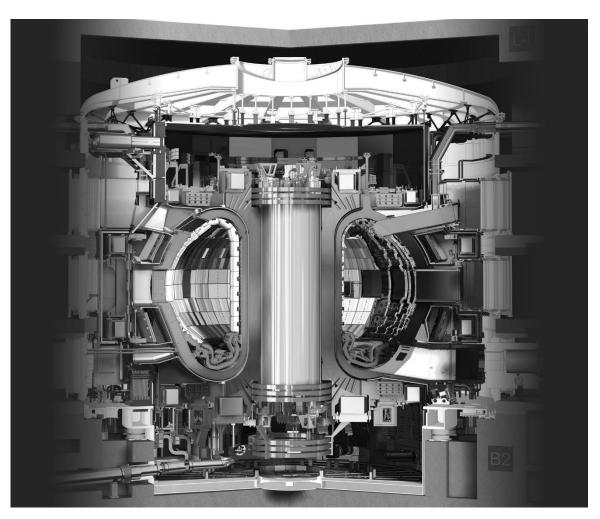
Blanket



ITER



- T=150M °C
- P=500 MW



ITER – Magnets



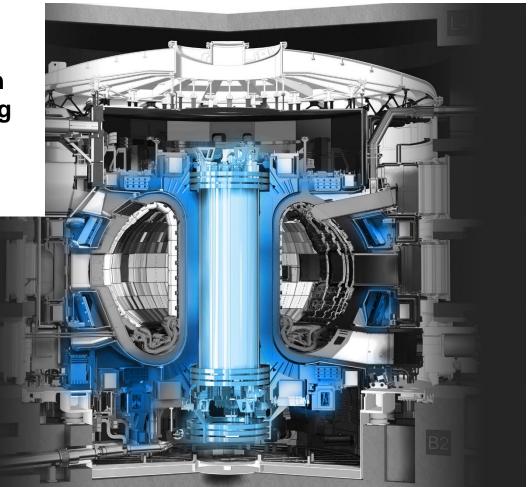
• E_B=51 GJ

T_B=4 K

 Length of Nb₃Sn superconducting strand: 10⁵ km

• $B_{T,max} = 11.8 T$

• B_{P,max}=6 T



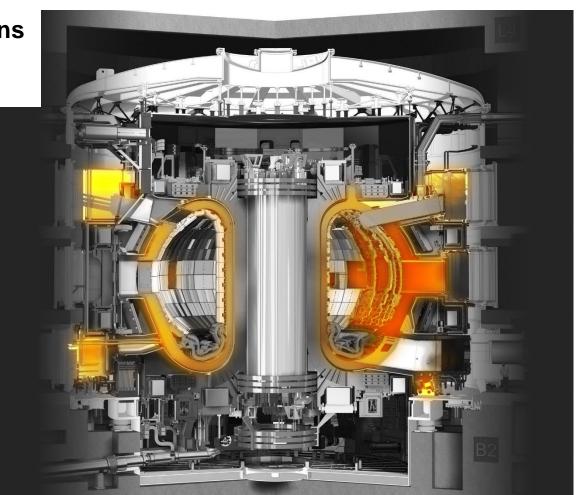
ITER - Vacuum vessel



• W = 8000 tons

• $V = 840 \text{ m}^3$

• R = 6 m

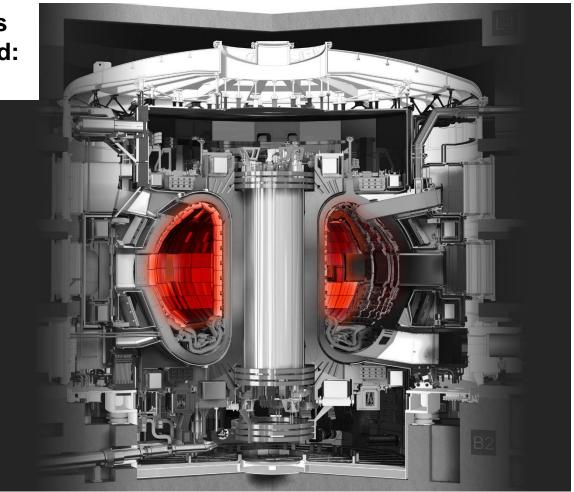


ITER - Blanket



• 440 modules

Thermal load:736 MW



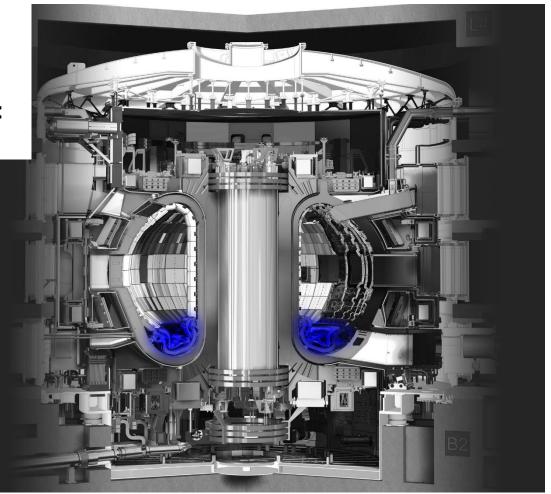
ITER - Divertor



54 cassettes

Thermal load:
 20 MW/m²

Each cassette:10 tons



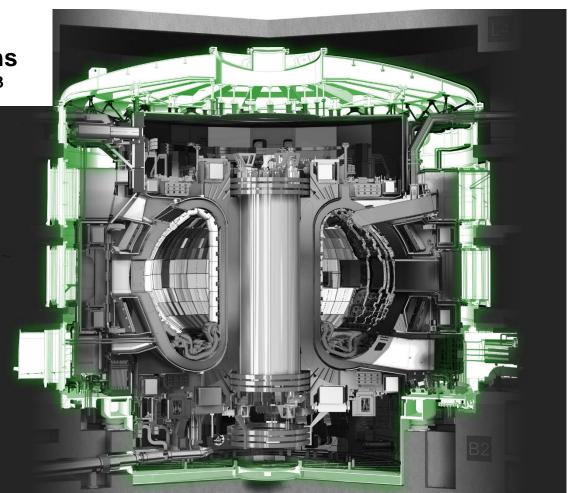
ITER – Crystat



• $P = 10^{-6}$ atm

• W = 3800 tons

• $V = 16000 \text{ m}^3$



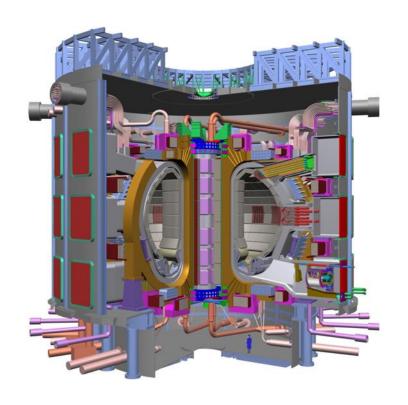
Supporting systems



- Tritium breeding
- Control, Data access and Communication (CODAC)
- Cooling water
- Cryogenics
- Diagnostics
- Fuel cycle
- Hot cell a secure environment for processing, repair or testing, etc., of components that have become activated by neutrons.
- Power supply
- Remote handling
- Heating and current drive
- Vacuum system

There is a long way to go, but we are on the right path...





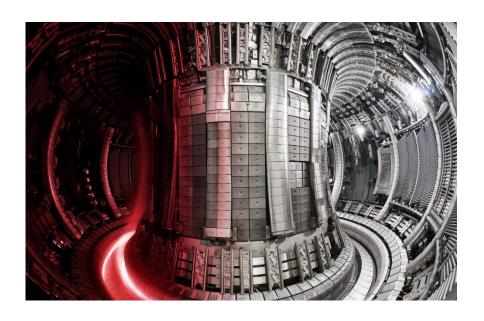
Dec 2025 First Plasma

2035

Deuterium-Tritium Operation begins

Joint European Torus (JET) facility has a recordbreaking 59 megajoules of sustained fusion energy

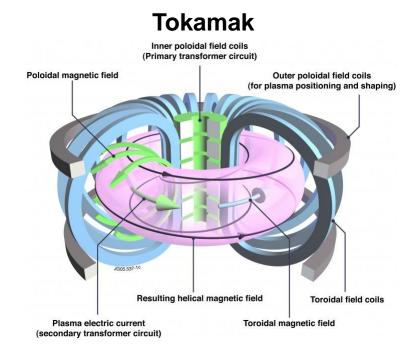




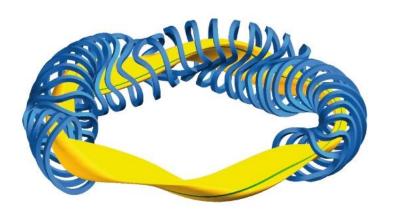
 Record-breaking 59 megajoules of sustained fusion energy in Joint European Torus (JET) facility in Oxford demonstrates powerplant potential and strengthens case for ITER.

Stellarator uses twisted coil to generate poloidal magnetic field



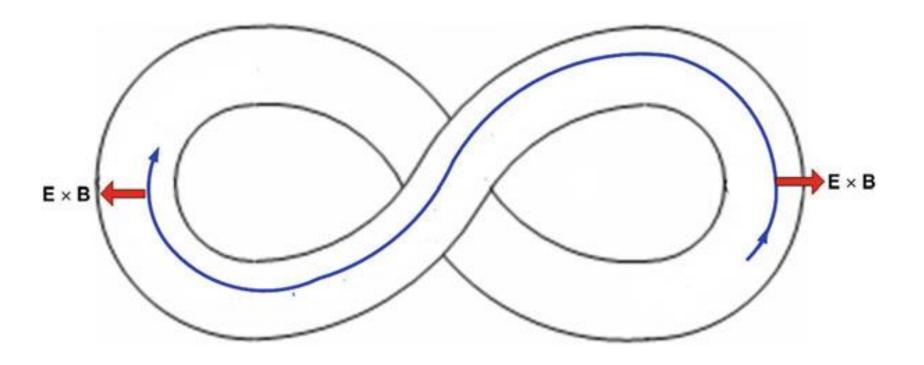


Stellarator



A figure-8 stellarator solved the drift issues





A figure-8 stellarator solved the drift issues



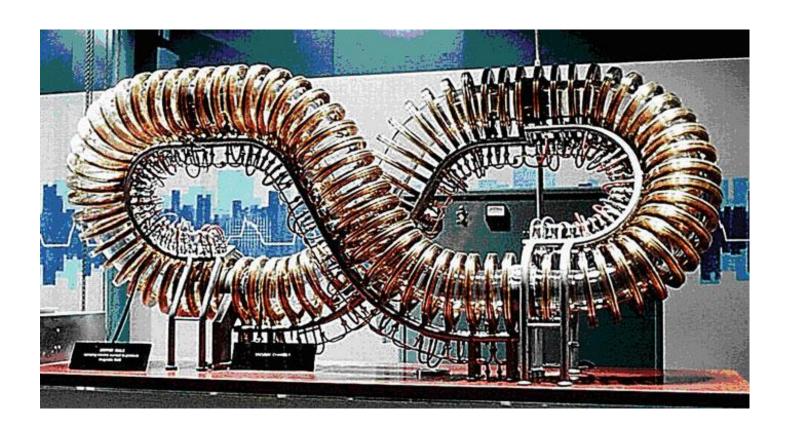
Lyman Spitzer, Jr. came out the idea during a long ride on a ski lift at Garmisch-Partenkirchen





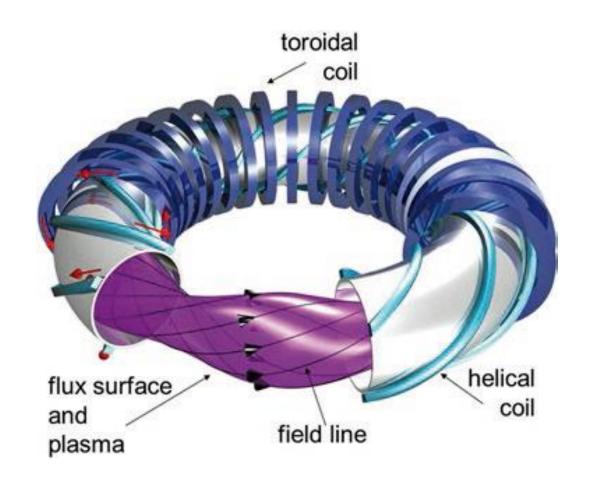
Exhibit model of a figure-8 stellarator for the Atoms for Peace conference in Geneva in 1958





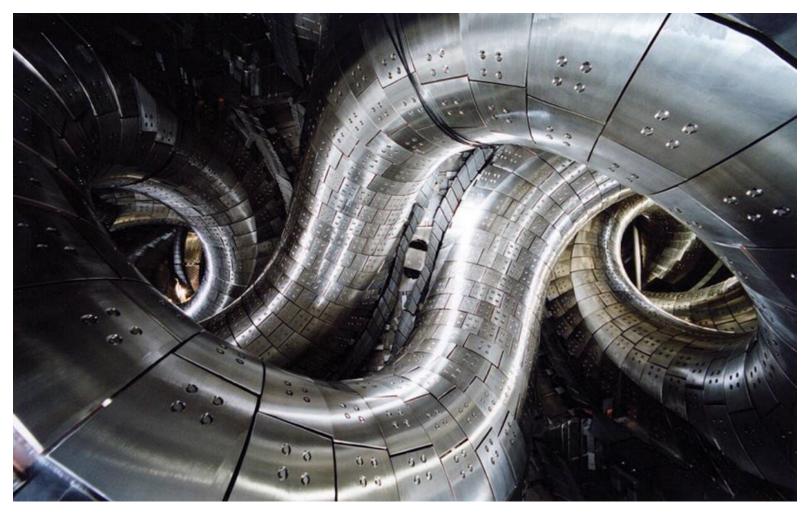
Twisted magnetic field lines can be provided by toroidal coils with helical coils



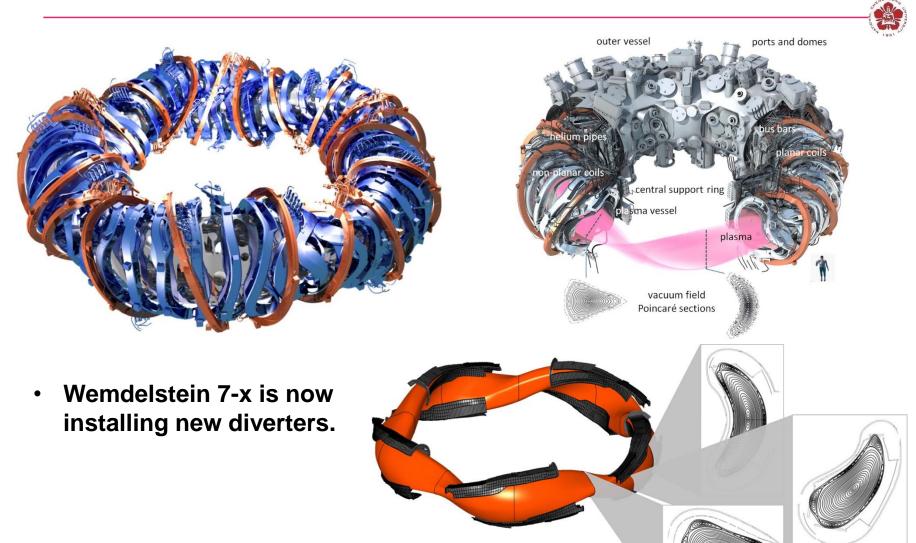


LHD stellarator in Japan



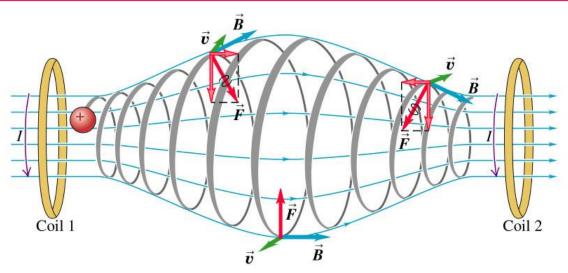


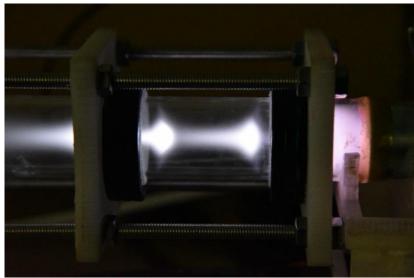
Wendelstein 7-X is a stellarator built by Max Planck Institute for Plasma Physics (IPP)



Demonstration of a magnetic mirror machine



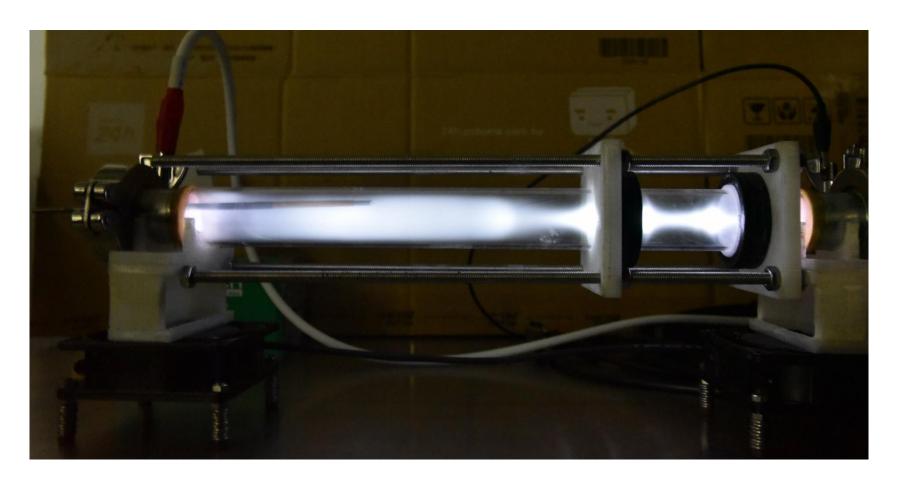




Show video.

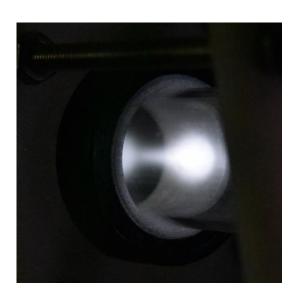
Plasma is partially confined by the magnetic field

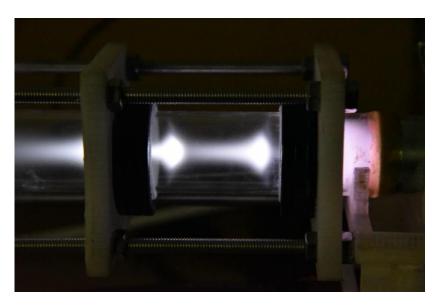


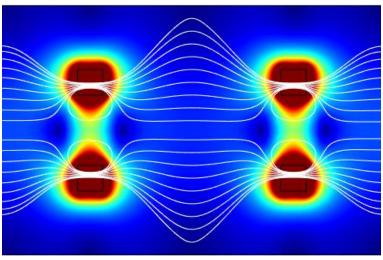


Many mirror points are provided by a pair of ring-type magnets







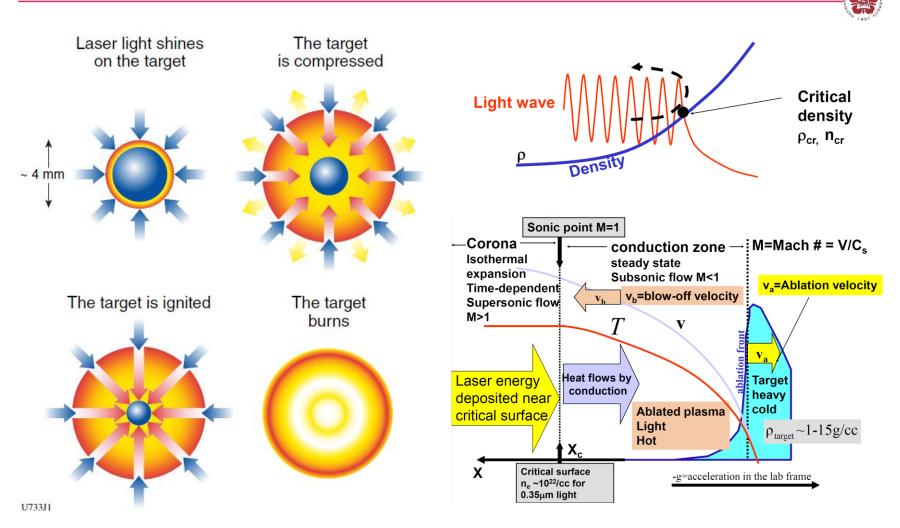


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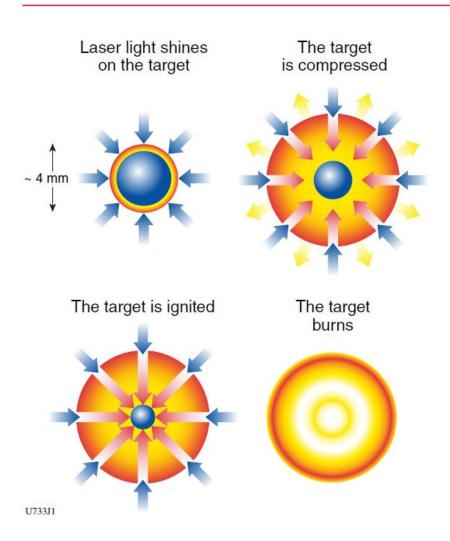
Compression happens when outer layer of the target is heated by laser and ablated outward



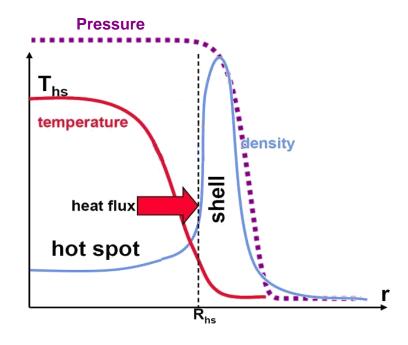
Inertial confinement fusion: an introduction, Laboratory for Laser Energetics, University of Rochester R. Betti, HEDSA HEDP Summer School, 2015

Plasma is confined by its own inertia in inertial confinement fusion (ICF)





Spatial profile at stagnation

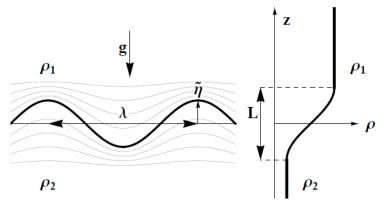


A ball can not be compressed uniformly by being squeezed between several fingers

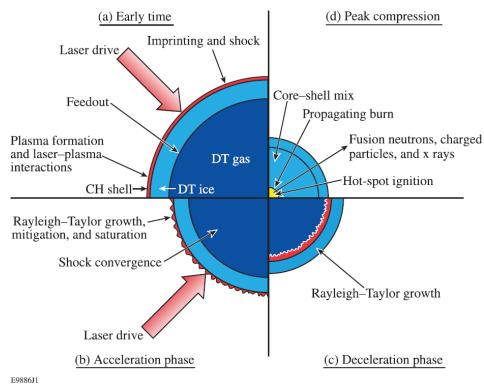




Rayleigh-Taylor instability



Stages of a target implosion

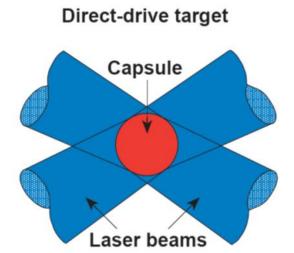


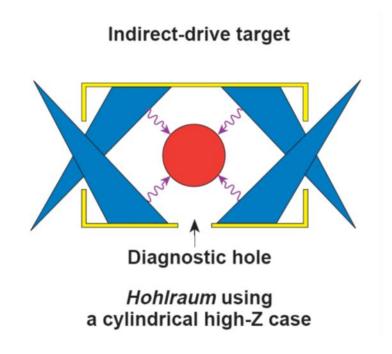
P.-Y. Chang, PhD Thesis, U of Rochester (2013)

R. S. Craxton, etc., Phys. Plasmas 22, 110501 (2015)

A spherical capsule can be imploded through directly or indirectly laser illumination







Rochester is known as "The World's Image Center"





There are many famous optical companies at Rochester



Kodak





Eastman school of music

BAUSCH+LOMB



Laboratory for Laser Energetics, University of Rochester is a pioneer in laser fusion

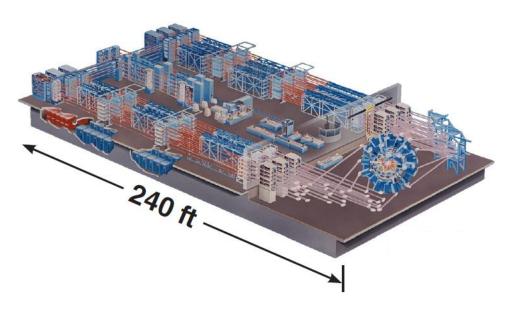
- OMEGA Laser System
 - 60 beams
 - >30 kJ UV on target
 - 1%~2% irradiation nonuniformity
 - Flexible pulse shaping

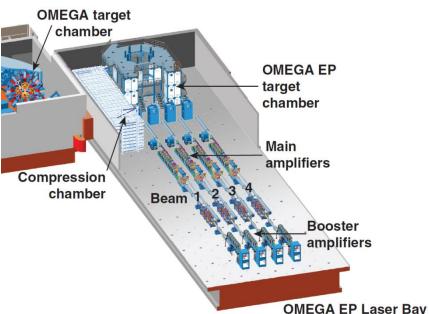






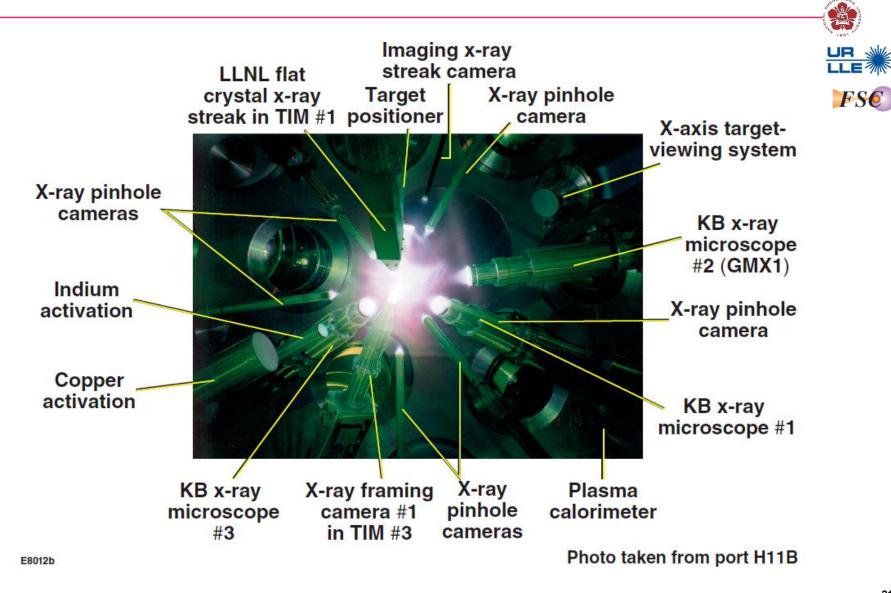
- 2.6 kJ IR in 10 ps
- Can propagate to the OMEGA or OMEGA EP target chamber





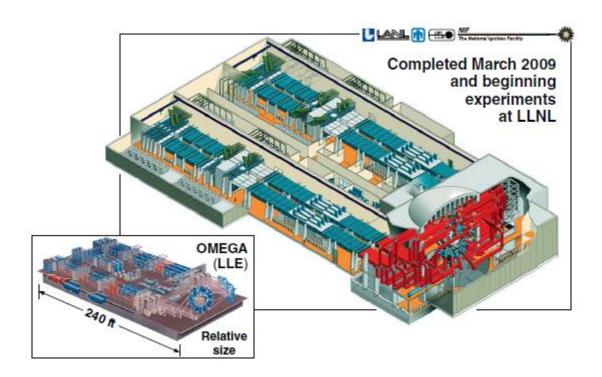
FSC

The OMEGA Facility is carrying out ICF experiments using a full suite of target diagnostics



The 1.8-MJ National Ignition Facility (NIF) will demonstrate ICF ignition and modest energy gain

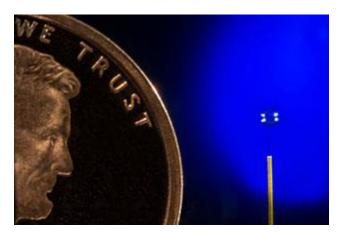




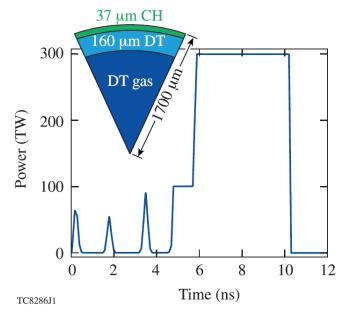
OMEGA experiments are integral to an ignition demonstration on the NIF.

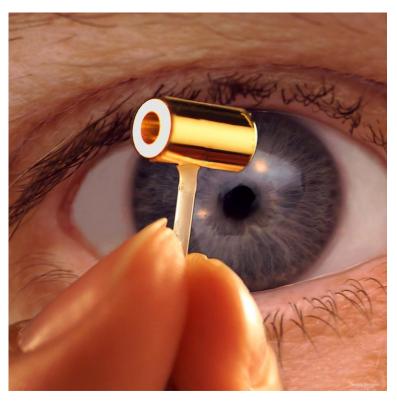
Targets used in ICF





Triple-point temperature : 19.79 K





http://www.lle.rochester.ed https://en.wikipedia.org/wiki/Inertial_confinement_fusion R. S. Craxton, etc., *Phys. Plasmas* **22**, 110501 (2015)

Softer material can be compressed to higher density

Compression of a baseball



Compression of a tennis ball



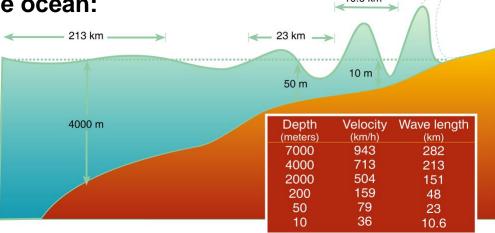




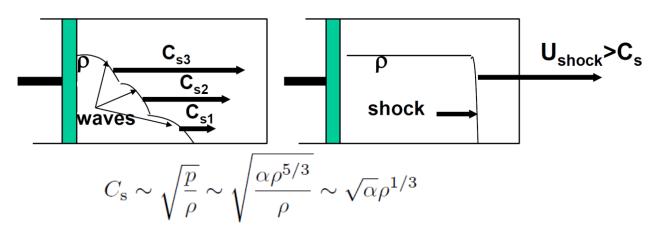
A shock is formed due to the increasing sound speed of a compressed gas/plasma







Acoustic/compression wave driven by a piston:



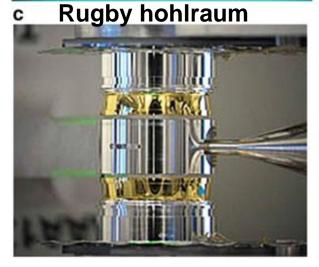
Targets used in ICF

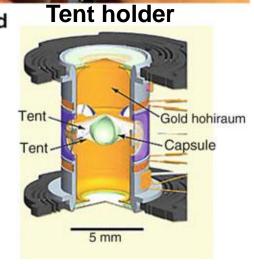








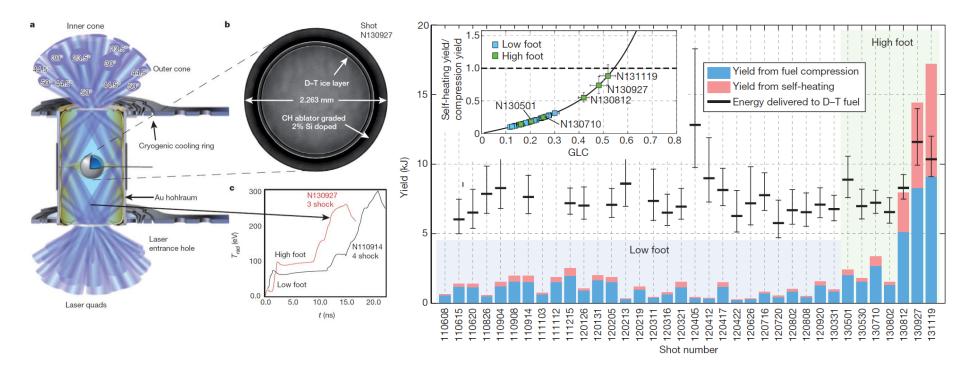




https://www.lle.rochester.edu/index.php/2014/11/10/next-generation-cryo-target/ Introduction to Plasma Physics and Controlled Fusion 3rd Edition, by Francis F. Chen

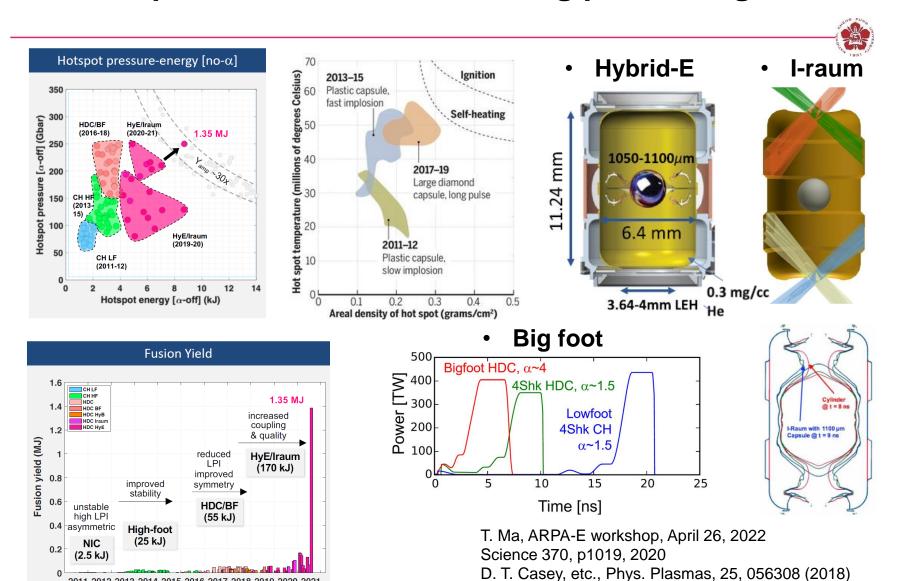
Nature letter "Fuel gain exceeding unity in an inertially confined fusion implosion"





Fuel gain exceeding unity was demonstrated for the first time.

The hot spot has entered the burning plasma regime



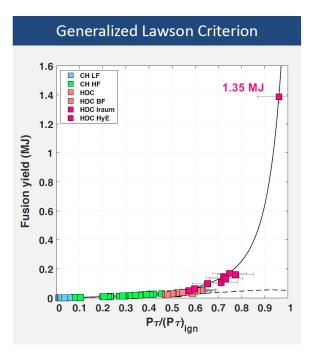
2011 2012 2013 2014 2015 2016 2017 2018 2019 2020 2021

Year

A. L. Kritcher, etc., Phys. Plasmas, 28, 072706 (2021)

H. F. Robey, etc., Phys. Plasmas, 25, 012711 (2018)

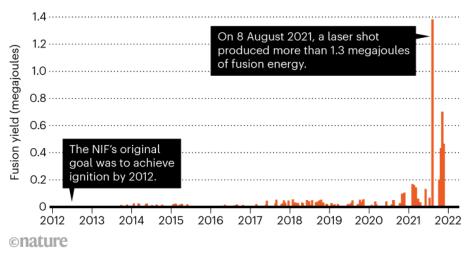
National Ignition Facility (NIF) achieved a yield of more than 1.3 MJ from ~1.9 MJ of laser energy in 2021 (Q~0.7)



National Ignition Facility (NIF)
 achieved a yield of more than 1.3
 MJ (Q~0.7). This advancement puts
 researchers at the threshold of
 fusion ignition.

THE ROAD TO IGNITION

The National Ignition Facility (NIF) struggled for years before achieving a high-yield fusion reaction (considered ignition, by some measures) in 2021. Repeat experiments, however, produced less than half the energy of that result.



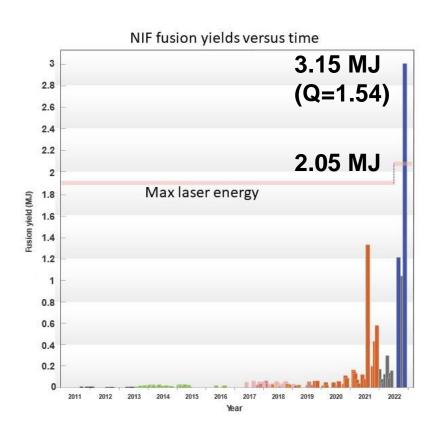
 Laser-fusion facility heads back to the drawing board.

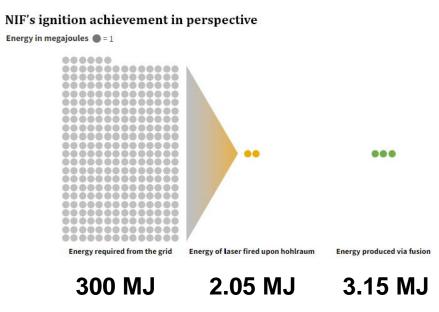
T. Ma, ARPA-E workshop, April 26, 2022

J. Tollefson, Nature (News) 608, 20 (2022)

"Ignition" (target yield larger than one) was achieved in NIF on 2022/12/5



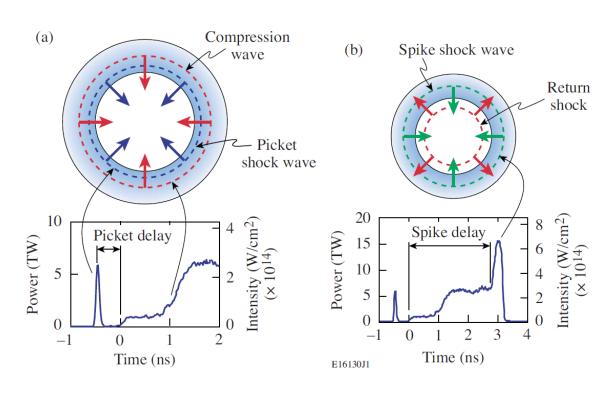




External "spark" can be used for ignition

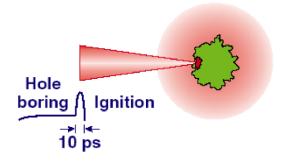


Shock ignition

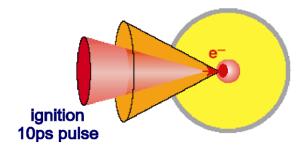


Fast ignition

a) channeling FI concept



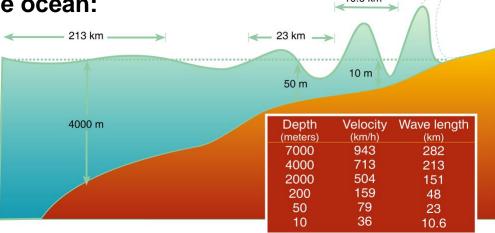
b) cone-in-shell FI concept



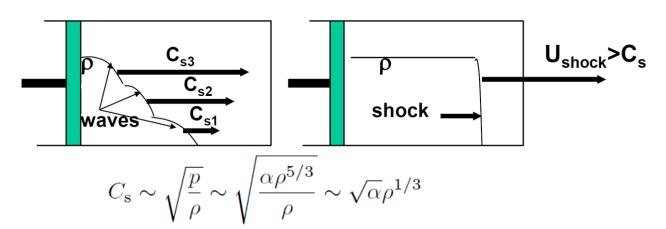
A shock is formed due to the increasing sound speed of a compressed gas/plasma







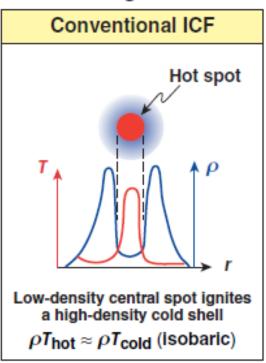
Acoustic/compression wave driven by a piston:



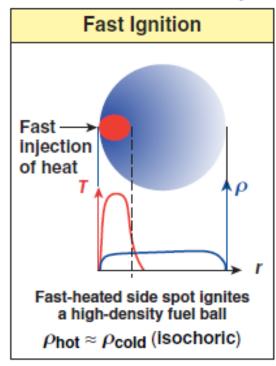
Ignition can happen by itself or being triggered externally

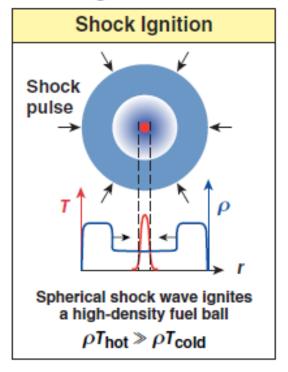


Self-ignition



External "spark" for fast ignition





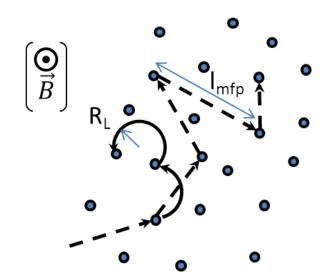
Outline



- Introduction to nuclear fusion
- Magnetic confinement fusion (MCF)
 - Tokamak
 - Stellarator
- Inertial confinement fusion (ICF)
 - Indirection drive ICF
 - Direct drive ICF
- Innovation idea MCF + ICF
- Pulsed-power system at NCKU

A strong magnetic field reduces the heat flux





$$oldsymbol{q}_{T} = -\kappa_{||}
abla_{||} oldsymbol{T} - \kappa_{\perp}
abla_{\perp} oldsymbol{T}$$
 $oldsymbol{\kappa}_{||} = \kappa_{0} oldsymbol{T}^{5/2}$

$$\kappa_{||} = \kappa_0 T^{5/2}$$

$$\kappa_{\perp} = \frac{\kappa_{||}}{\chi^2}$$
 for large Hall parameter $\chi \propto \frac{I_{\text{mfp}}}{R_{\text{L}}} >> 1$

Typical hot spot conditions:

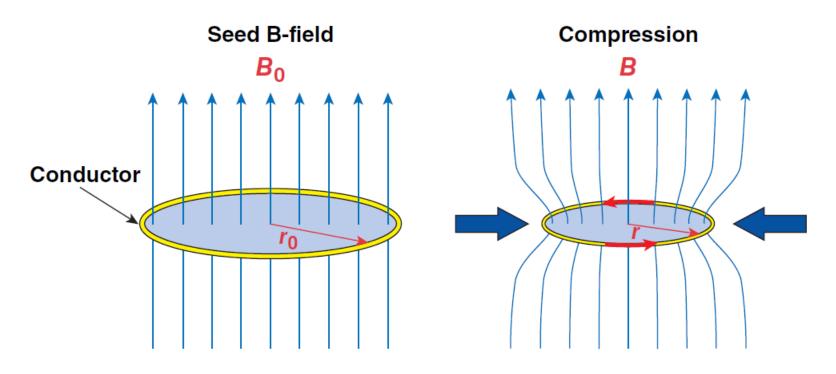
 $R_{hs} \sim 40 \ \mu m, \ \rho \sim 20 \ g/cm^3, \ T \sim 5 \ keV$:

 $B > 10 \, \text{MG}$ is needed for $\chi > 1$

Magnetic-flux compression can be used to provide the needed magnetic field.

Principle of frozen magnetic flux in a good conductor is used to compress fields

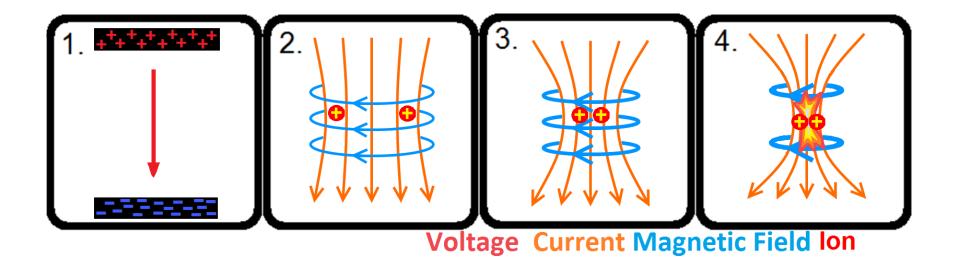




$$\Phi = \pi r_0^2 B_0 = \pi r^2 B$$

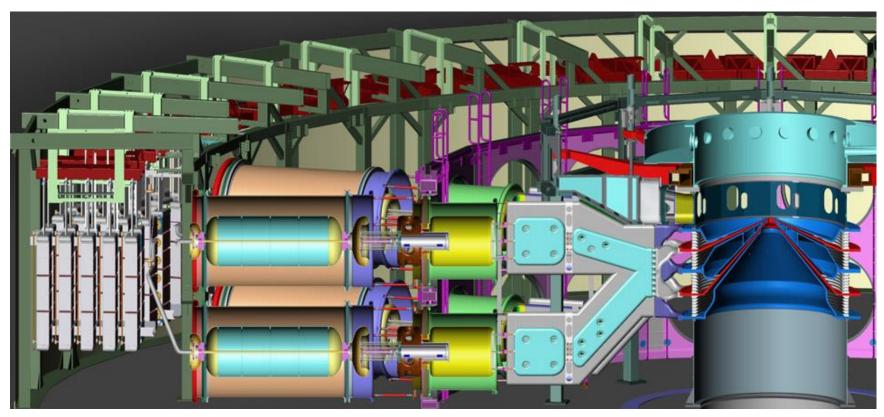
Plasma can be pinched by parallel propagating plasmas





Sandia's Z machine is the world's most powerful and efficient laboratory radiation source





Stored energy: 20 MJ

Marx charge voltage: 85 kV

Peak electrical power: 85 TW

Peak current: 26 MA

Rise time: 100 ns

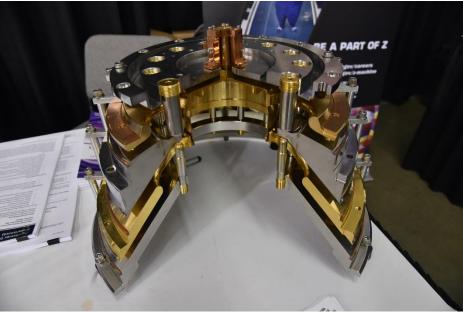
Peak X-ray emissions: 350 TW

Peak X-ray output: 2.7 MJ

Z machine



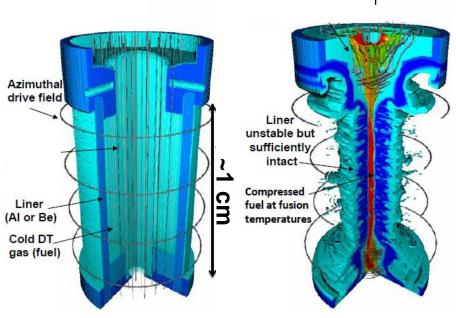




Z machine







Stored energy: 20 MJ

Peak electrical power: 85 TW

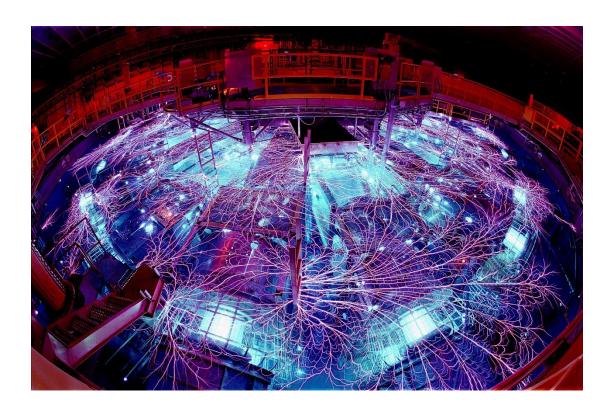
Peak current: 26 MA

Rise time: 100 ns

Peak X-ray output: 2.7 MJ

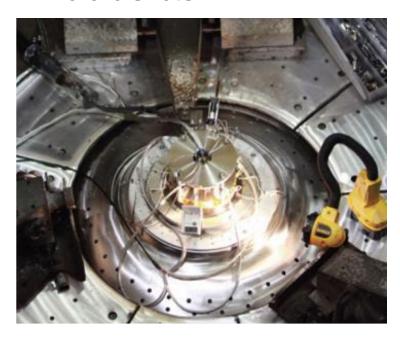
Z machine discharge



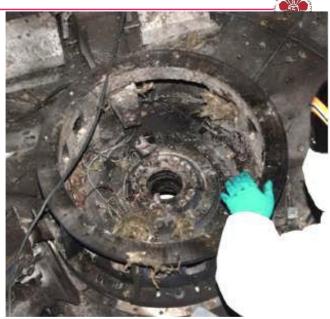


Before and after shots

Before shots



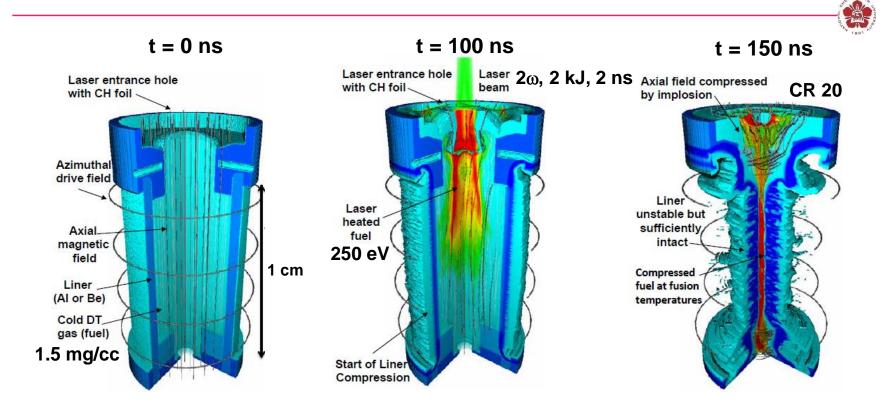
After shots





SAND2017-0900PE_The sandia z machine - an overview of the world's most powerful pulsed power facility.pdf

Promising results were shown in MagLIF concept conducted at the Sandia National Laboratories

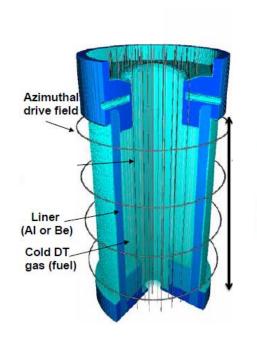


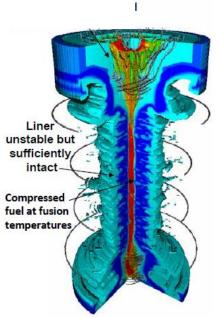
The stagnation plasma reached fusion-relevant temperatures with a 70 km/s implosion velocity

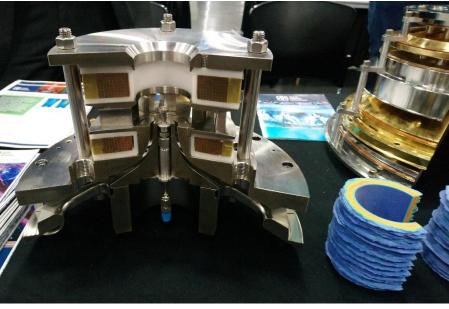
S. A. Slutz *et al* Phys. Plasmas 17 056303 (2010) M. R. Gomez *et al* Phys. Rev. Lett. 113 155003 (2014)

MagLIF target



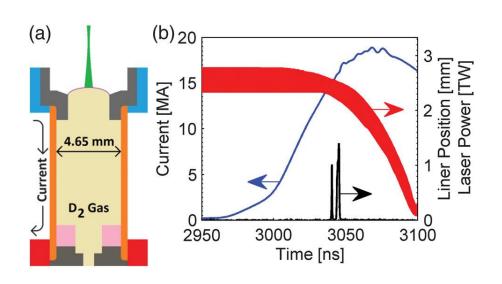


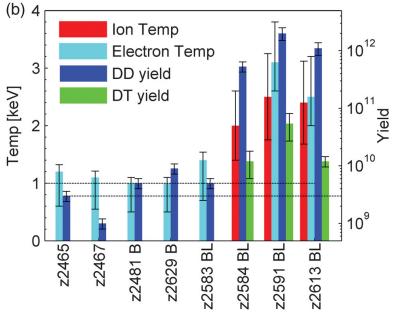




Neutron yield increased by 100x with preheat and external magnetic field.

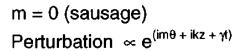


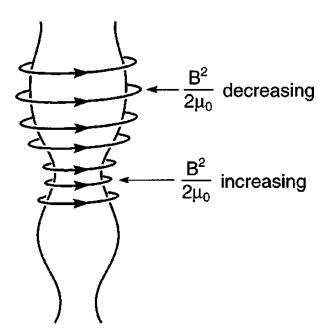




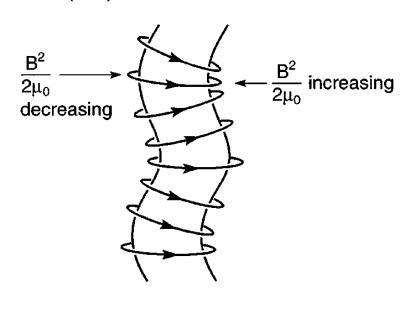
Sheared flow stabilizes MHD instabilities

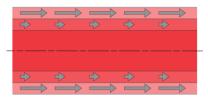


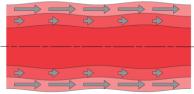


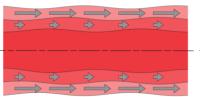


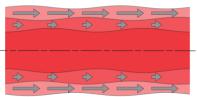
$$m = 1 (kink)$$









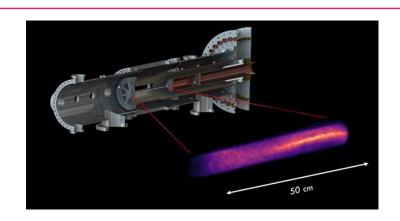


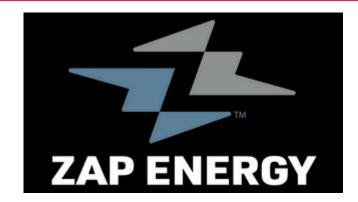
$$\frac{dV_Z}{dr}\neq 0$$

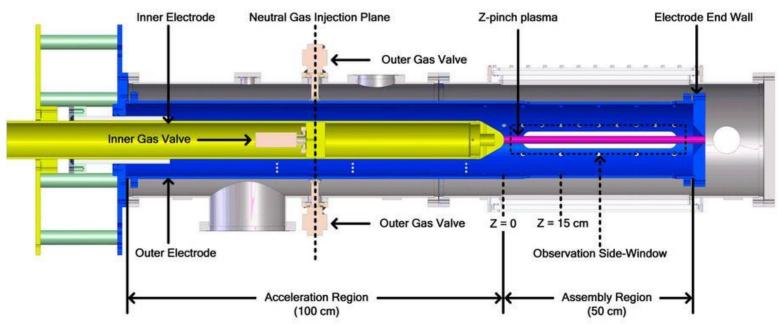
- M. G. Haines, etc., Phys. Plasmas 7, 1672 (2000)
- U. Shumlak, etc., Physical Rev. Lett. 75, 3285 (1995)
- U. Shumlak, etc., ALPHA Annual Review Meeting 2017

A z-pinch plasma can be stabilized by sheared flows





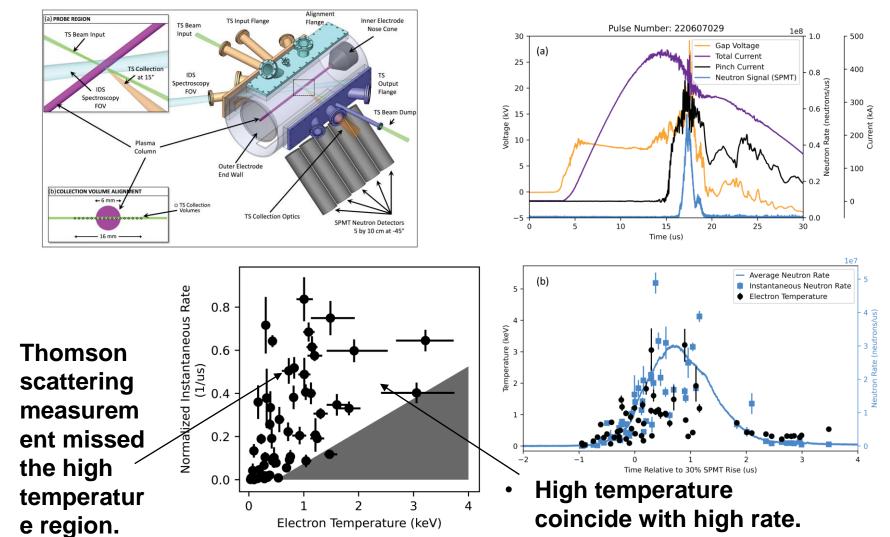




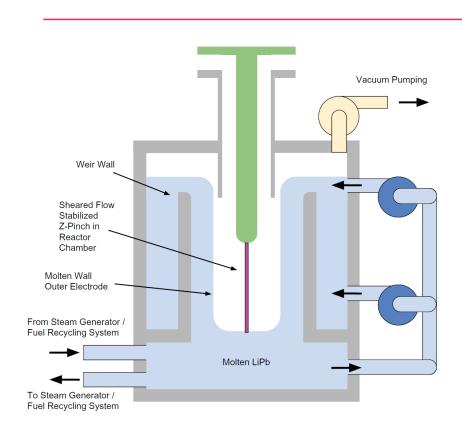
https://www.zapenergyinc.com/about

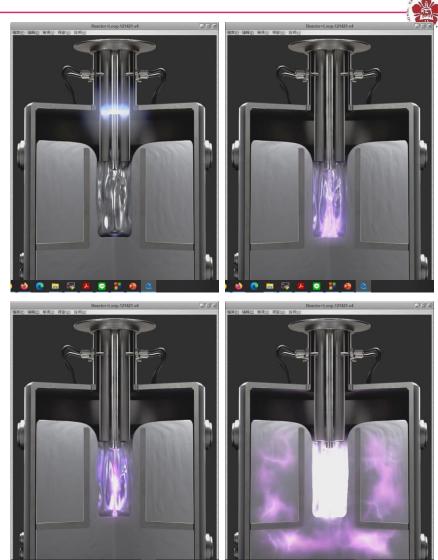
A. D. Stepanov, etc., Phys. Plasmas 27, 112503 (2020)

Elevated electron temperature coincident with observed fusion reactions in a sheared-flow-stabilized z pinch



Fusion reactor concept by ZAP energy

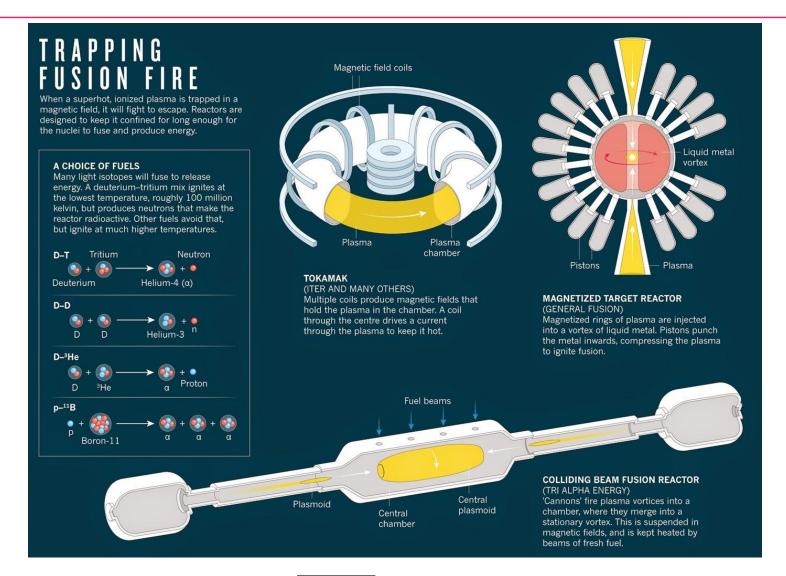




https://www.zapenergyinc.com/about E. G. Forbes, etc., Fusion Sci. Tech. 75, 599 (2019)

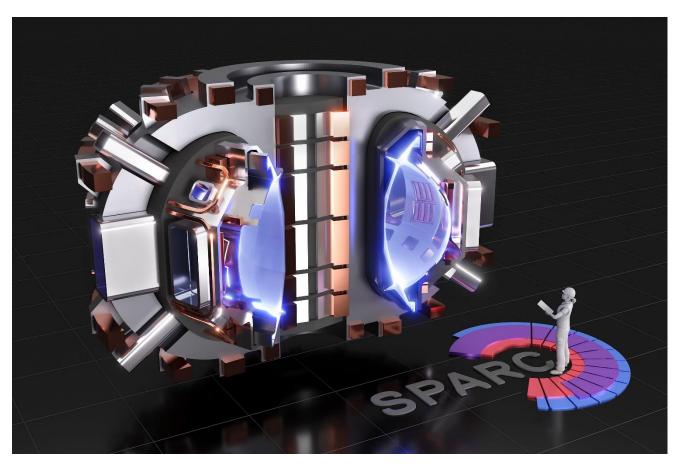
There are alternative





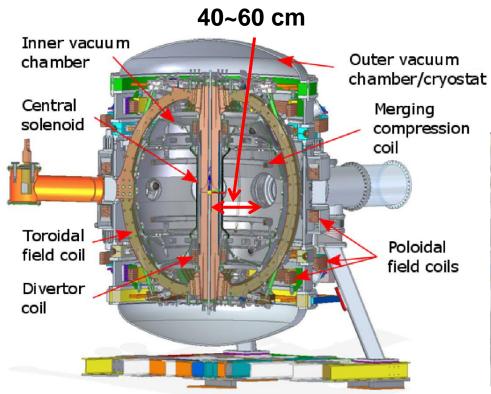
Commonwealth Fusion Systems, a MIT spin-out company, is building a high-magnetic field tokamak





- The fusion gain Q > 2 is expected for SPARC tokamak.

Merging compression is used to heat the tokamak at the start-up process in ST40 Tokamak at Tokamak Energy Ltd



- High temperature superconductors are used.
- $B_T \sim 3 T$

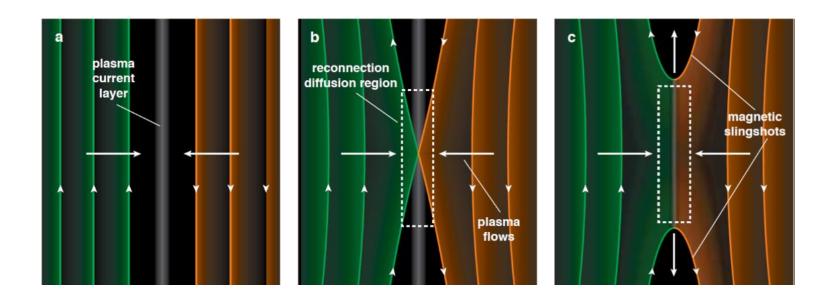


M. Gryaznevich, etc., Fusion Eng. Design, **123**,177 (2017) https://www.tokamakenergy.co.uk/

P. F. Buxton, etc., Fusion Eng. Design, 123, 551 (2017)

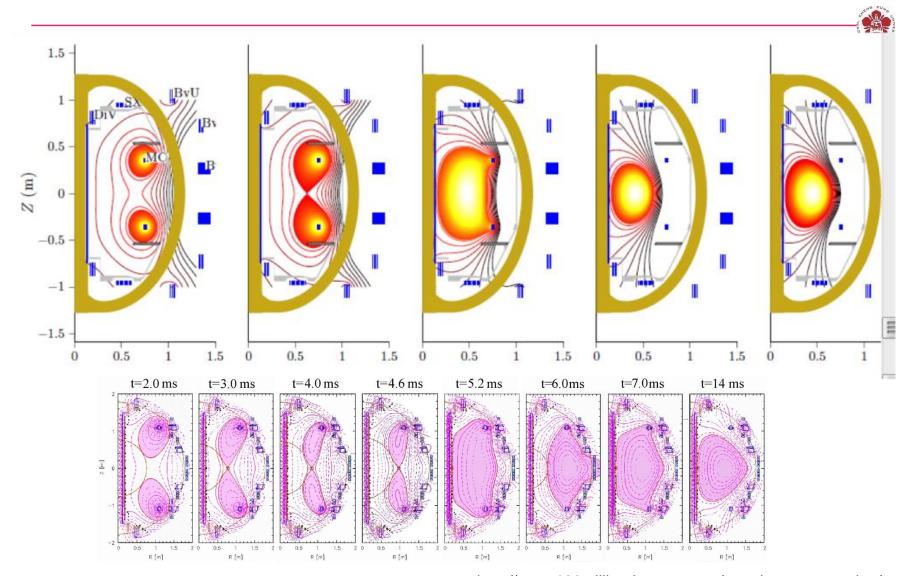
Reconnection





https://www.youtube.com/watch?v=7sS3Lpzh0Zw

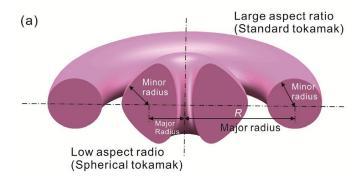
Merging compression is used to heat the plasma



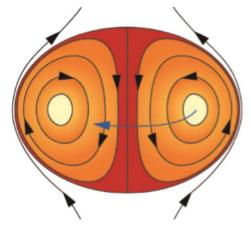
Spherical torus (ST) and compact torus (CT)



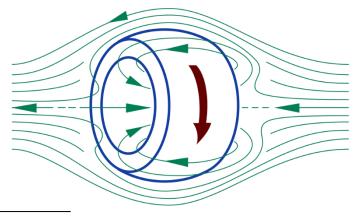
Spherical torus (ST)



- Compact torus (CT)
 - Spheromak



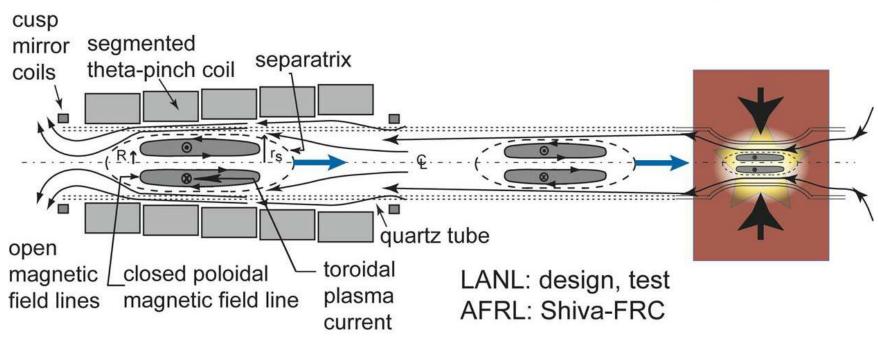
Field reversed configuration (FRC)

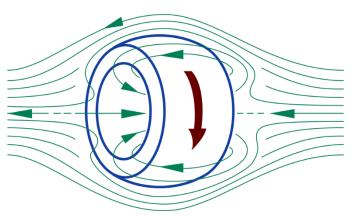


Zhe Gao, Matter Radiat. Extremes **1**, 153 (2016) https://en.wikipedia.org/wiki/Field-reversed_configuration

Field reverse configuration is used in Tri-alpha energy





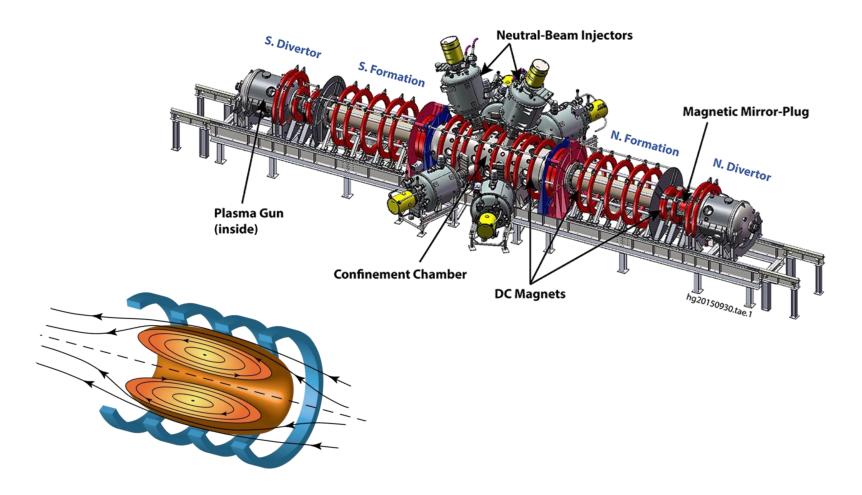


^{*}Magneto-Inertial Fusion & Magnetized HED Physics by Bruno S. Bauer, UNR & Magneto-Inertial Fusion Community

^{**}https://en.wikipedia.org/wiki/Field-reversed_configuration

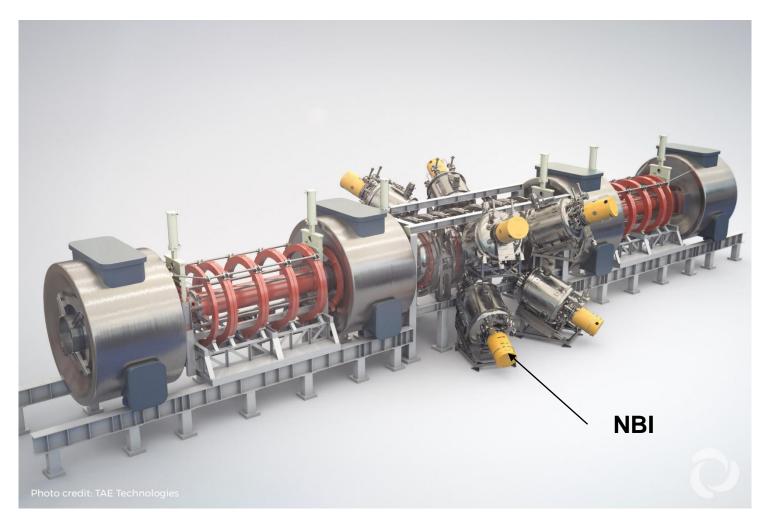
Field reverse configuration is used in Tri-alpha energy





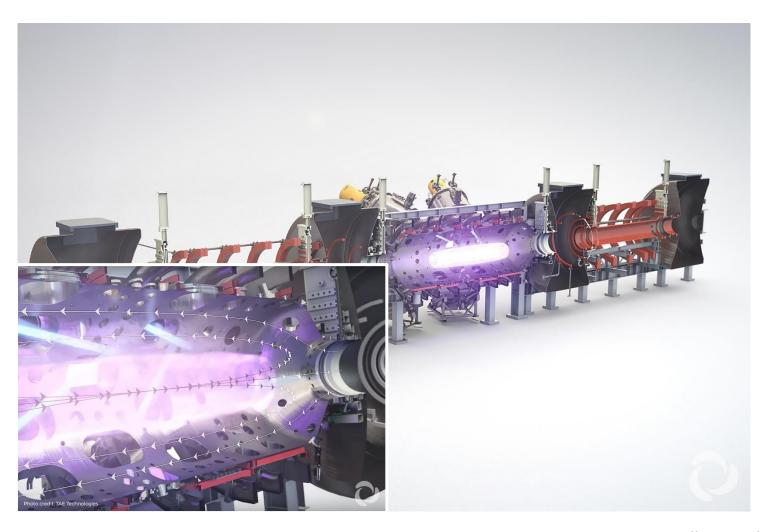
NBI for Tri-Alpha Energy Technologies





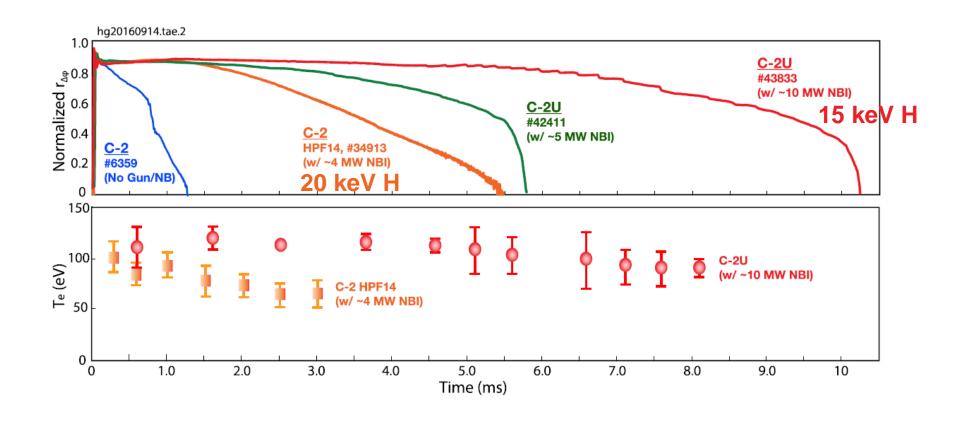
Neutral beams are injected in to the chamber for spinning the FRC





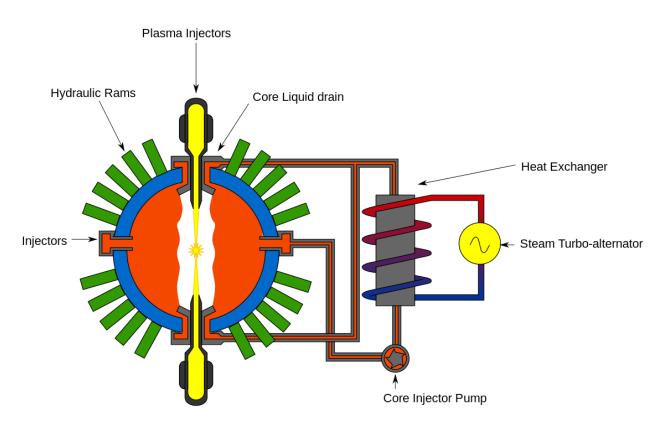
FRC sustain longer with neutral beam injection





General fusion is a design ready to be migrated to a power plant

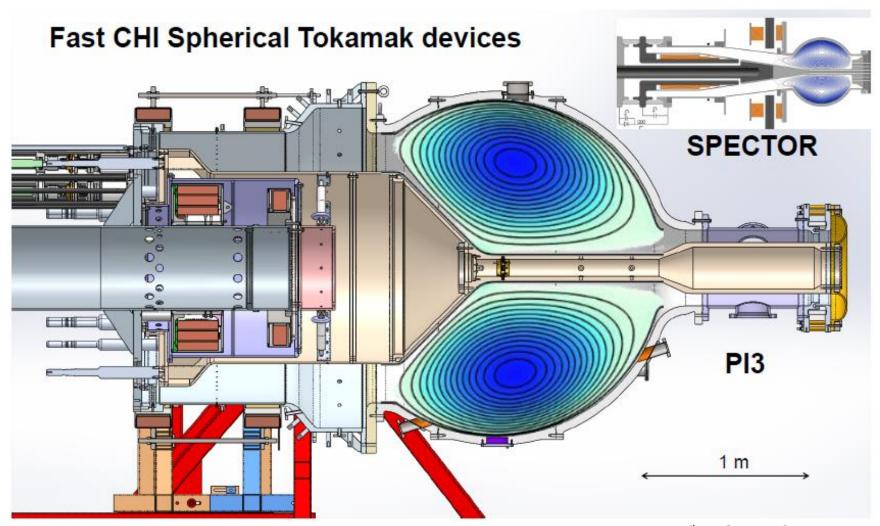






A spherical tokamak is first generated





Plasma injector for the spherical tokamak

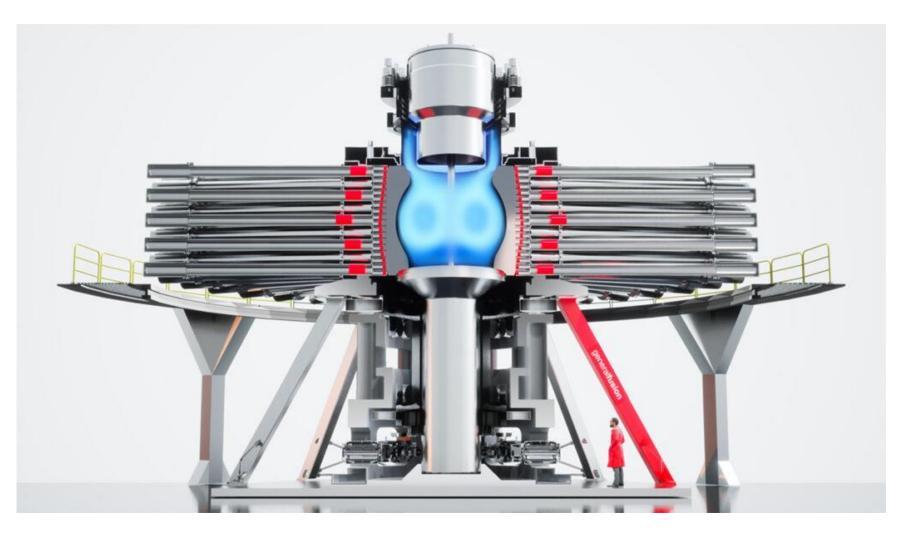






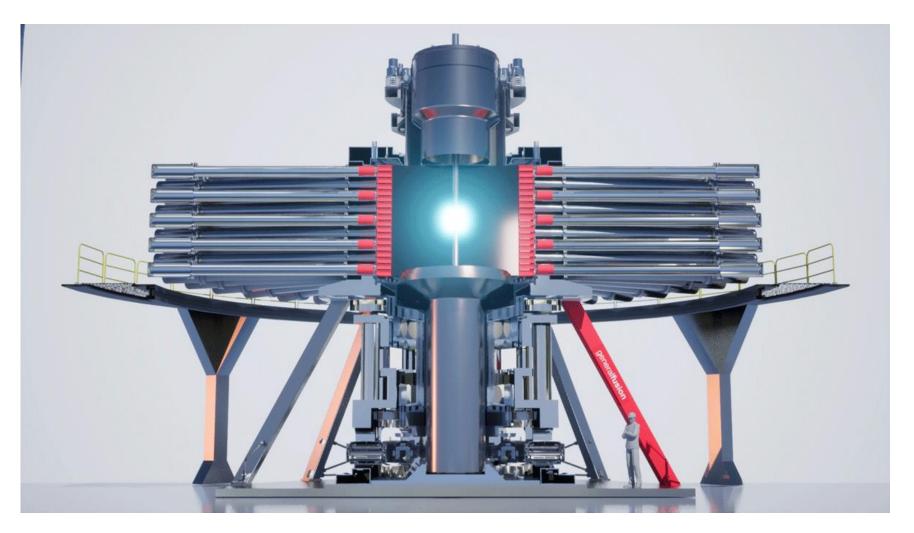
A spherical tokamak is generated in a liquid metal vortex





The spherical tokamak is compressed by the pressure provided by the sournding hydraulic pistons





BBC: General Fusion to build its Fusion Demonstration Plant in the UK, at the UKAEA Culham Campus

Nuclear energy: Fusion plant backed by Jeff Bezos to be built in UK

By Matt McGrath Environment correspondent

(1) 17 June



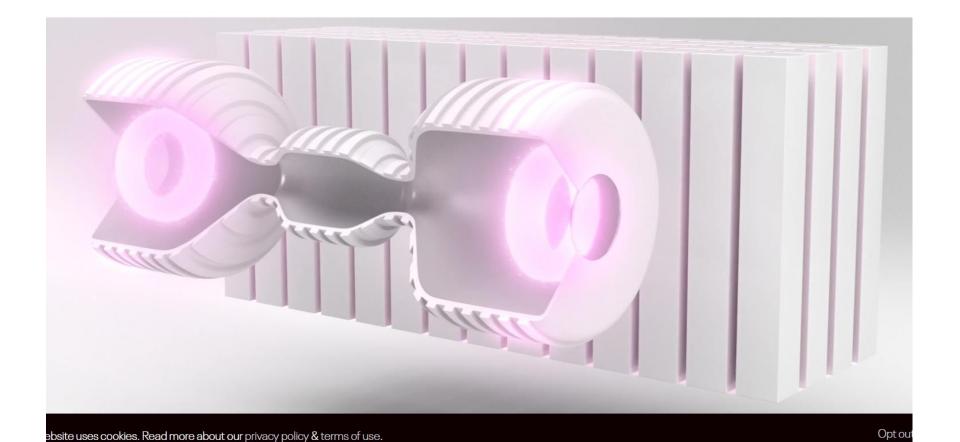


A company backed by Amazon's Jeff Bezos is set to build a large-scale nuclear fusion demonstration plant in Oxfordshire.

Canada's General Fusion is one of the leading private firms aiming to turn the

Helion energy is compressing the two merging FRCs

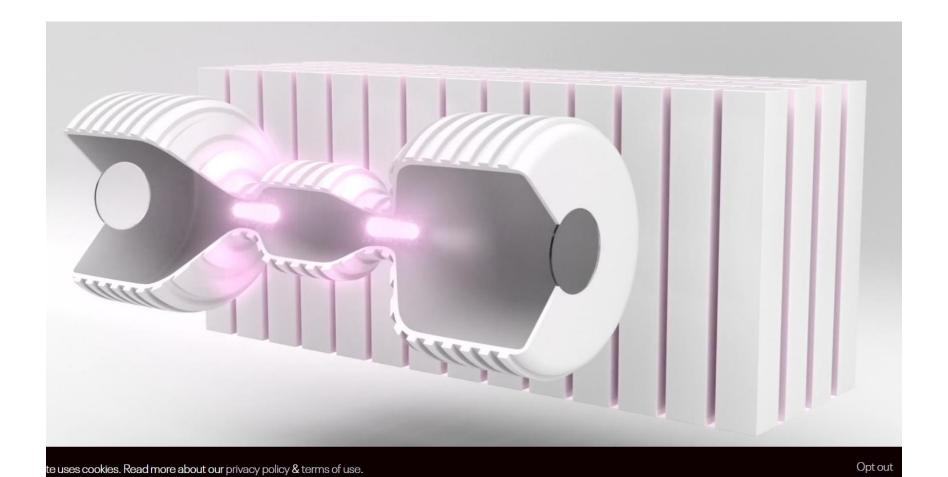




https://www.helionenergy.com/

Two FRCs are accelerated toward each other





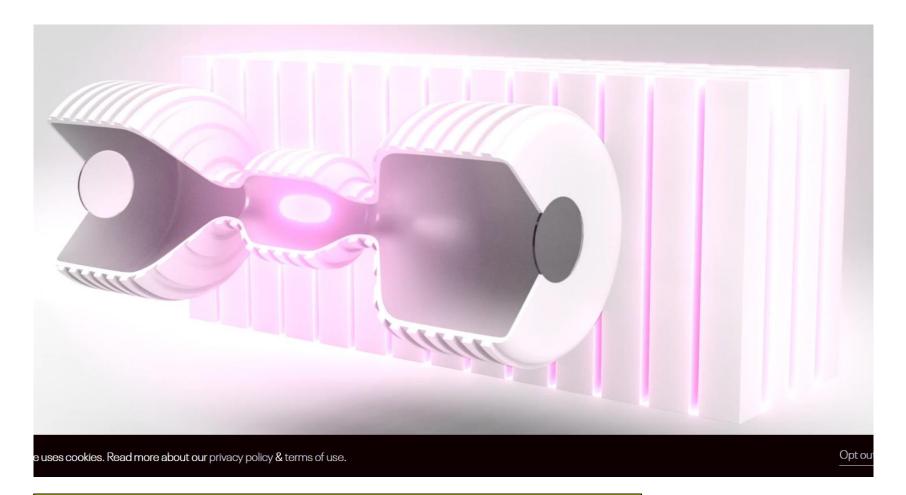
Two FRCs merge with each other





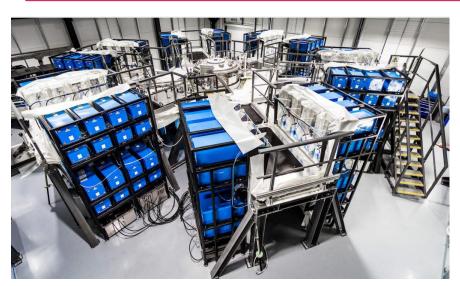
The merged FRC is compressed electrically to high temperature

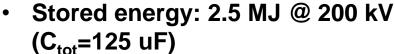




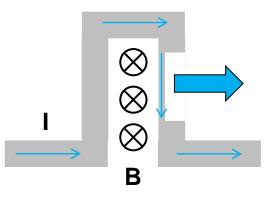
Similar concept will be studied in our laboratory.

Projectile Fusion is being established at First Light Fusion Ltd, UK

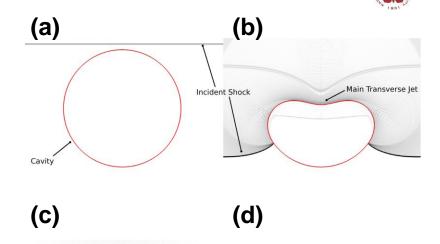


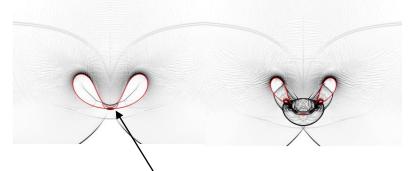


I_{peak}=14 MA w/ T_{rise}~2us.









 High pressure is generated by the colliding shock.
 https://www.youtube.com/watch?v =aTMPigL7FB8

https://firstlightfusion.com/
B. Tully and N. Hawker, Phys. Rev. **E93**, 053105 (2016)

A gas gun is used to eject the projectile







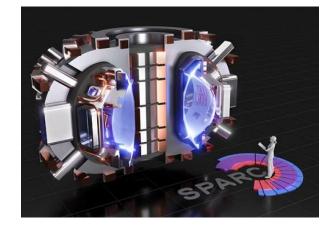
https://www.youtube.com/watch?v=JN7lyxC11n0 https://www.youtube.com/watch?v=aW4eufacf-8

Many groups aim to achieve ignition in the MCF regime in the near future

- ITER 2025 First Plasma
 2035 D-T Exps
 2050 DEMO
- Tokamak energy, UK
 - 2025 Gain
 - 2030 to power grid



Commonwealth Fusion Systems, USA– 2025 Gain



https://www.iter.org

https://www.tokamakenergy.co.uk/ https://www.psfc.mit.edu/sparc

Fusion is blooming!



FIA Members













































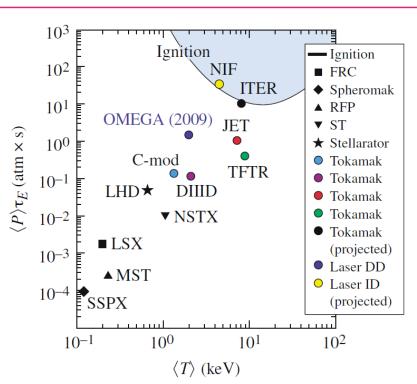


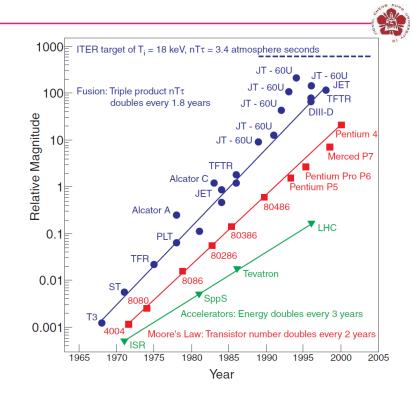




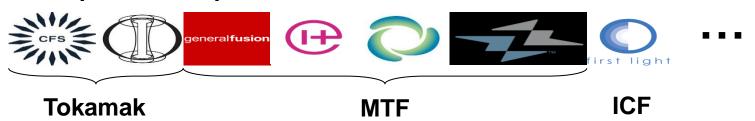
:

We are closed to ignition!





Other private companies:

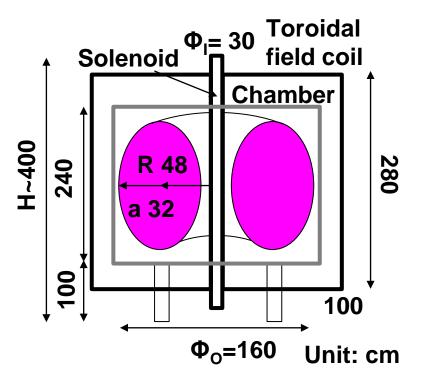


A. J. Webster, Phys. Educ. 38, 135 (2003)R. Betti, etc., Phys. Plasmas, 17, 058102 (2010)

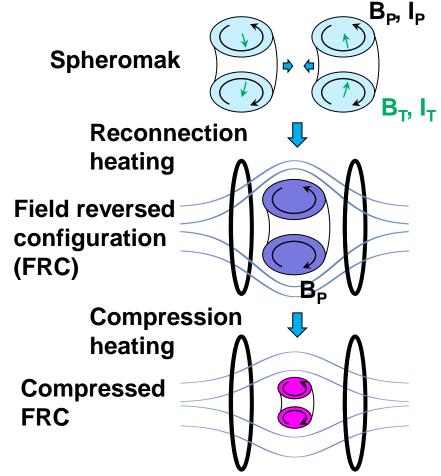
Fusion projects in Inst. Space and Plasma Sciences, National Cheng Kung University

· 國科會計畫 - 磁約束高溫電漿研究

Formosa Integrated Research Spherical Tokamak (FIRST)



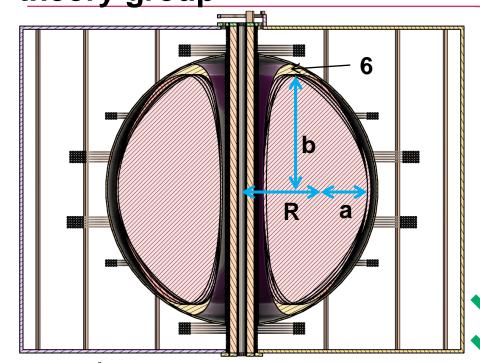
Magneto-inertial fusion (MIF)



We welcome anyone interested in fusion research to join our team!

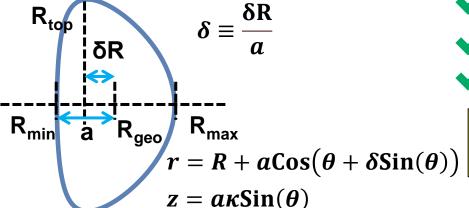
A new design using a spherical chamber can tolerate several potential shapes and sides calculated by the theory group





- Parameters:
 - Elongation κ=b/a
 - Triangularity δ
 - T~100 eV
 - B_T~0.5 T
 - I_p~100 kA

	R (cm)	a (cm)	R/a	K	δ
1	45	32	1.41	2.2	0.5
2	45	32	1.41	2.2	0.3
3	45	32	1.41	2.2	0.4
4	45	32	1.41	2.2	0.6
5	47	32	1.47	2.2	0.5



We welcome anyone interested in fusion research to join us!